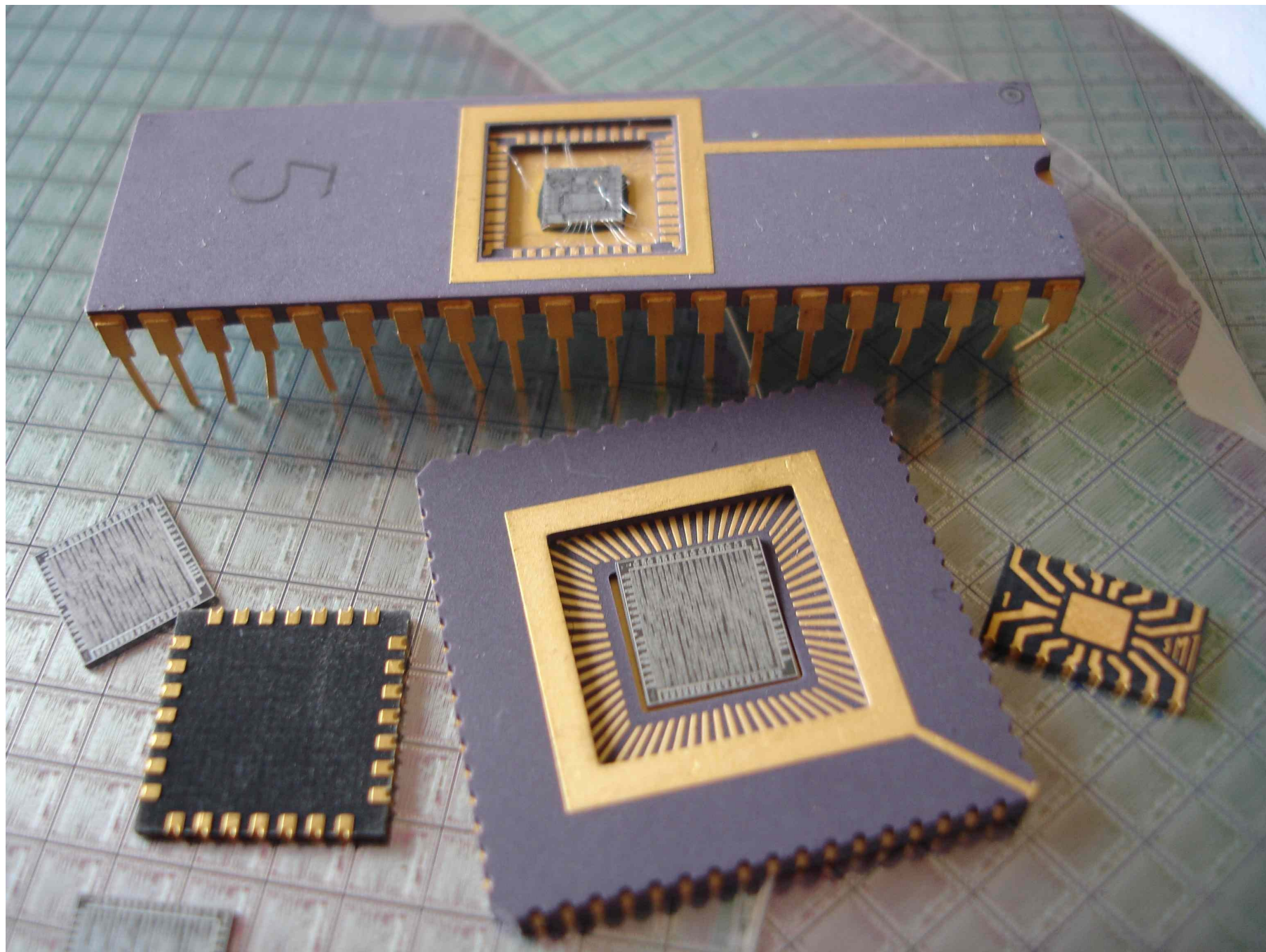


MOORE 's LAW

- The history and evolution of IC
- Collection from various sources
- J.-C. Martin, Gabriel 32, 2034 Peseux
- Jean-Claude.martin@hefr.ch
- jcmartin@net2000.ch
- last update date 13.8.2006 JCM



chapitres

- Histoire et vocabulaire
- Évolution (loi de Moore)
- Multimétal
- FPGA
- Téléphones
- Suisse
- Prévisions pour 2015

Some references

- IEEE Spectrum
- <http://tcm.org/html/history/timeline/threads/components/index.html>
- CEH (presently CSEM), Neuchâtel
- FASELEC (presently Philips) Zürich
- <http://www.microwind.org>
- - <Http://micro.magnet.fsu.edu/chipshot.html>

60 ans de microélectronique

- 
- Vacuum tubes, discrete components
 - 1947 The first integrated transistor (Bell Telephone Laboratories)
 - 1959 The first bipolar planar transistor
 - 1961 The first integrated circuit available as a monolithic chip (flip-flop)
 - 1965 The first op-amp
 - 1971 The first 4bit microprocessor (Intel 4004)
 - 1972 The first 8bit microprocessor (Intel 8008)
 - 1981 The first IBM PC
 - 1987 Microprocessor Motorola 68030
 - 2006 Moore law still valid

Vocabulaire des IC

- **VLSI** Very Large Scale Integration
- **SoC** System-on Chip
- **SiP** System-in Package
- **SoB** System-on Board
- **IP** Intellectual Property (reuse)
- **ASIC** Application Specific IC

VLSI

PARIS

70 km²

70 mm²

Complex IC

Integration
scaling

0.25 m

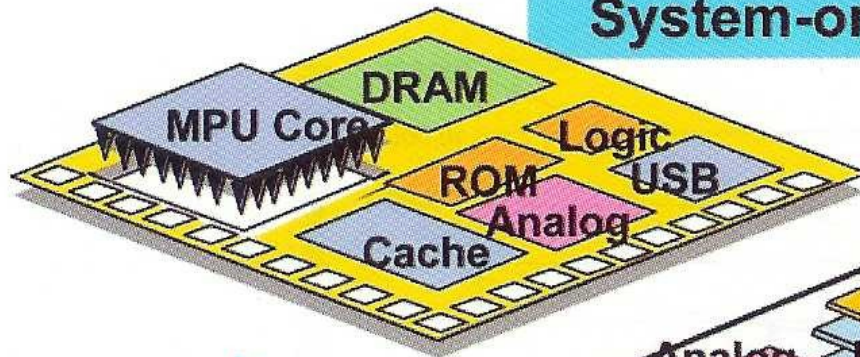
0.25 μm

SoC

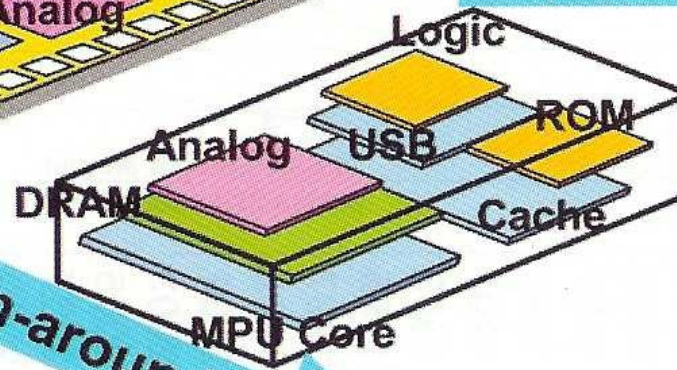
SiP

SoB

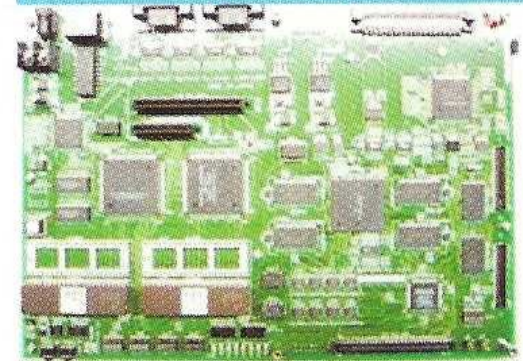
System-on-Chip (SoC)



System-in-Package (SiP)



System-on-Board (SoB)



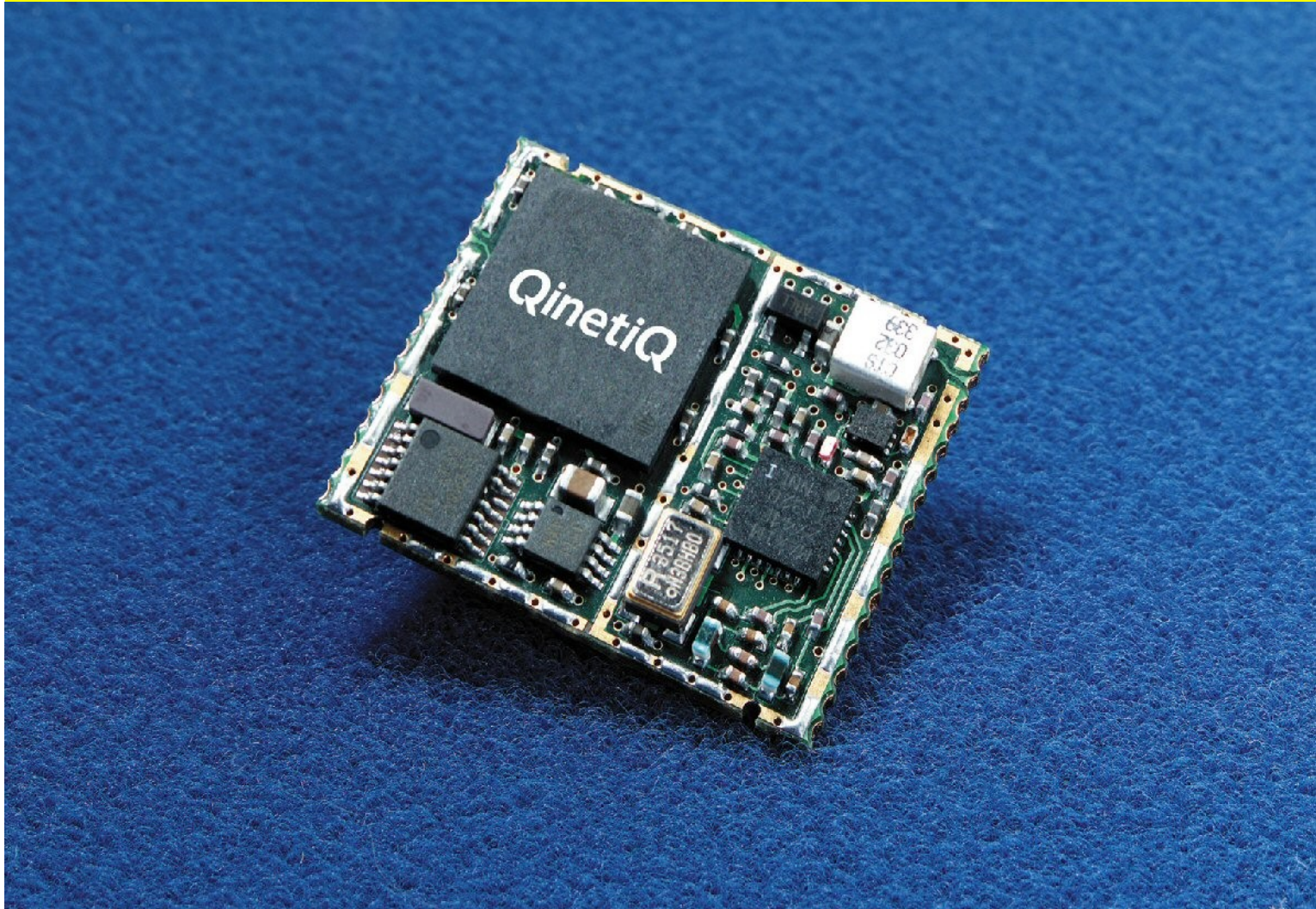
Quick Turn-around Time
Smaller form factor
Lower power, cost

Proceeding IEEE june 2006

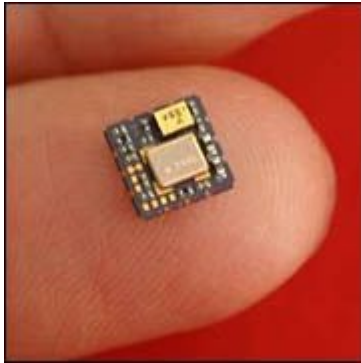
Exemple du GPS



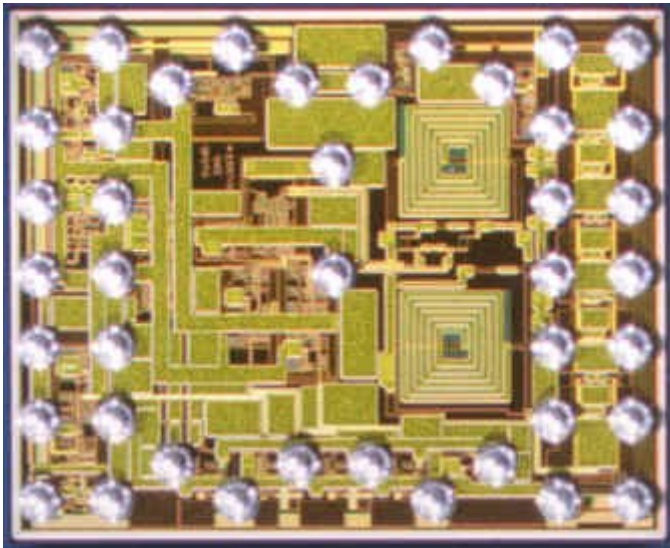
Exemple d'un produit GPS



Exemples de composants GPS

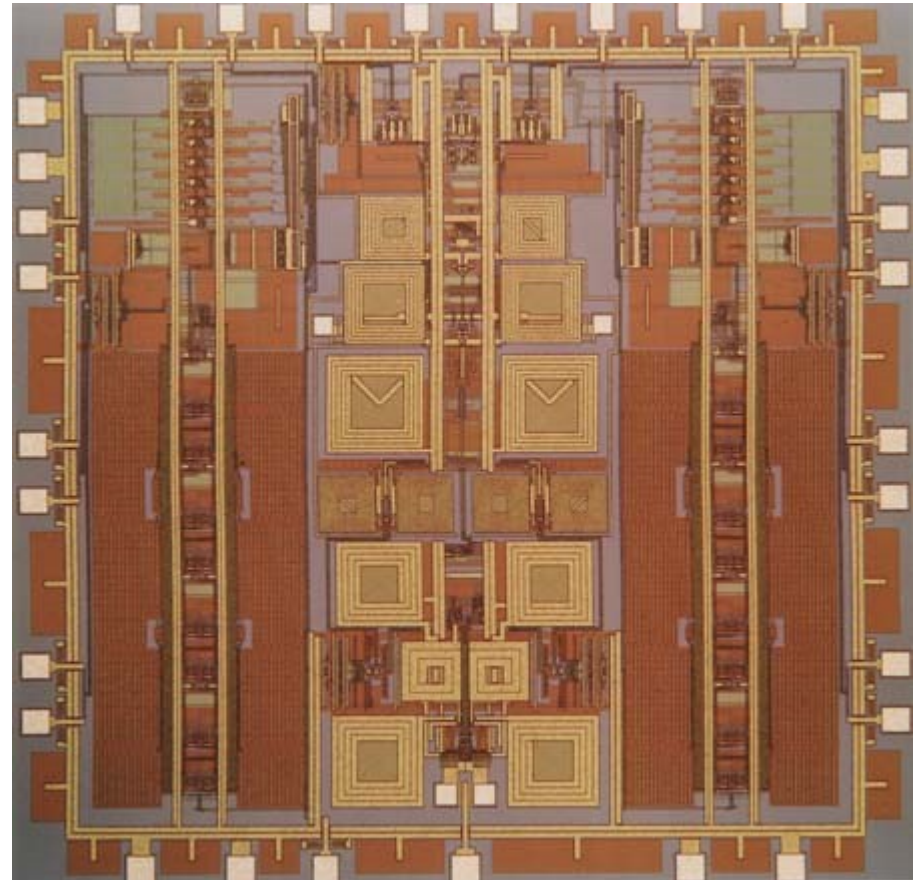


Module



SiGe

2006



Circuit récepteur

J.-C. Martin

Module GPS complet

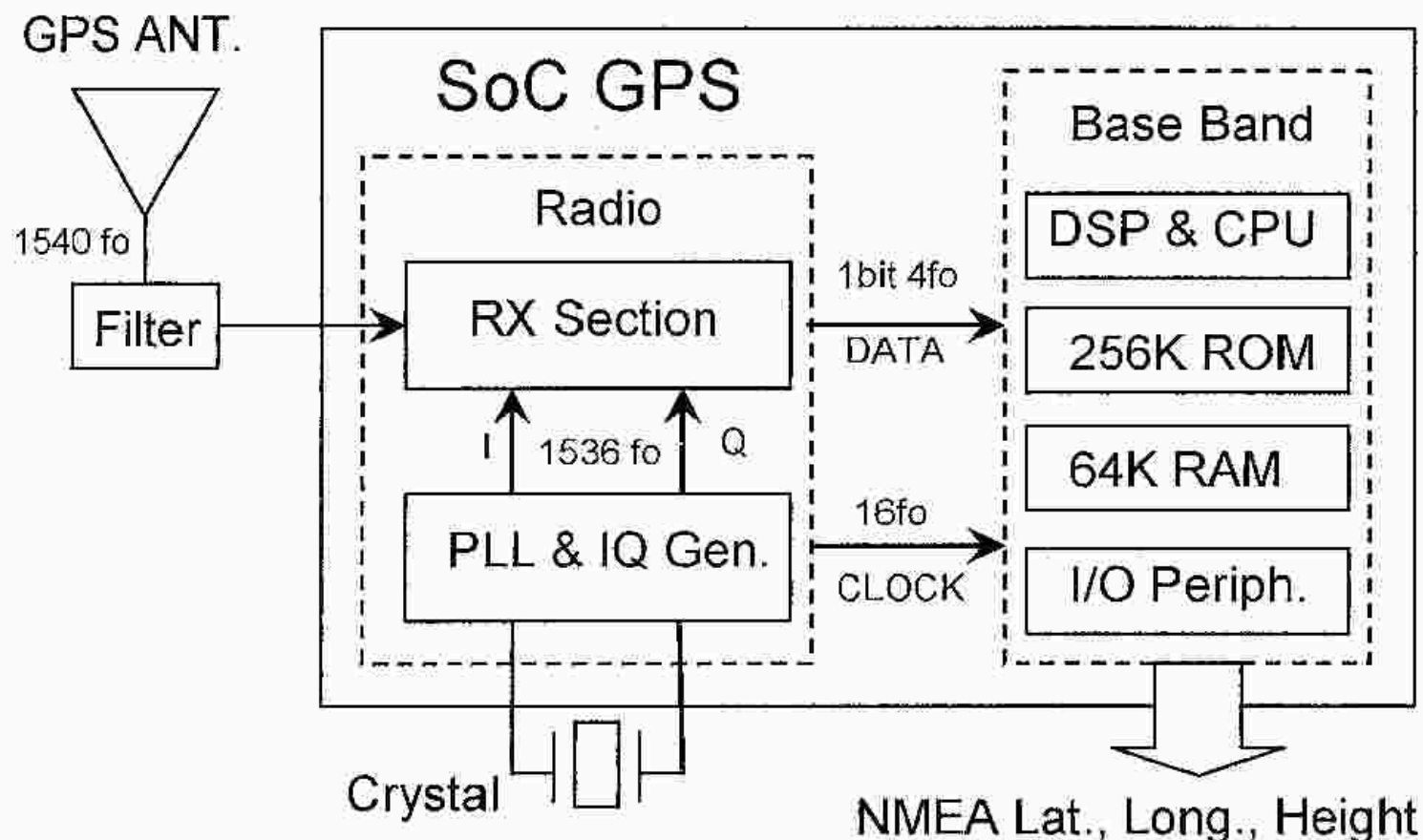
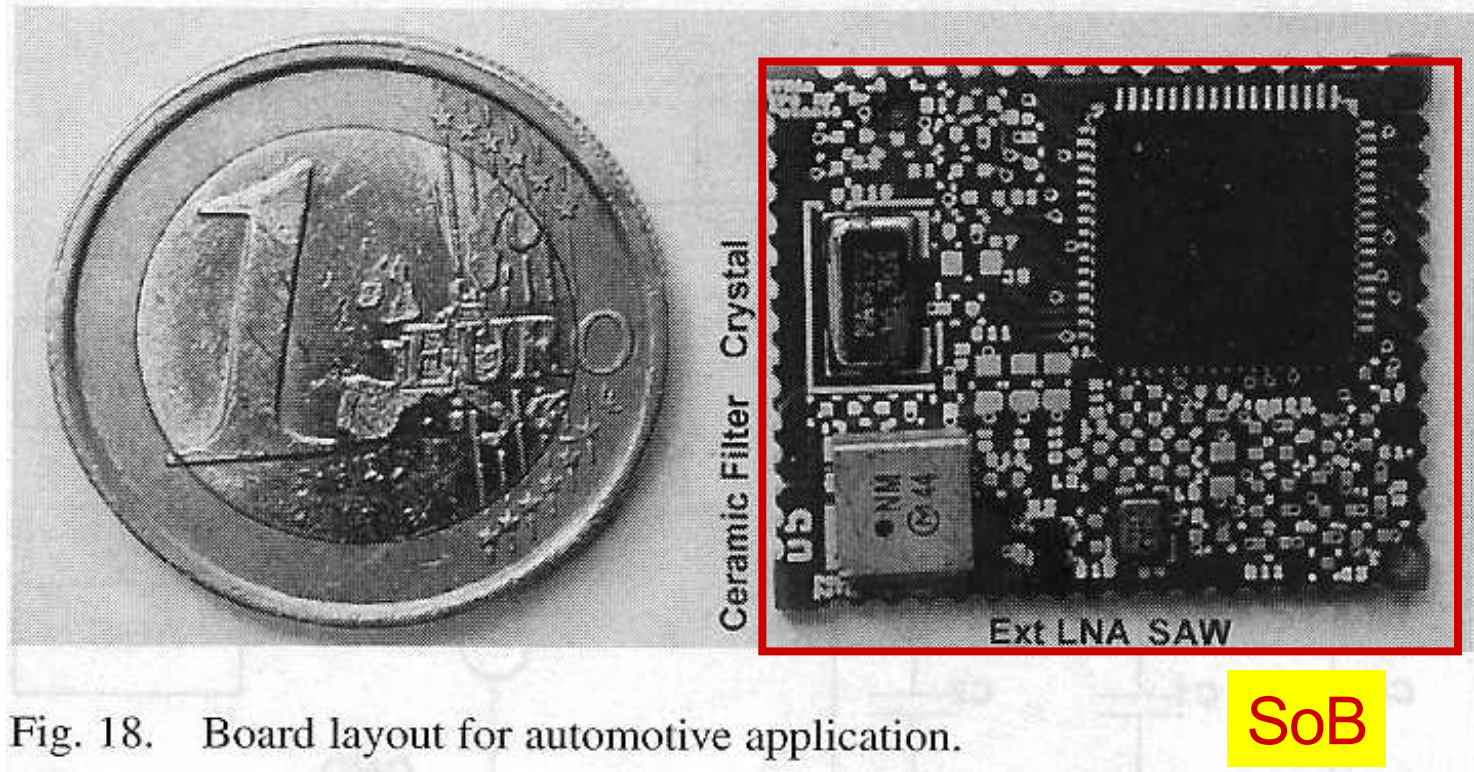


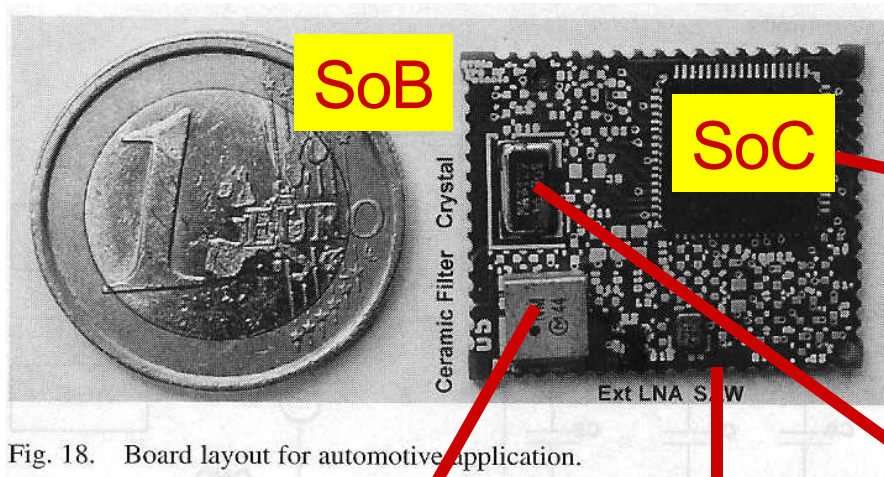
Fig. 1. SoC GPS and required external components.

SoB, CMOS 180nm GPS



IEEE JSSC march 2006, STMicroelectronics

SoB, CMOS GPS

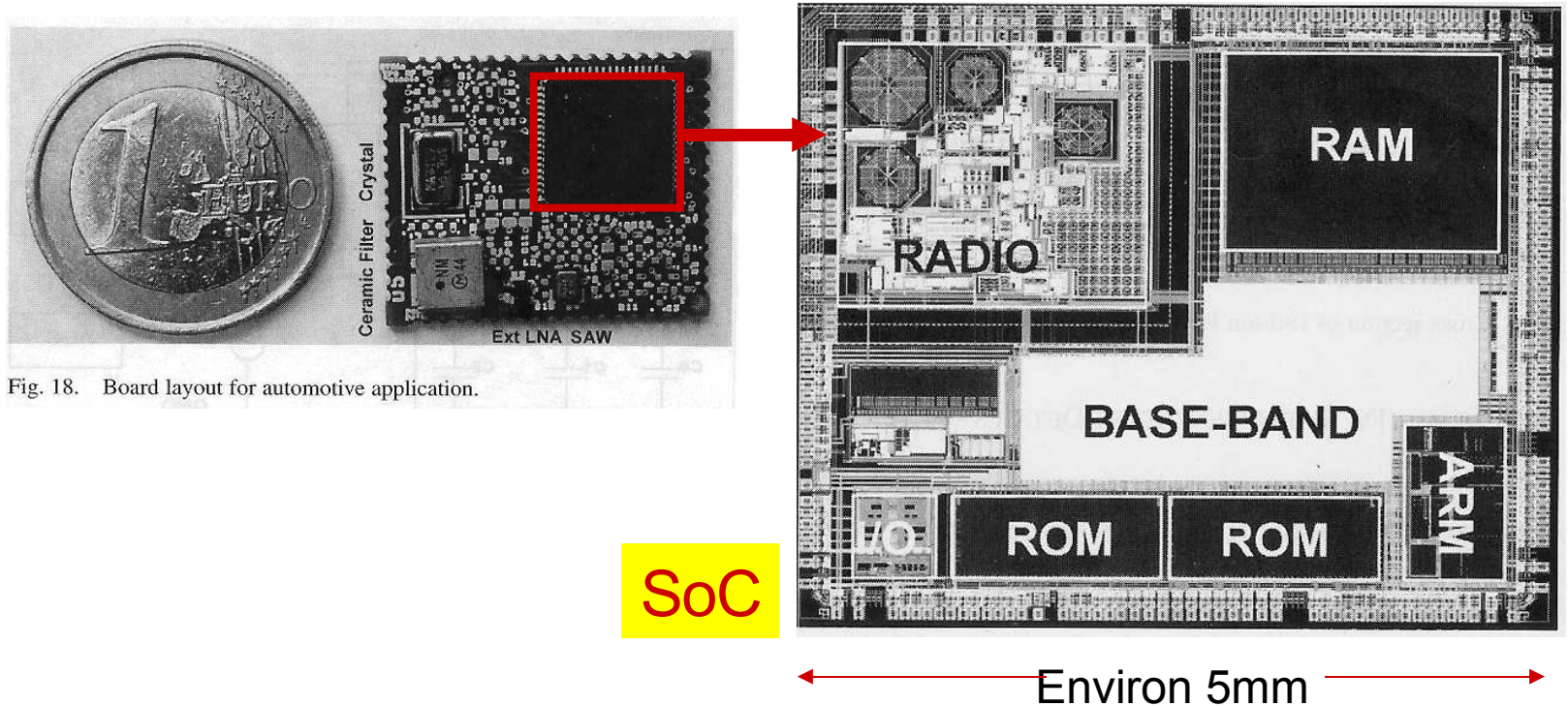


Filtre et antenne 1.54 GHz

Quartz crystal 16.368 MHz

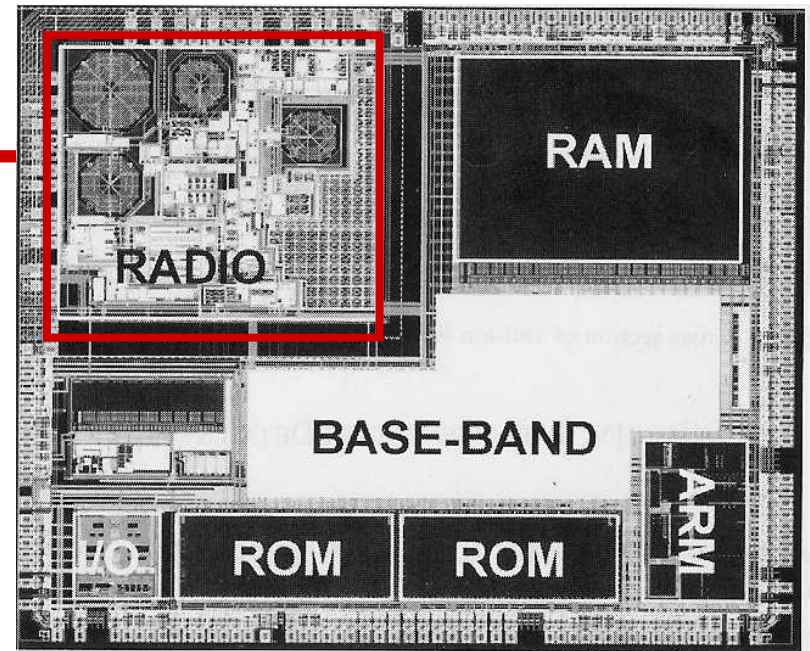
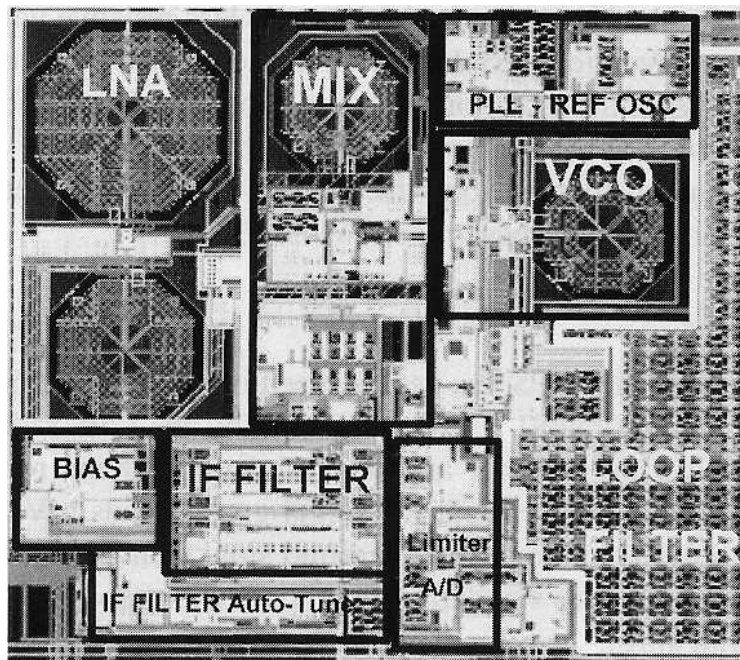
Longitude, latitude, hauteur

SoC, CMOS IC



CMOS IC 56mW 23mm³

SoC, CMOS IC with radio



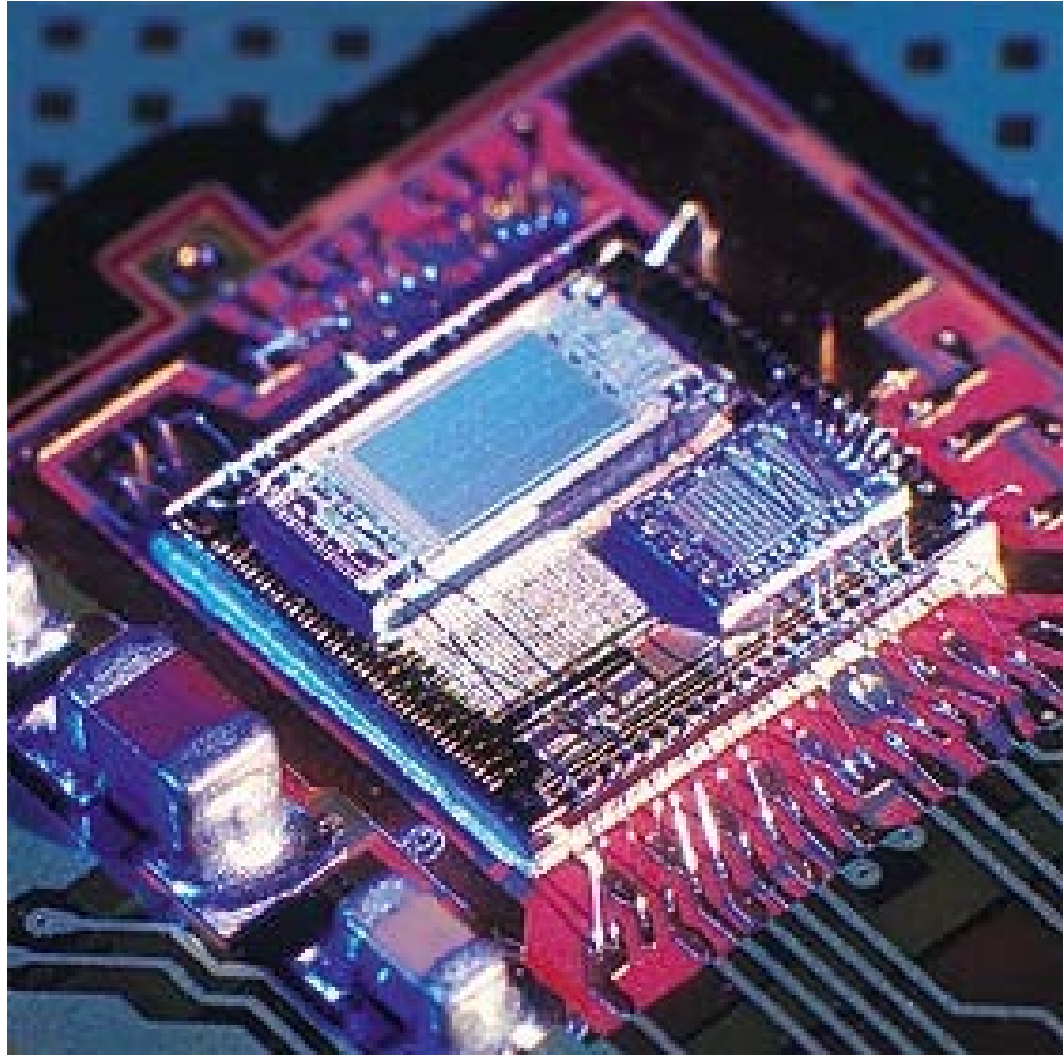
← Environ 5mm →

CMOS radio 2.2x1.8mm

SiP

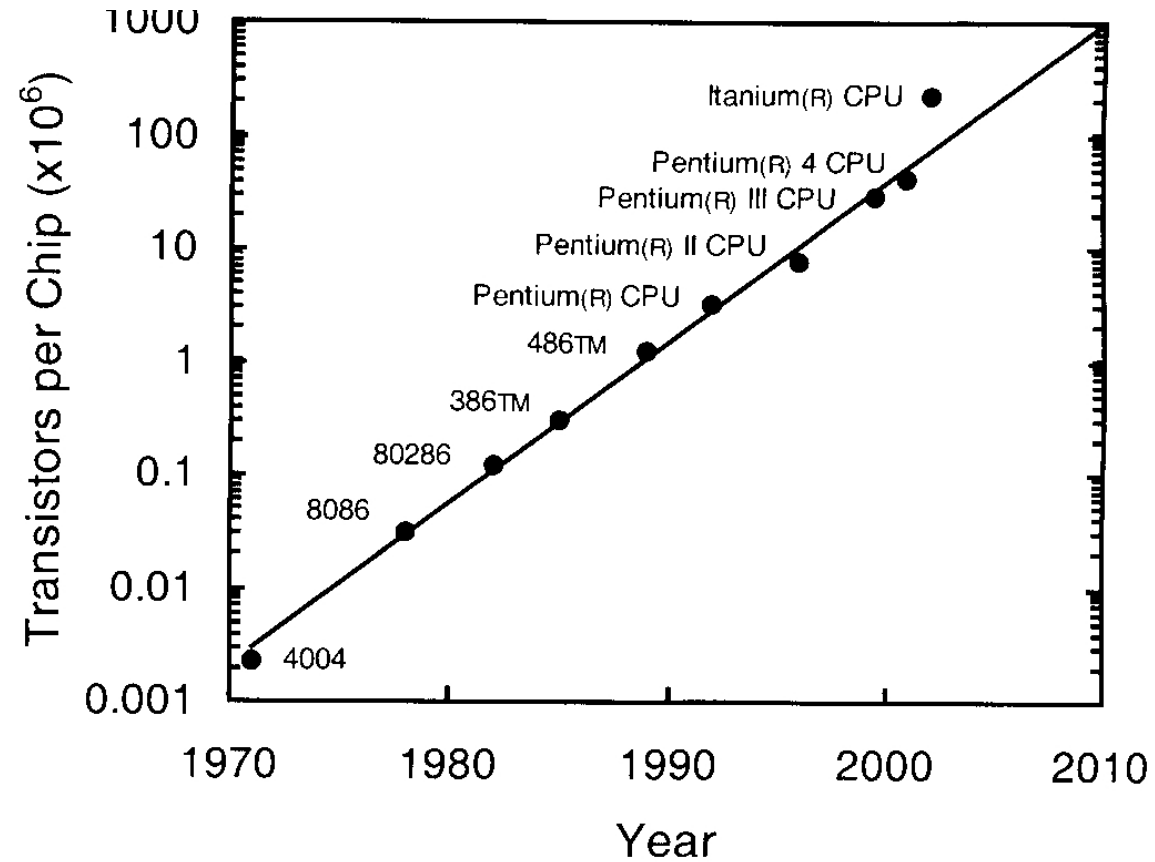
Microdul

- COC
- MD100
- MD300
- bonding

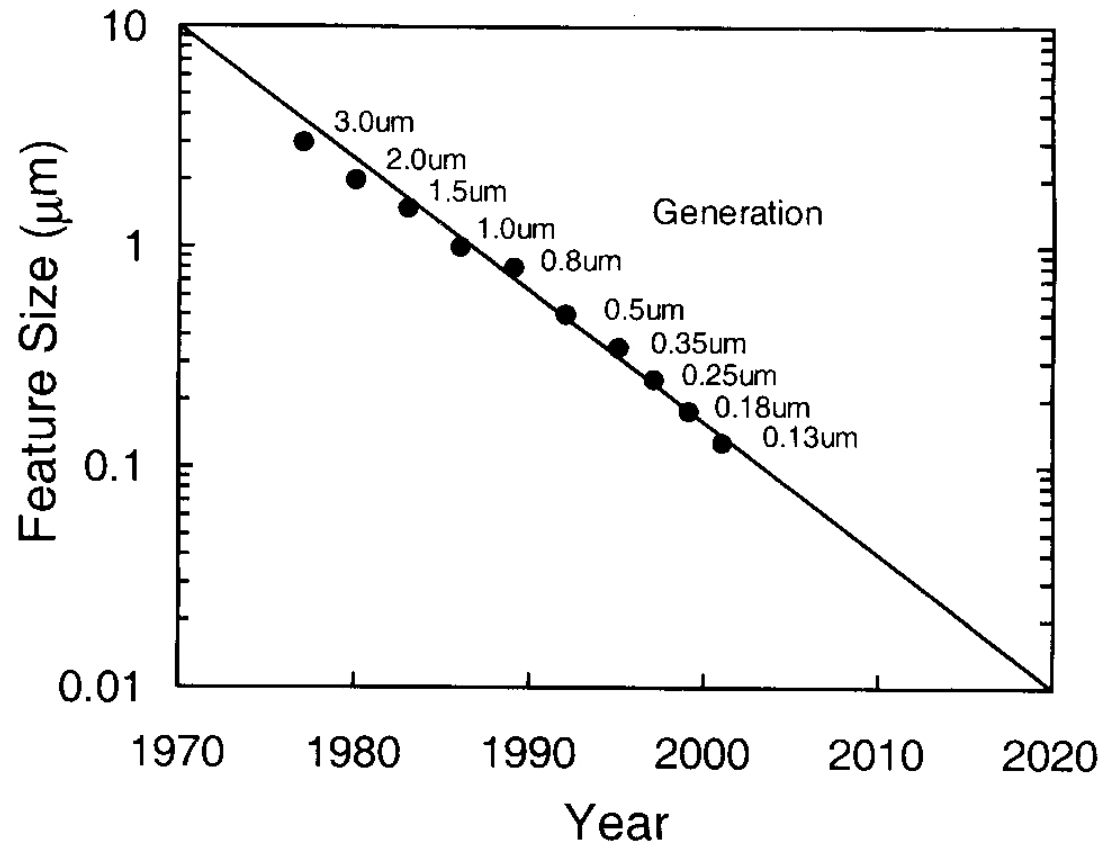


Evolution of IC

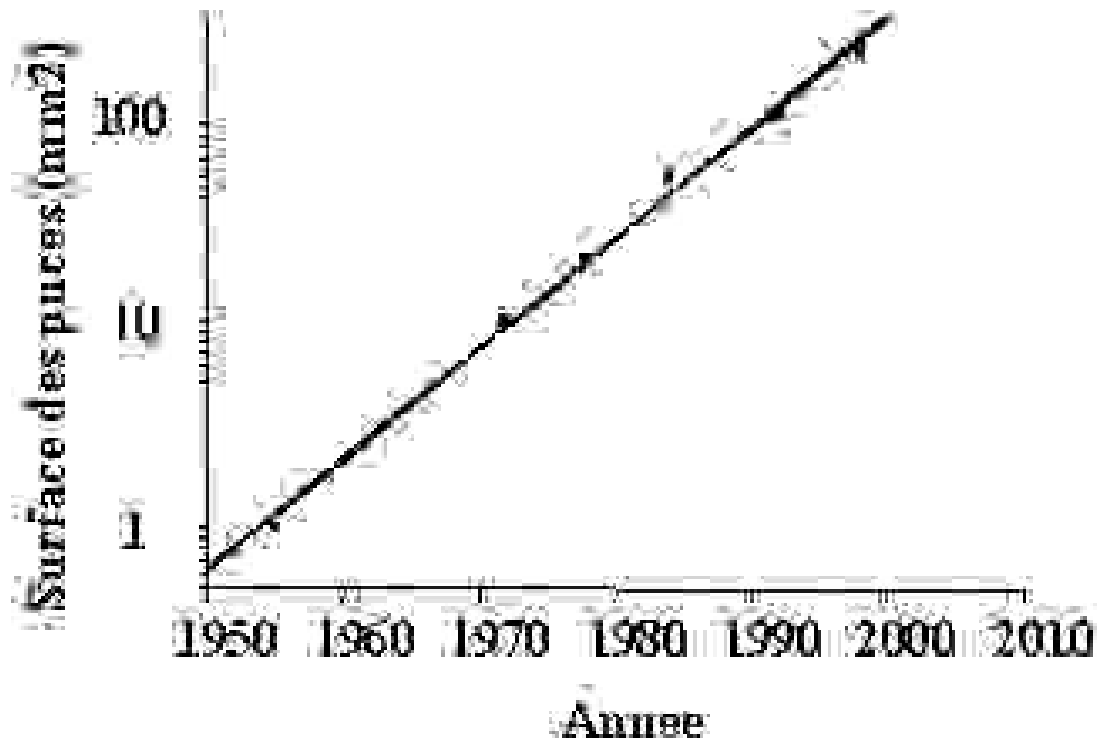
Evolution of complexity



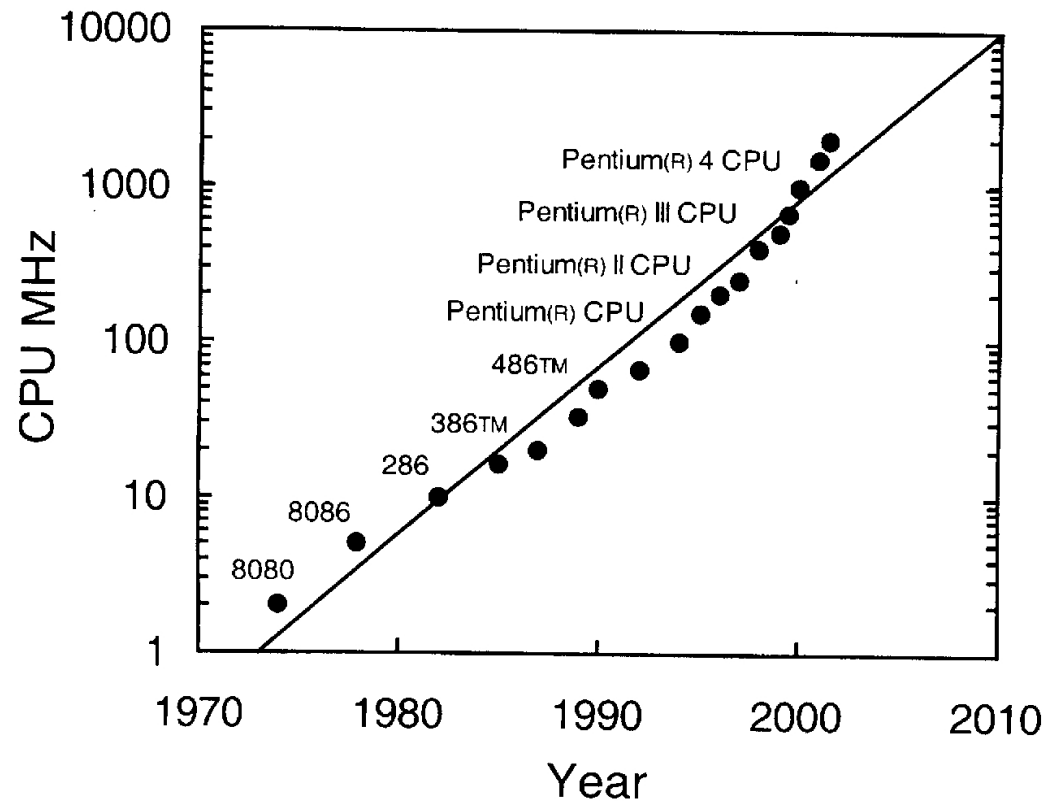
Evolution of technology



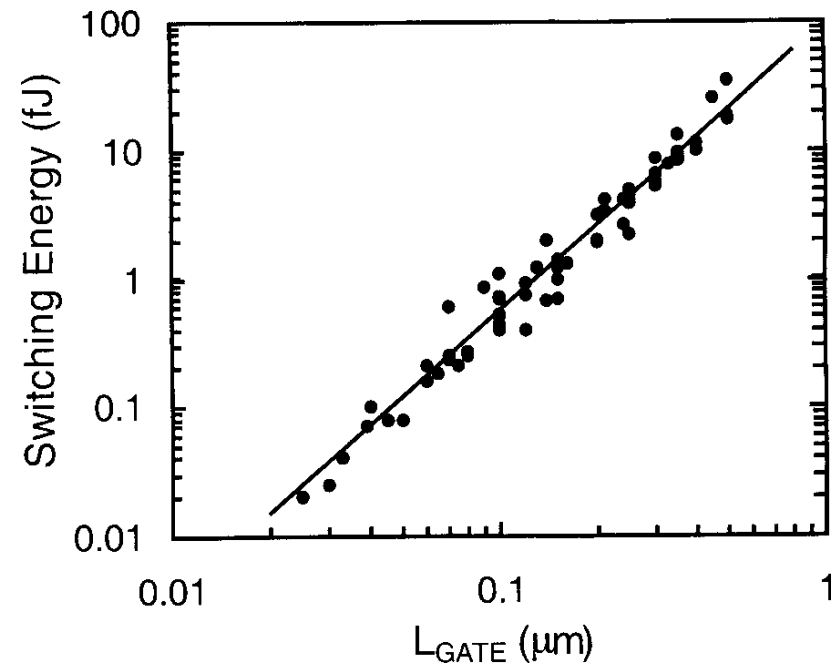
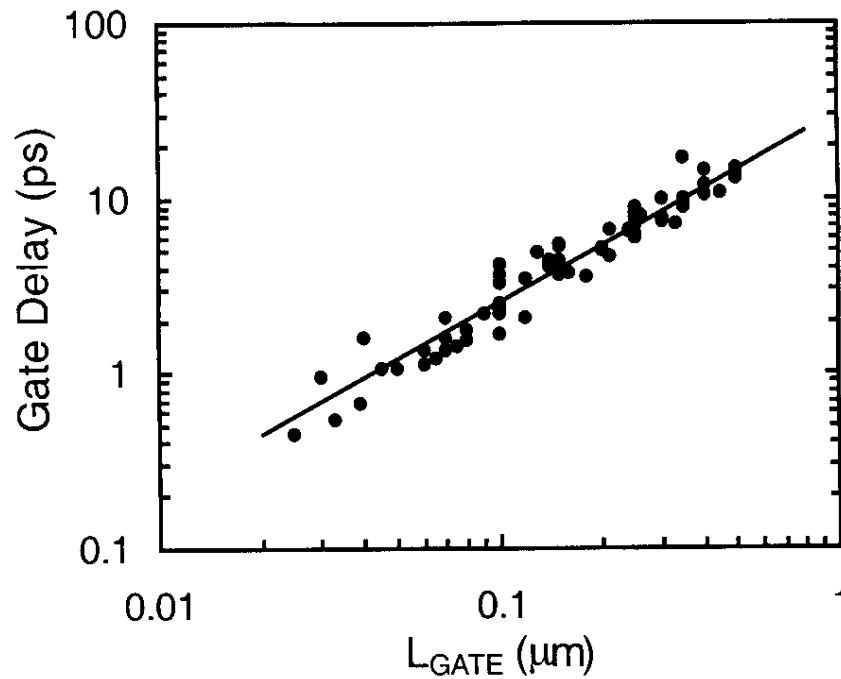
Evolution of chip size



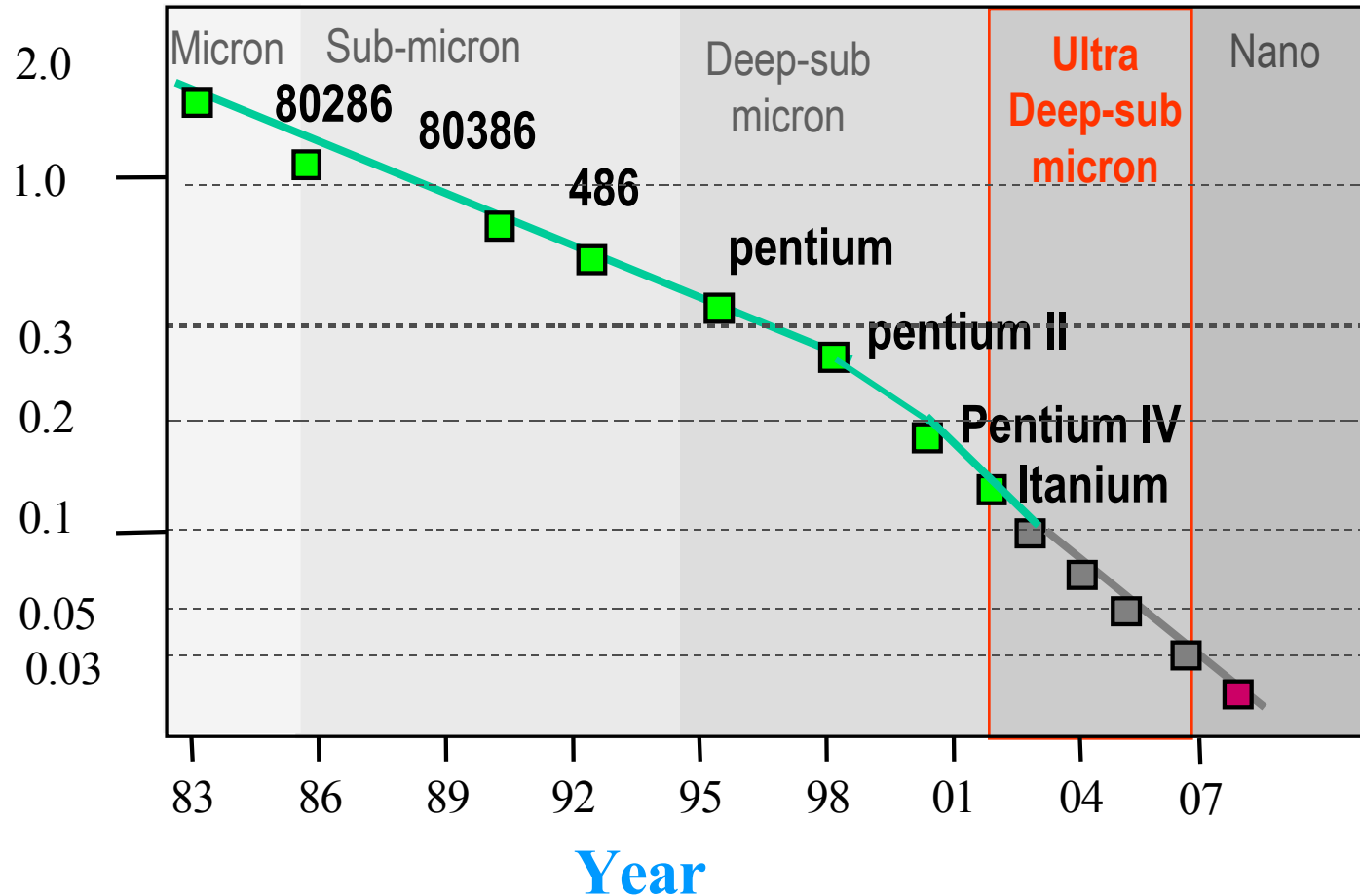
Frequency of PC's

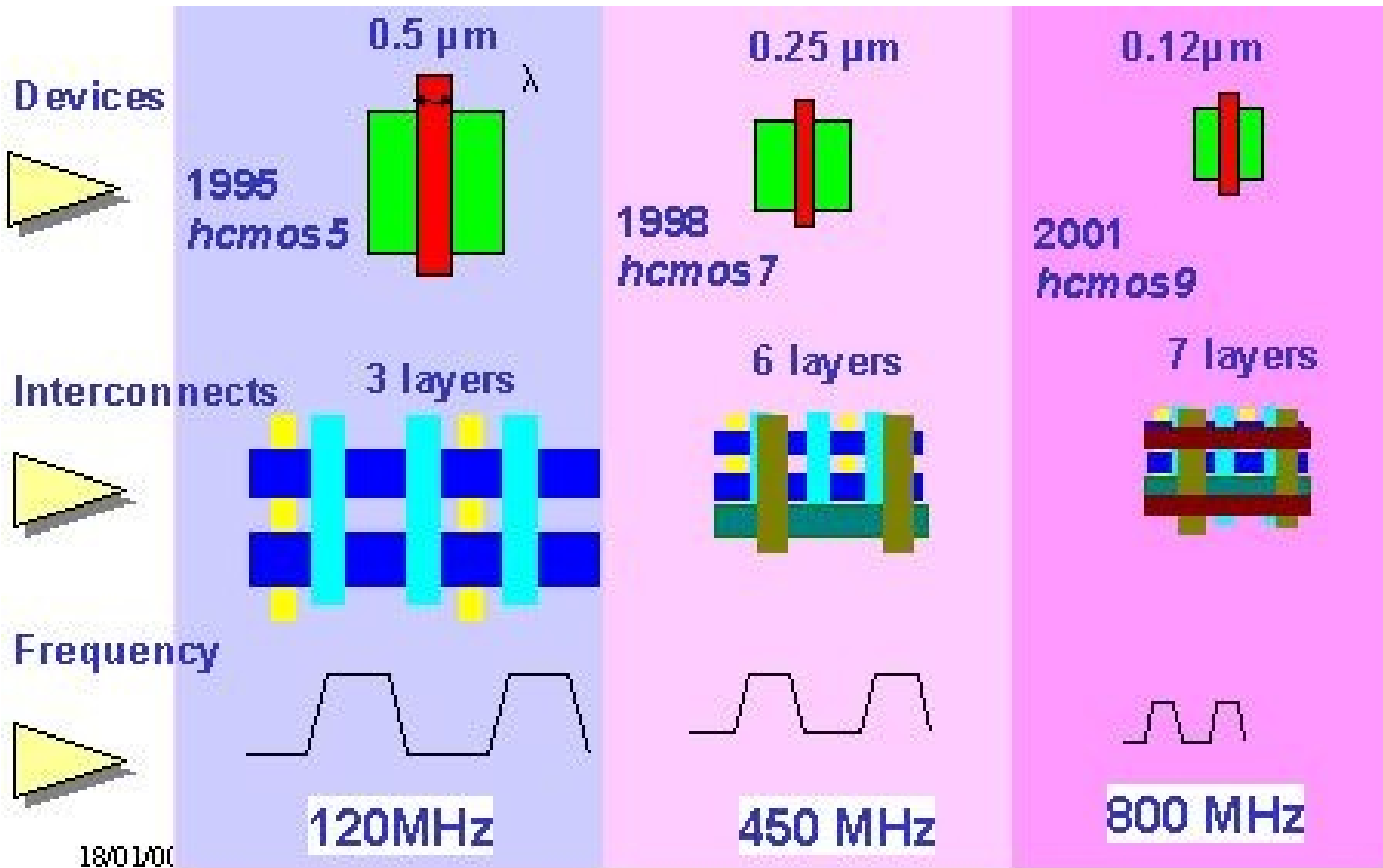


$L(\text{gate})$



Loi de Moore

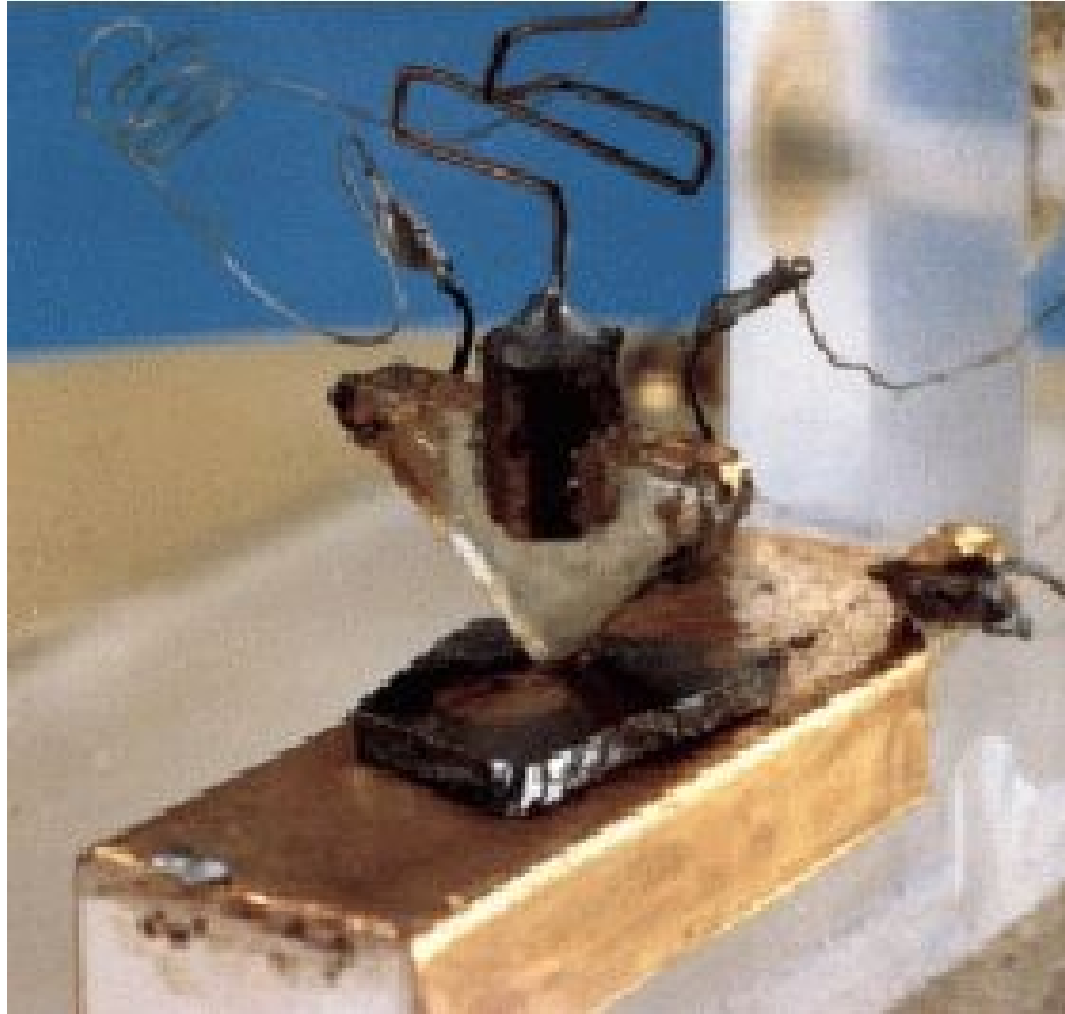


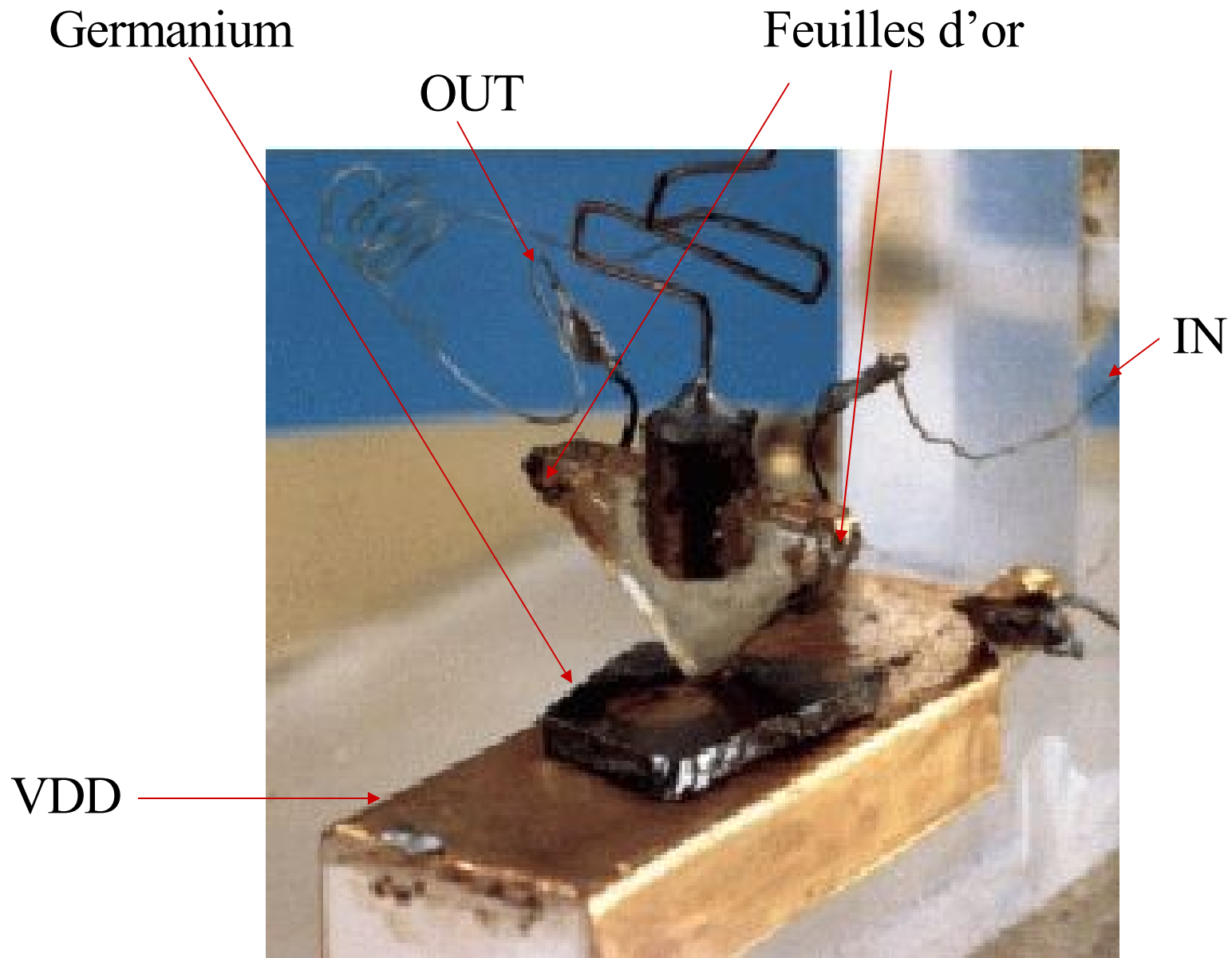


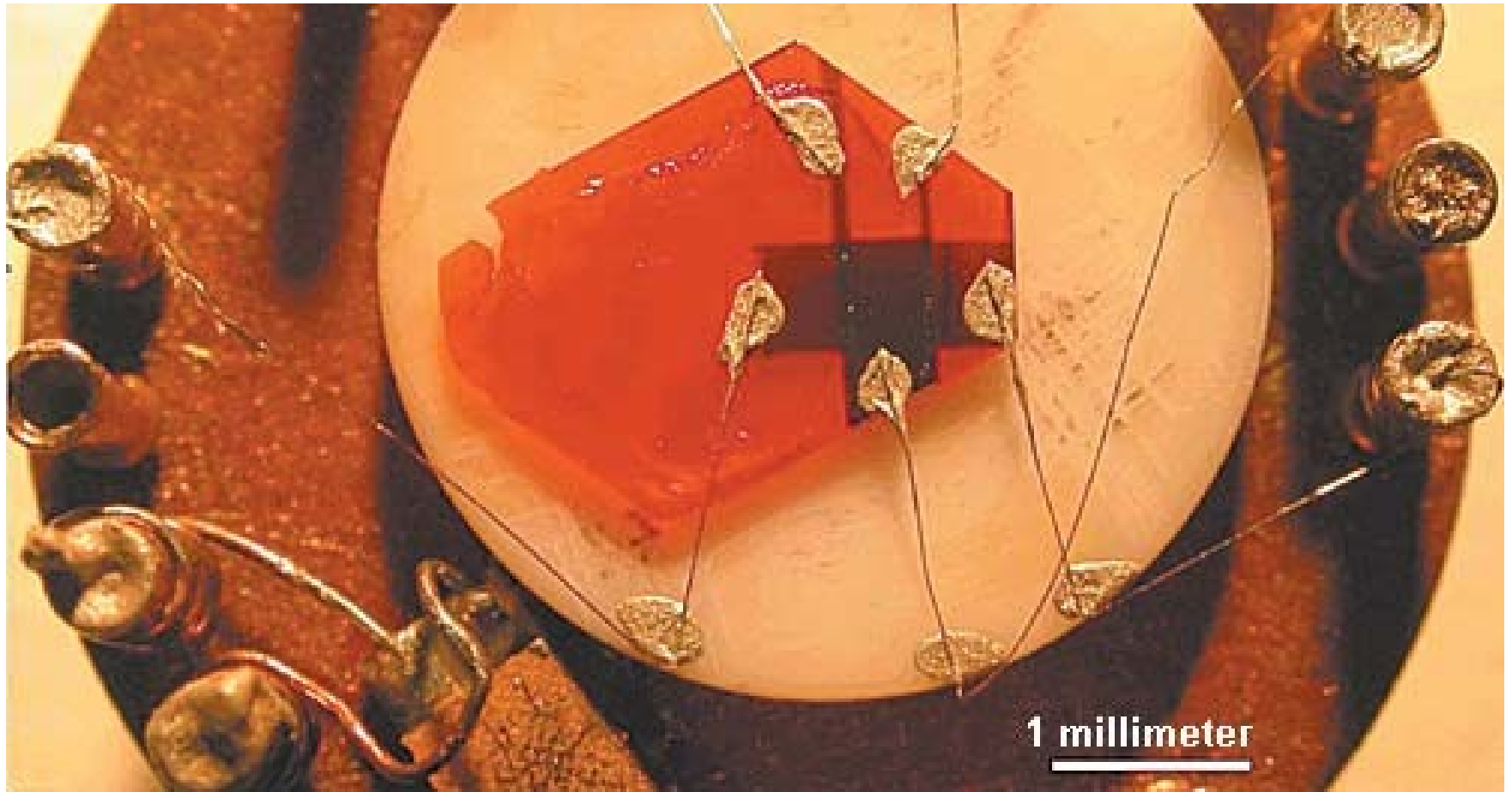
18/01/06

History of chips

1947 bipolar transistor







This single-crystal organic field-effect transistor, created by researchers at Rutgers University, in New Jersey is based on a rubrene single crystal [red hexagon] and is shown wired to the pins of a sample holder. It is the first organic transistor to be light-switchable.

IEEE Spectrum aug.2005

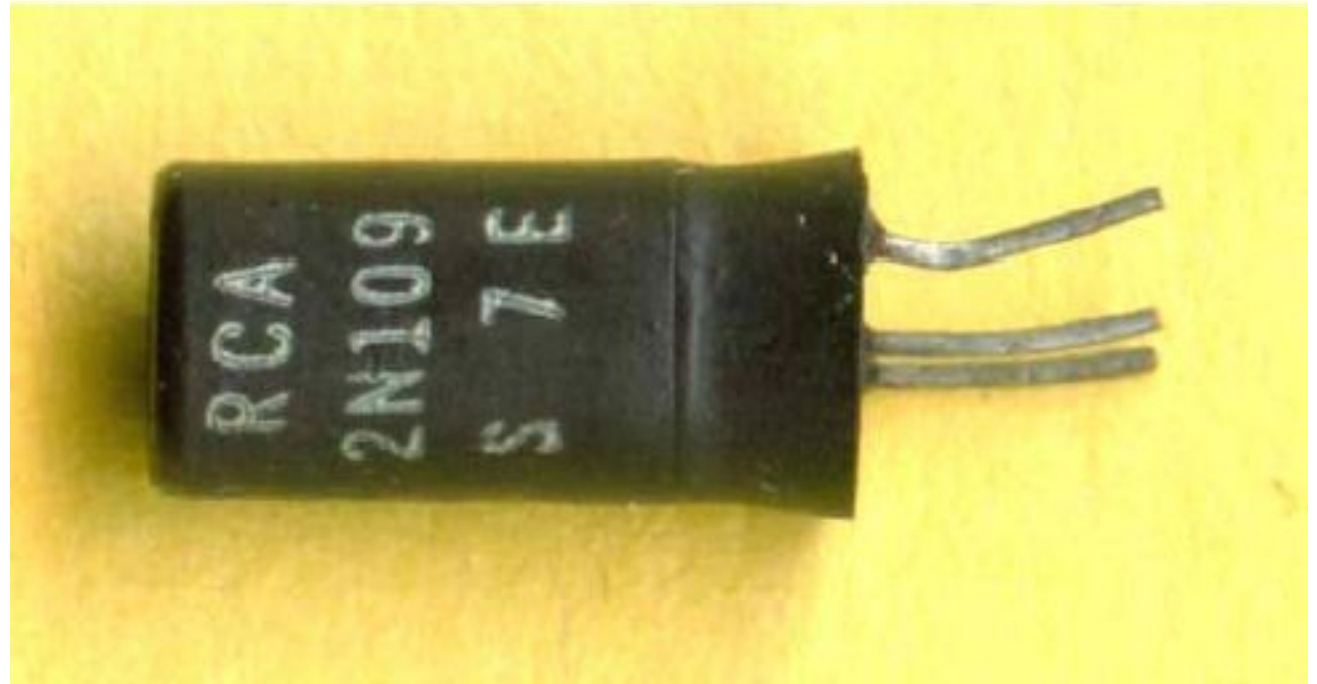
2006

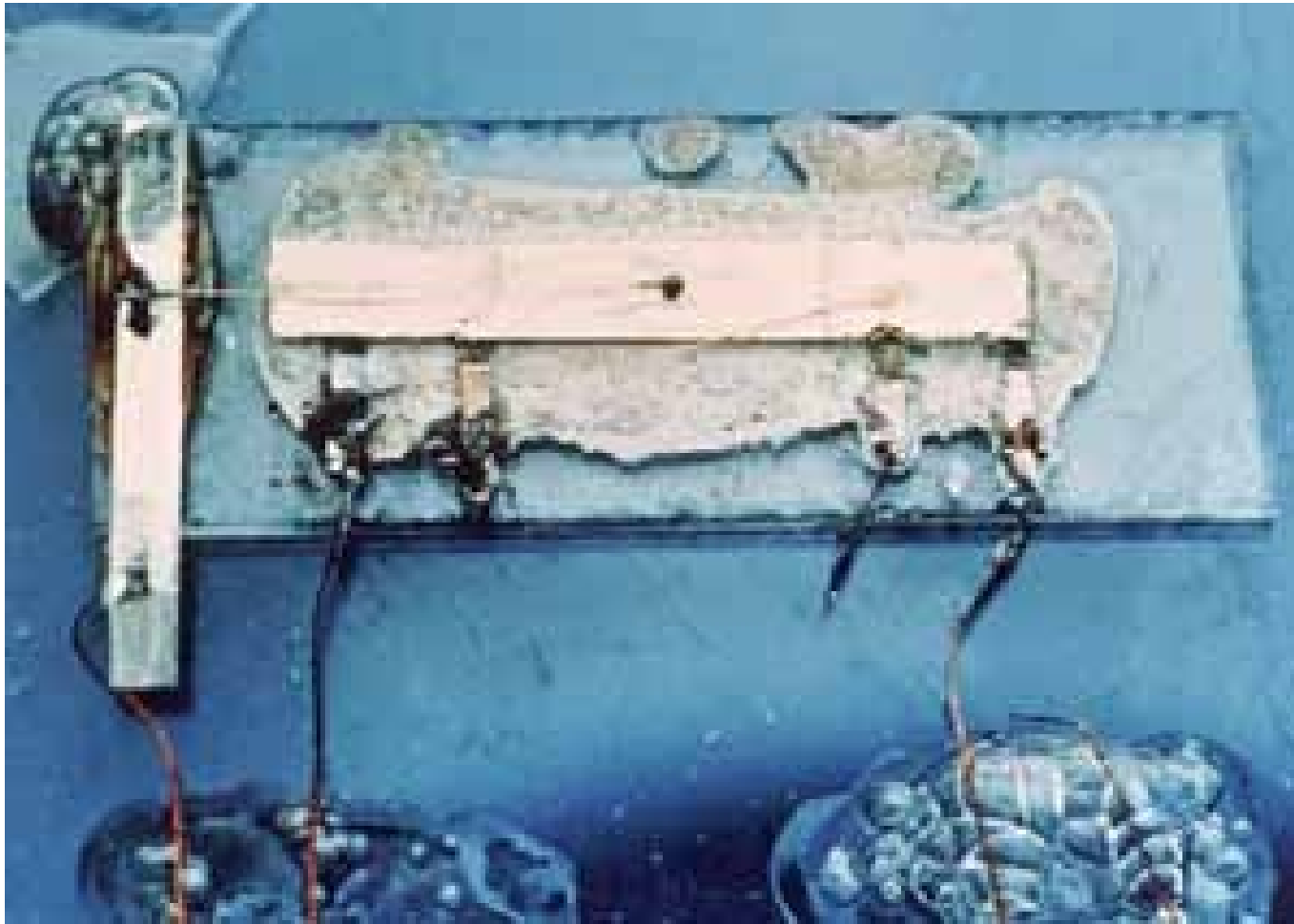
J.-C. Martin

29

RCA 2N109 (1955)

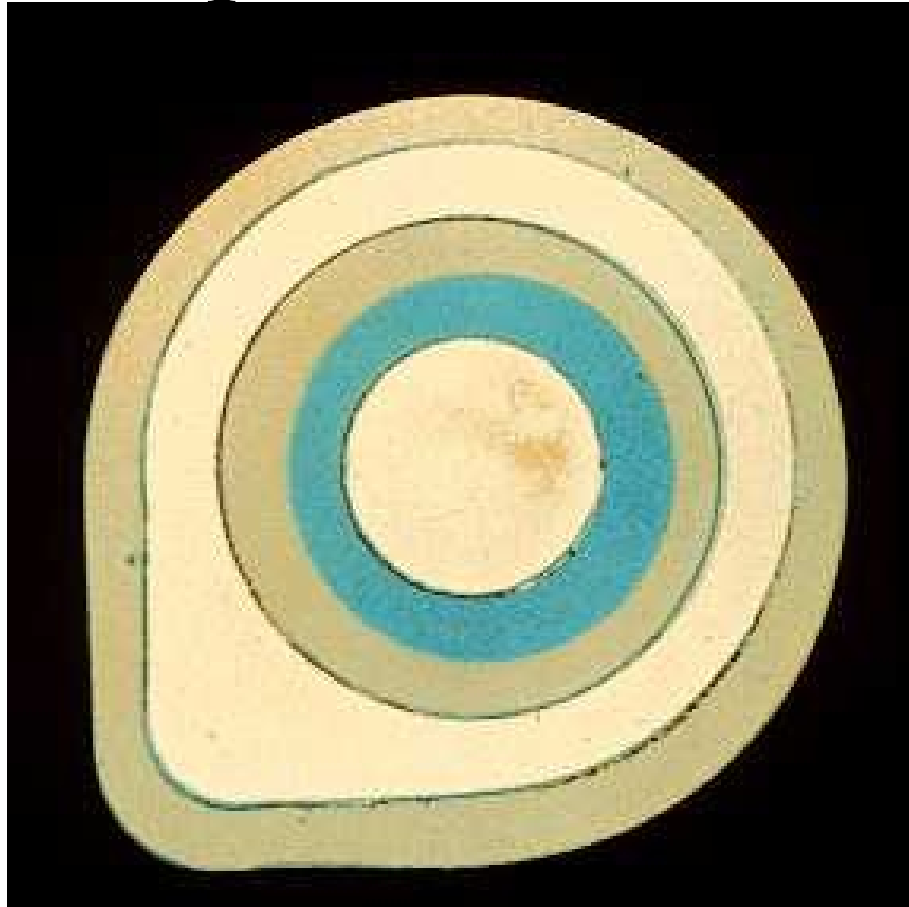
- Pour radios
- PNP
- Ge
- 2.5\$



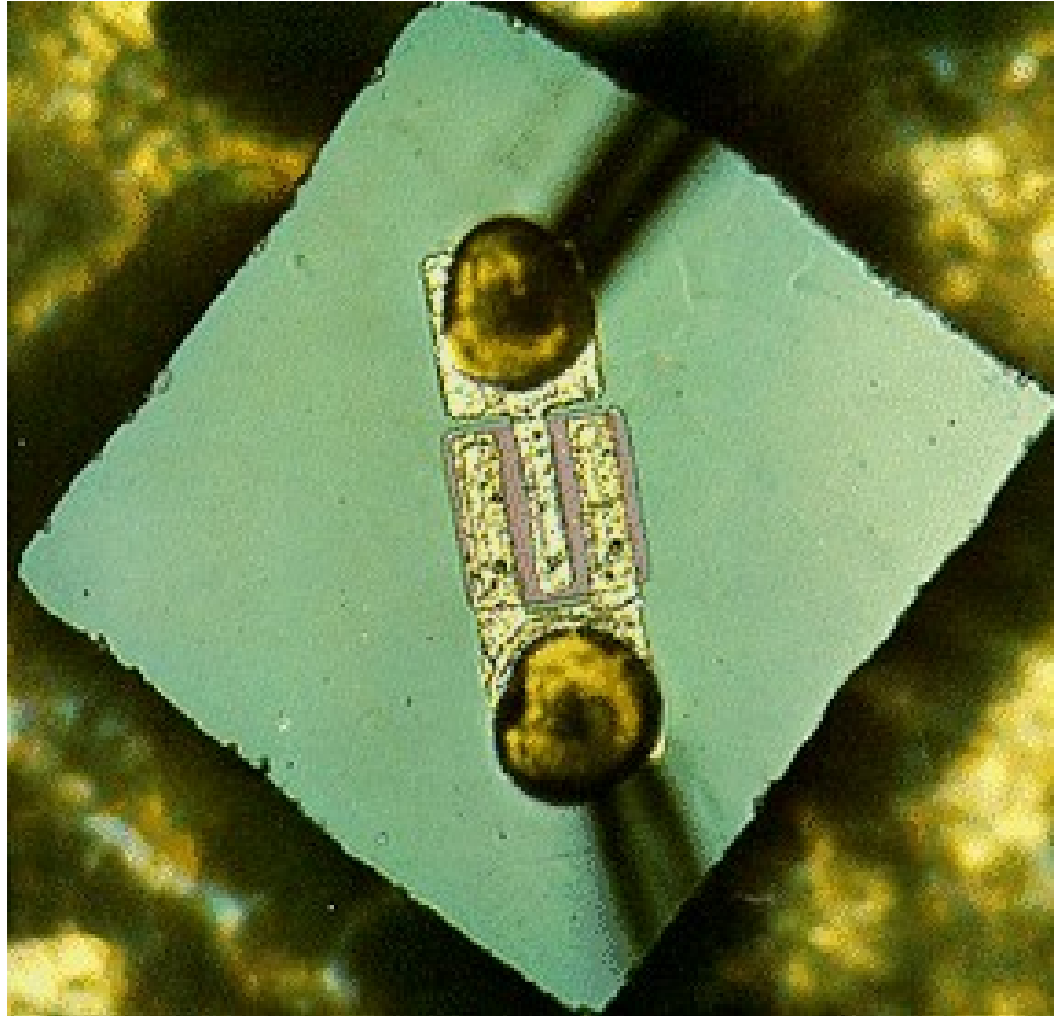


Jack Kilby of Texas Instruments made this, the first integrated circuit, in 1958.

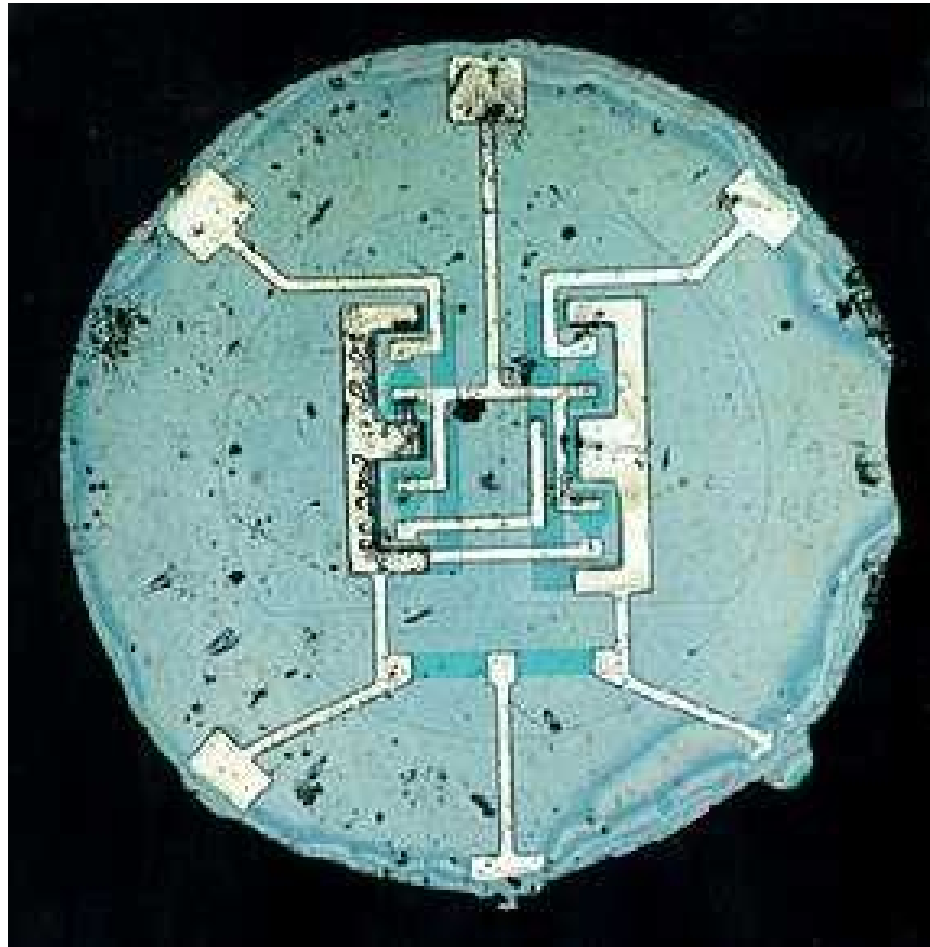
1959 planar transistor



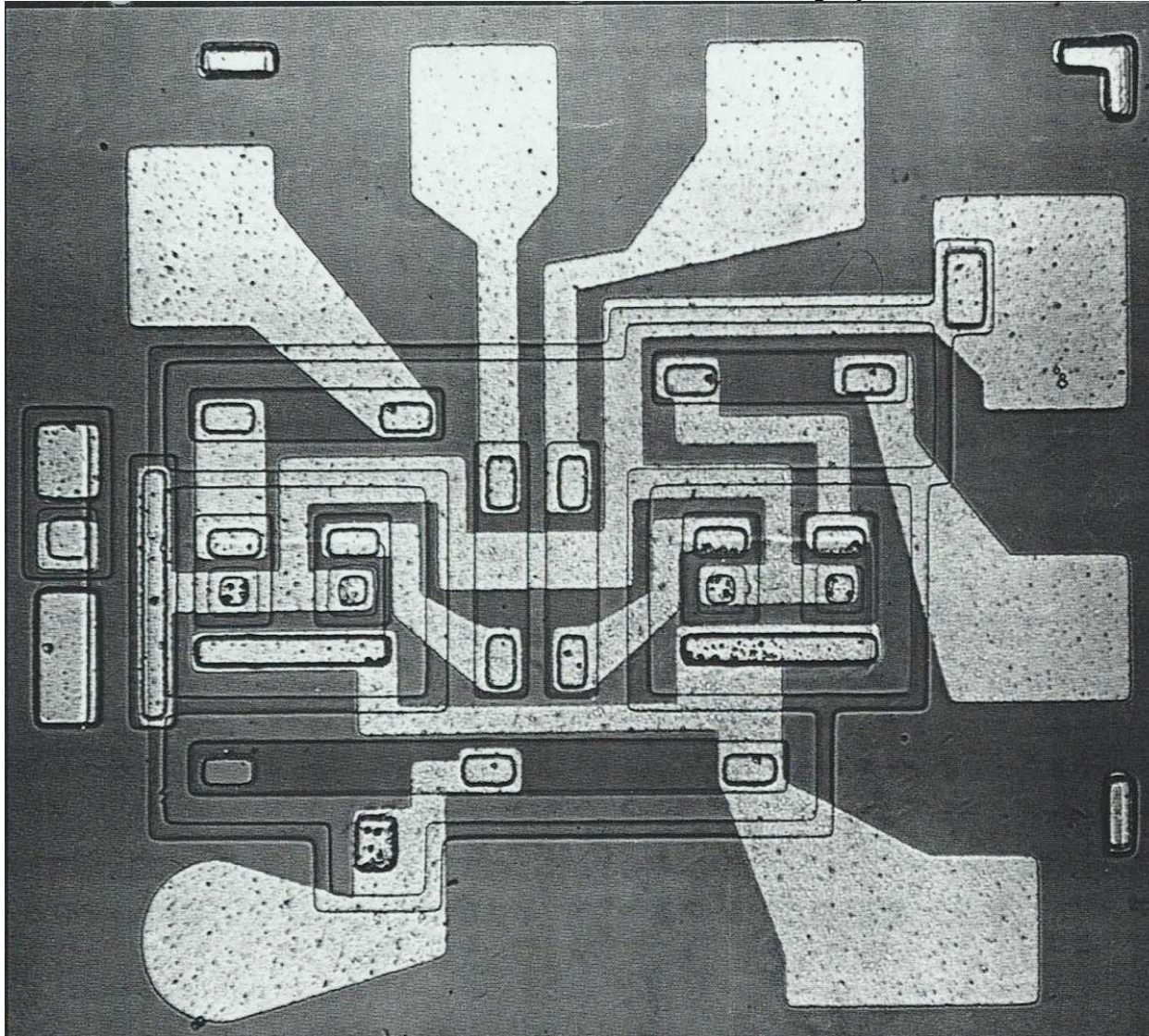
NPN transistor



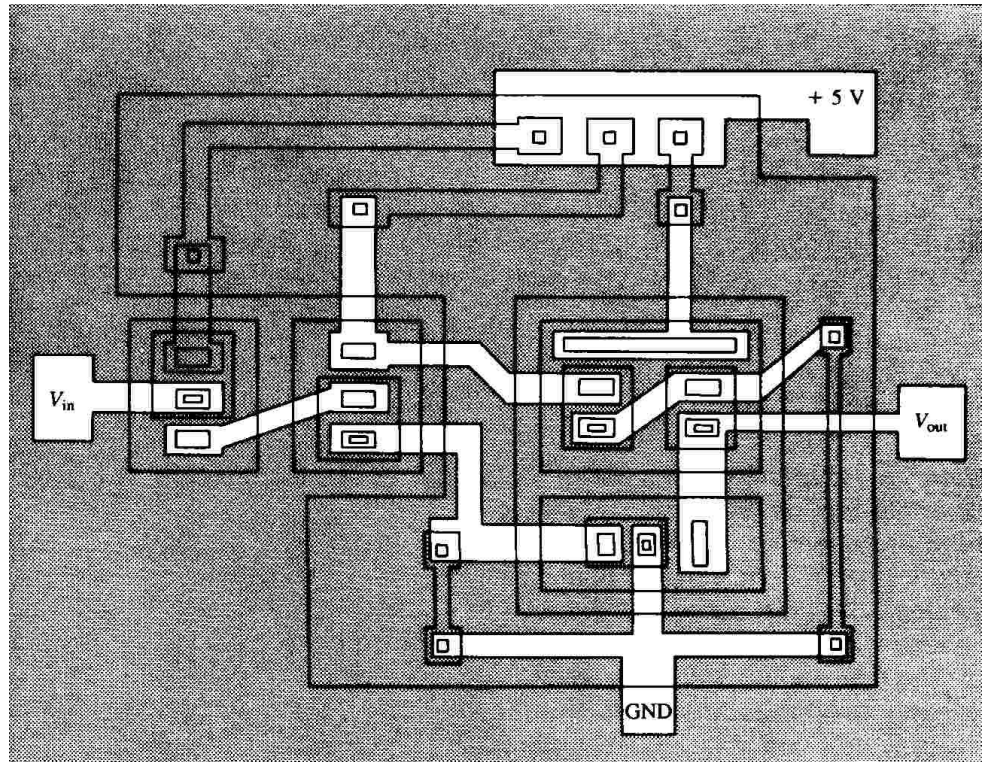
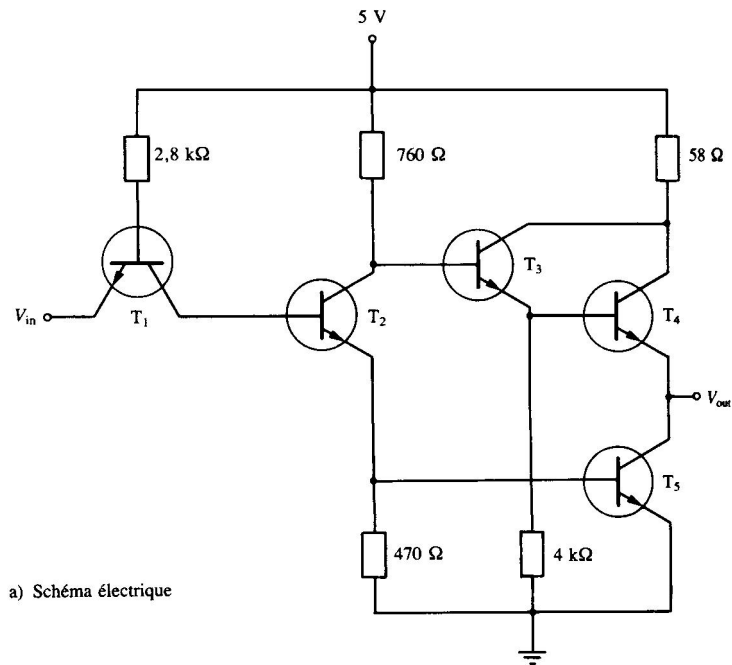
1961 integrated circuit



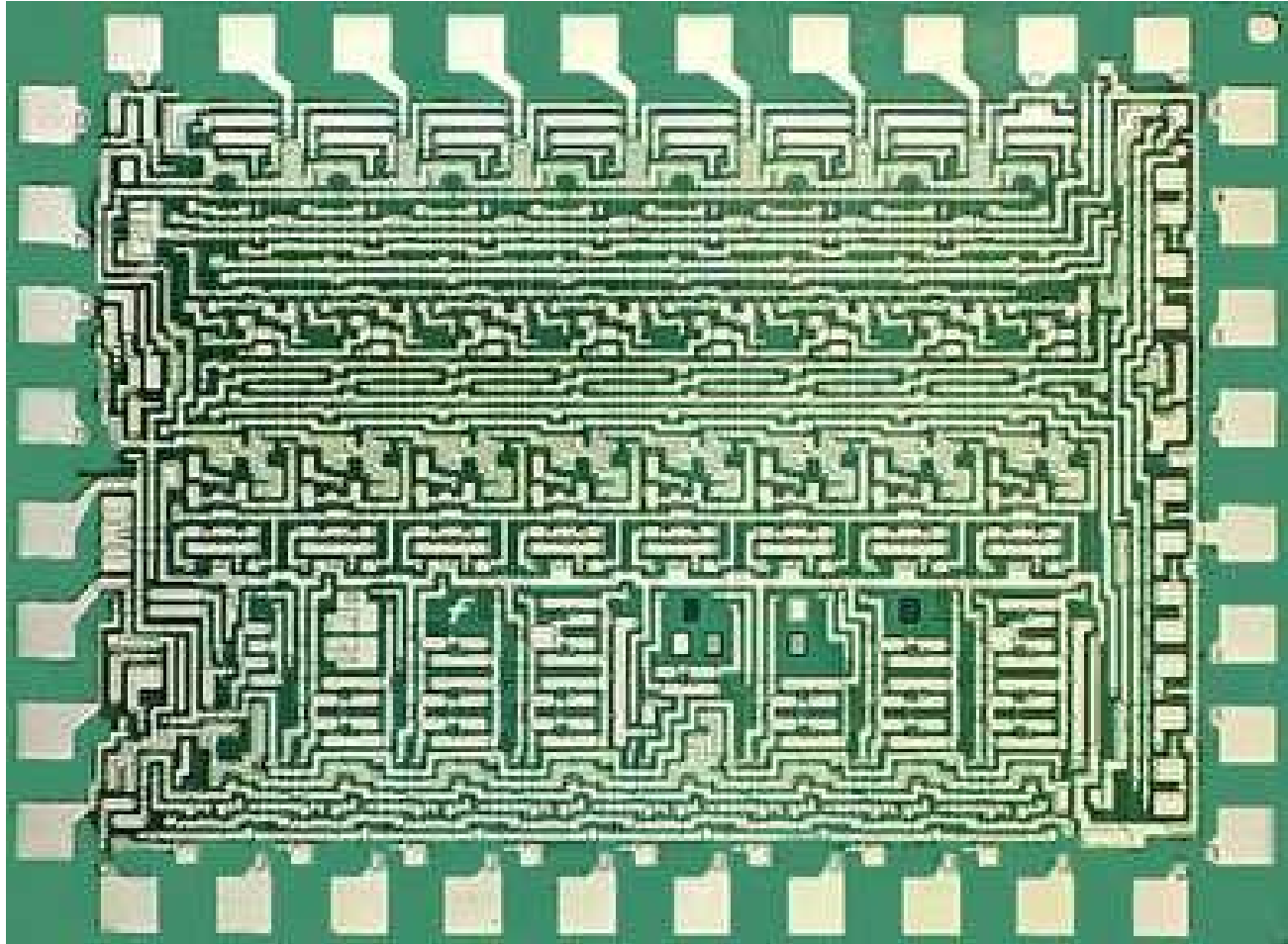
1963 RTL logic



TTL

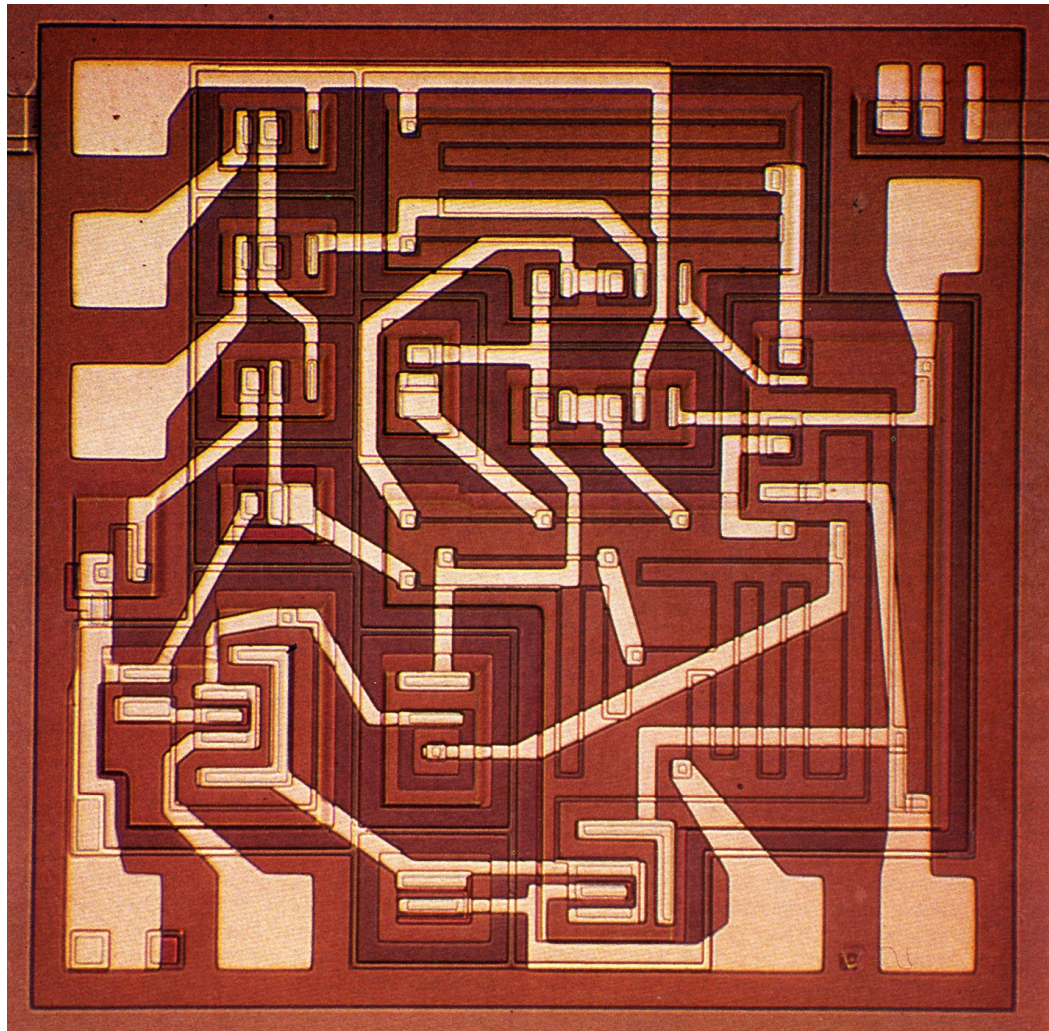


1967 MOS

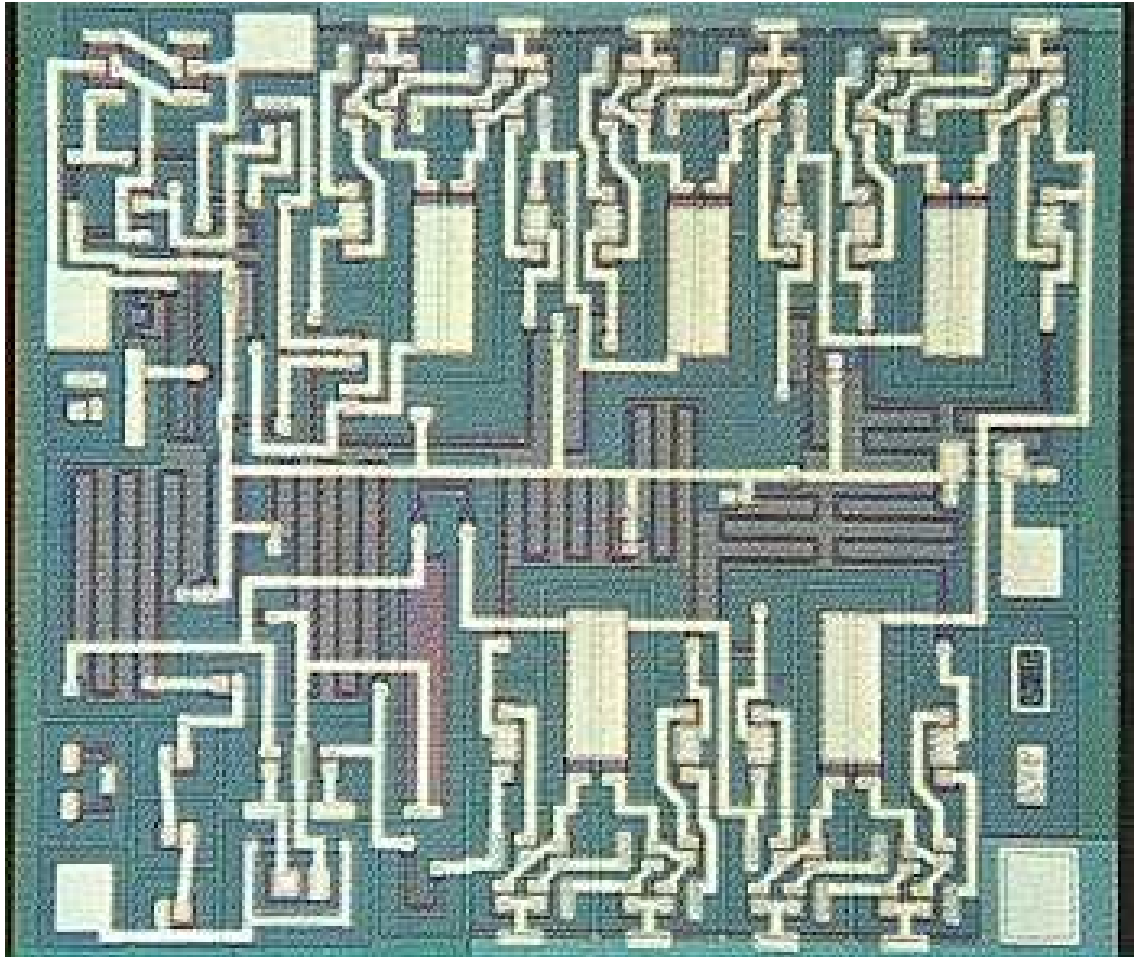


Ampli Op

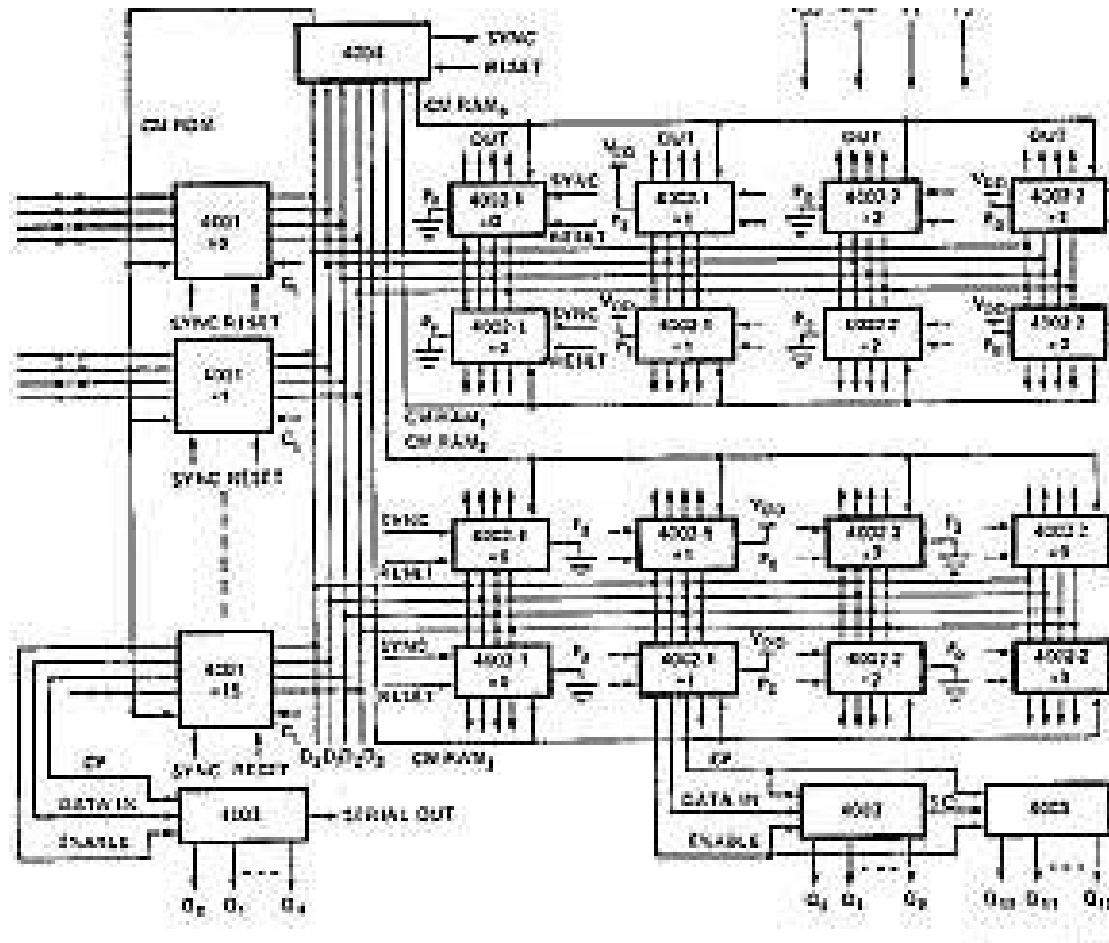
- bipolaire

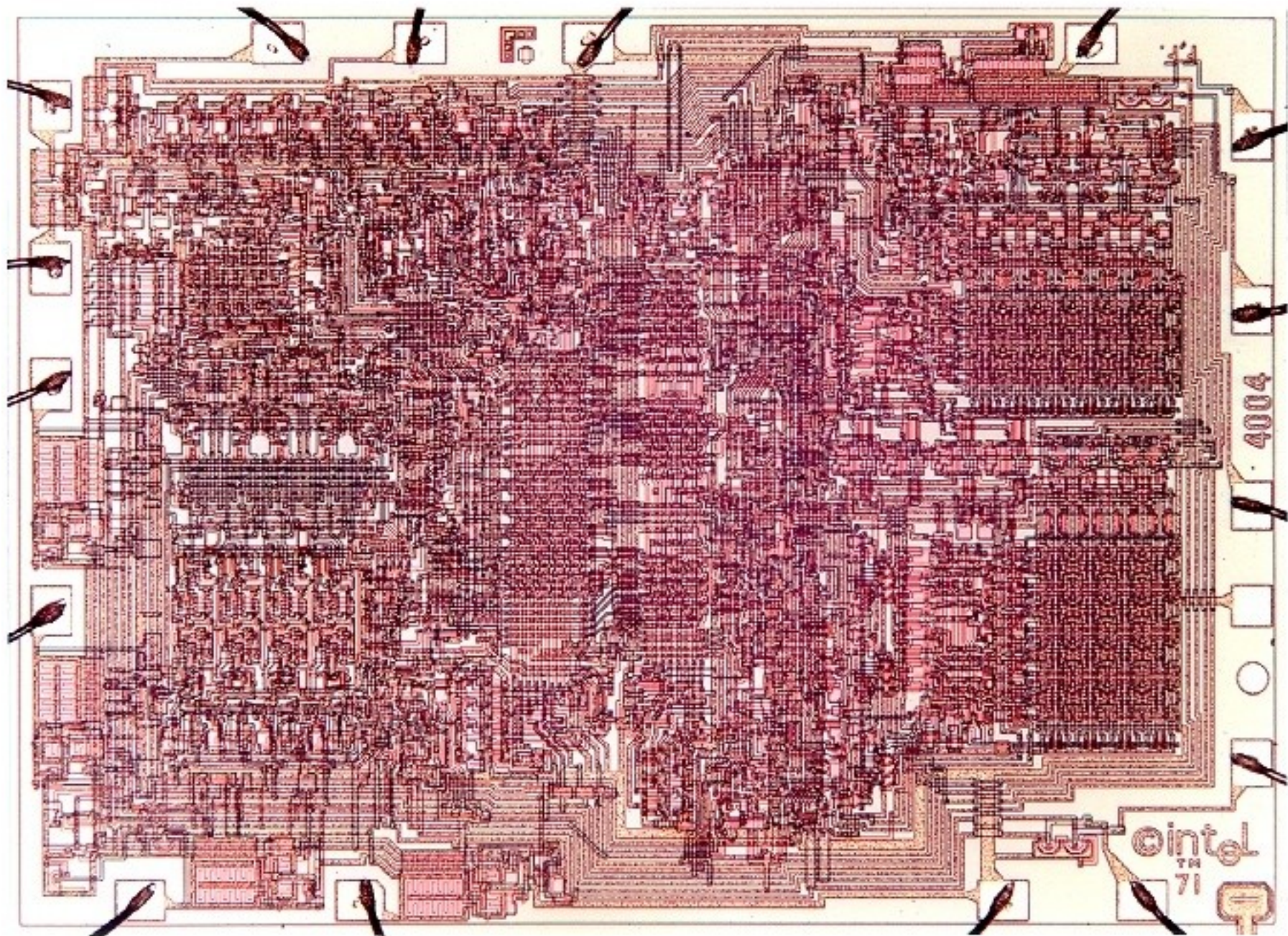


1967 first quartz watch (CEH)

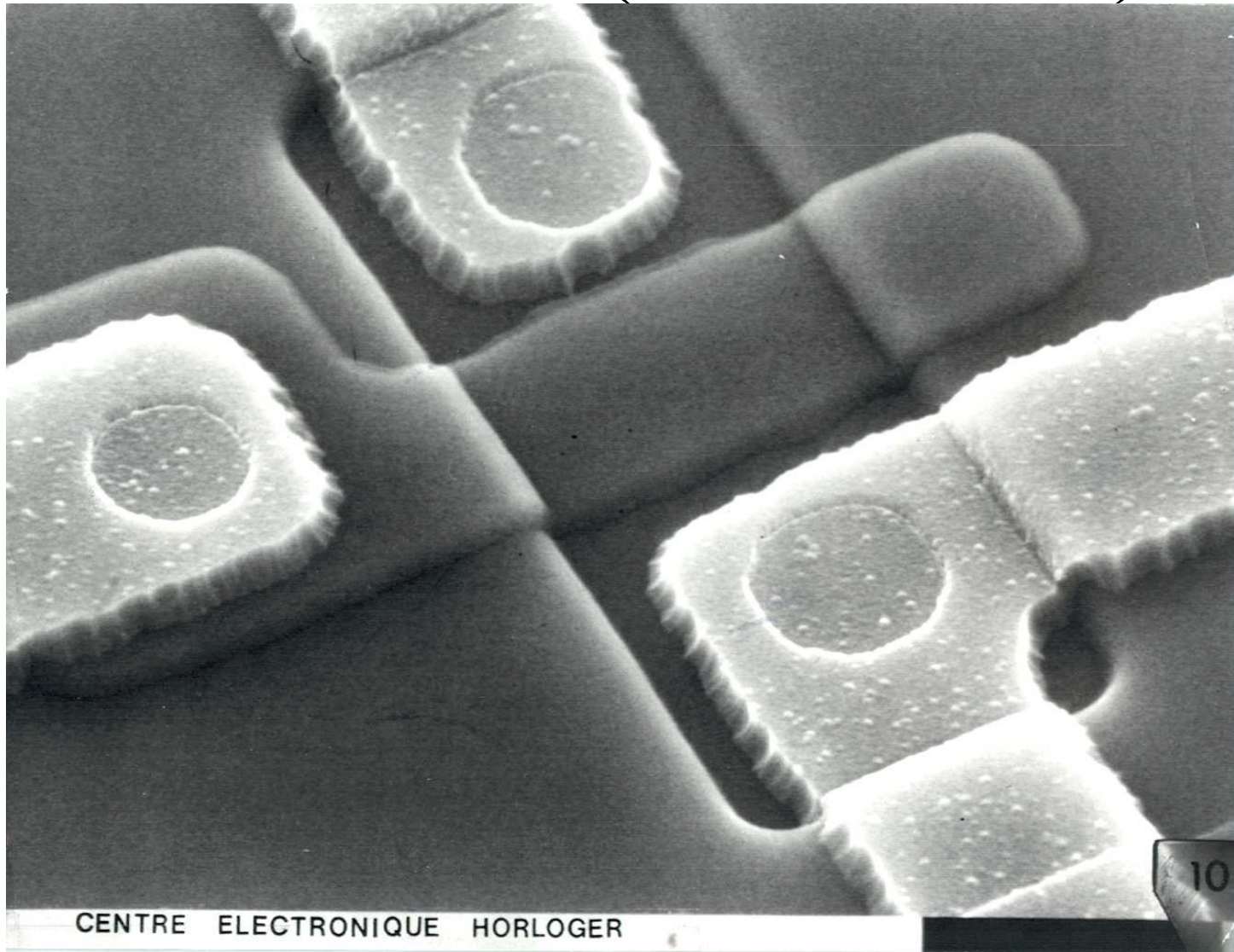


1971 Intel 4004

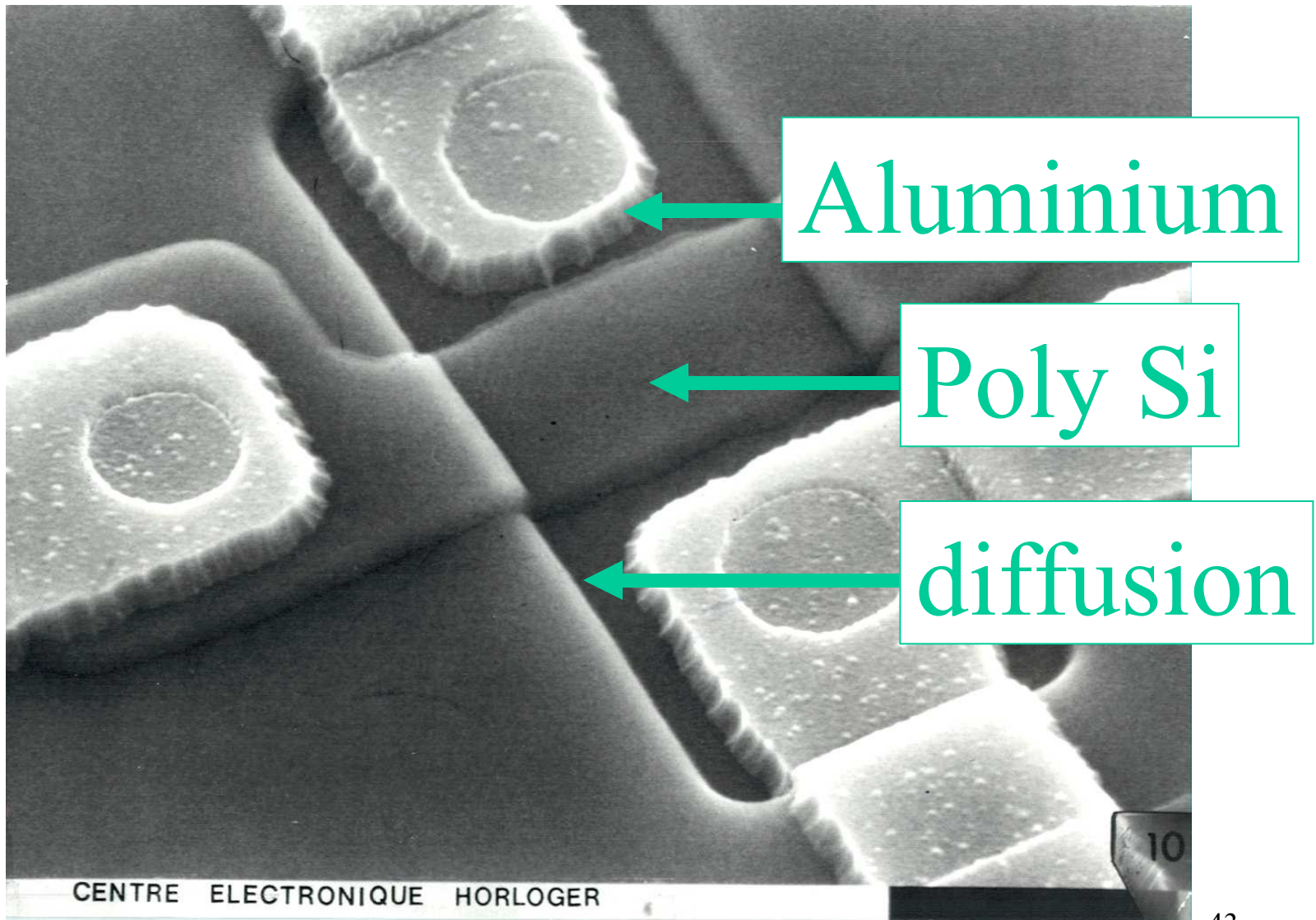




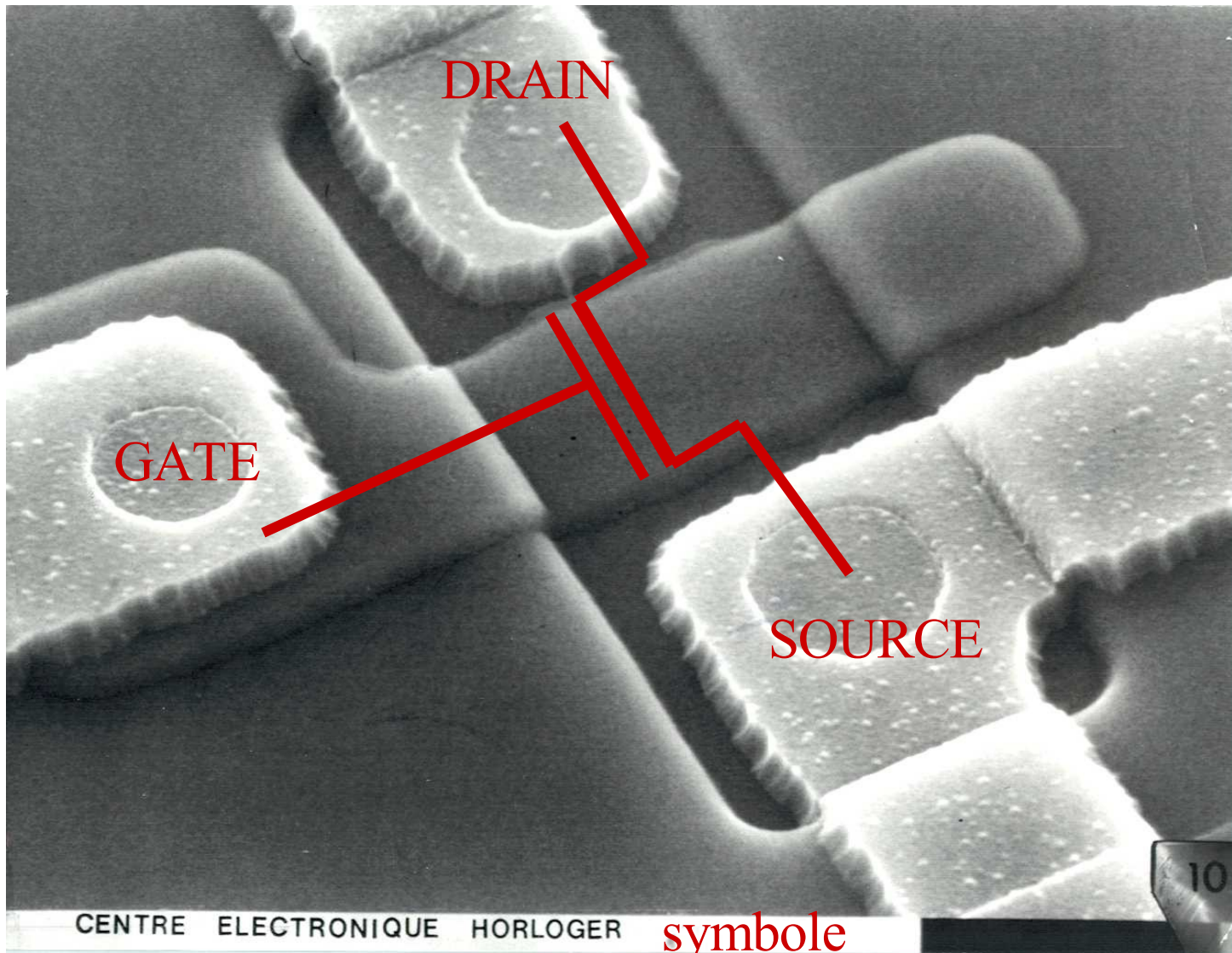
1972 CMOS (Switzerland)



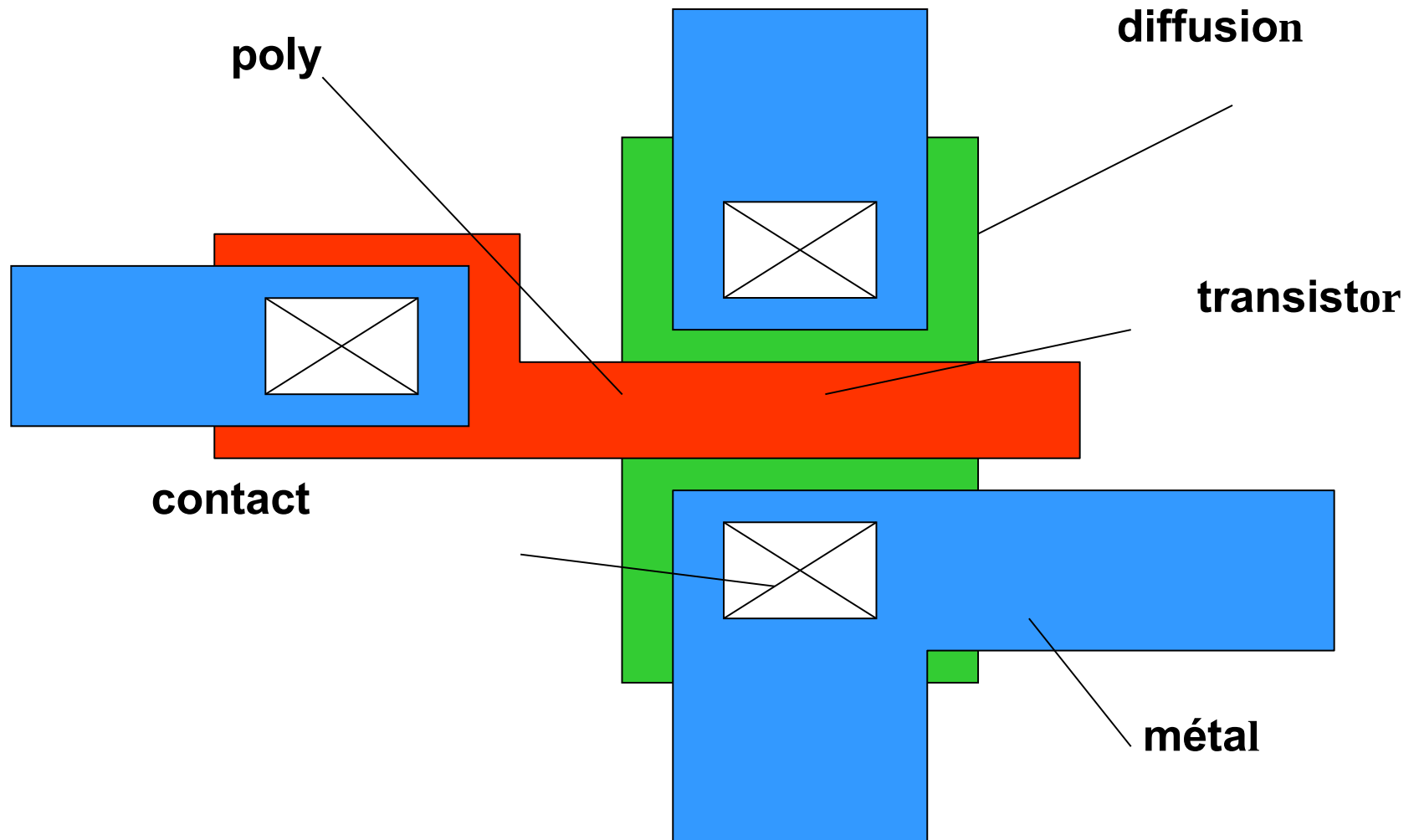
Transistor MOS

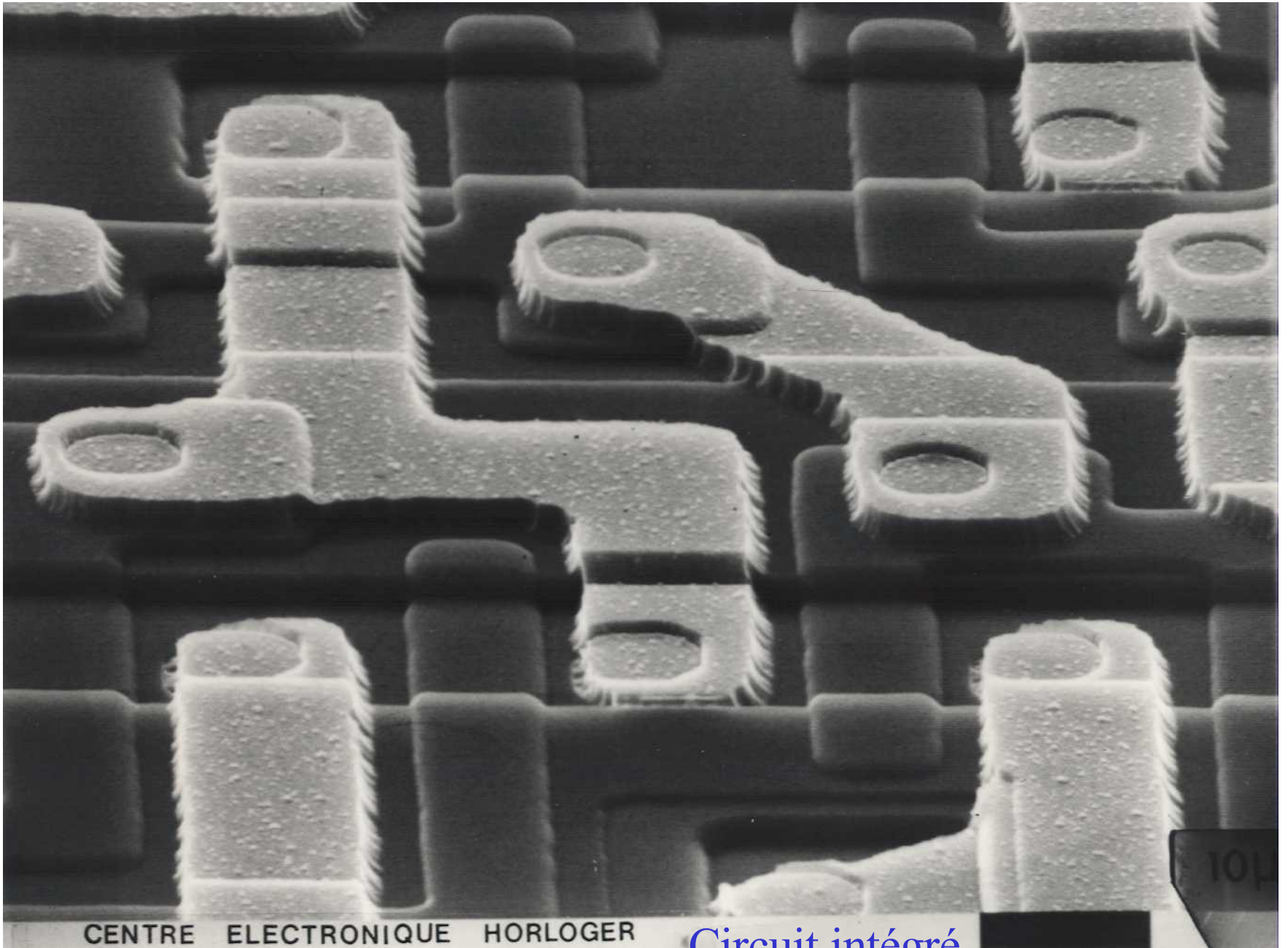


Transistor MOS



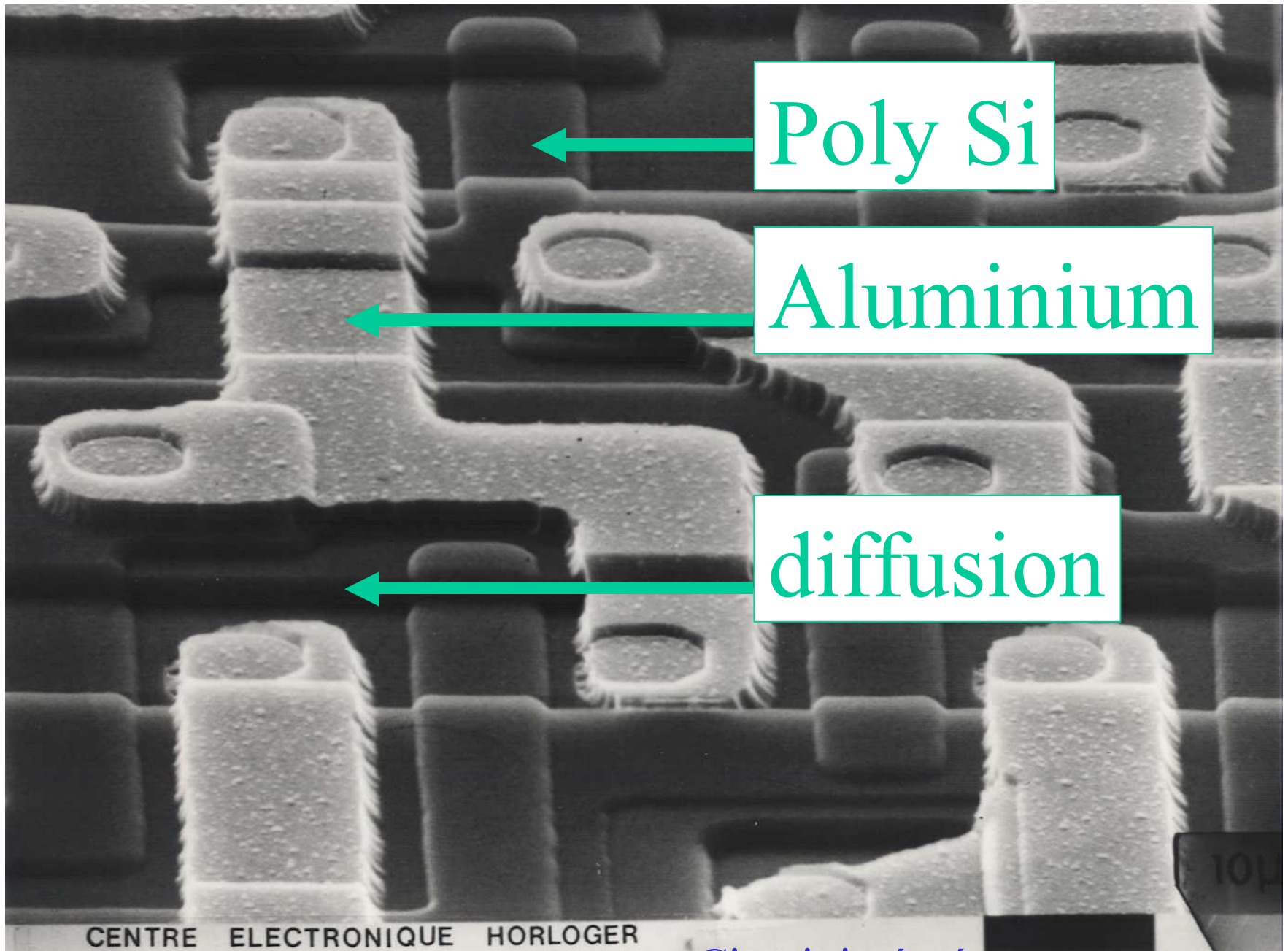
MOS, layout (masques)





CENTRE ELECTRONIQUE HORLOGER

Circuit intégré



Poly Si

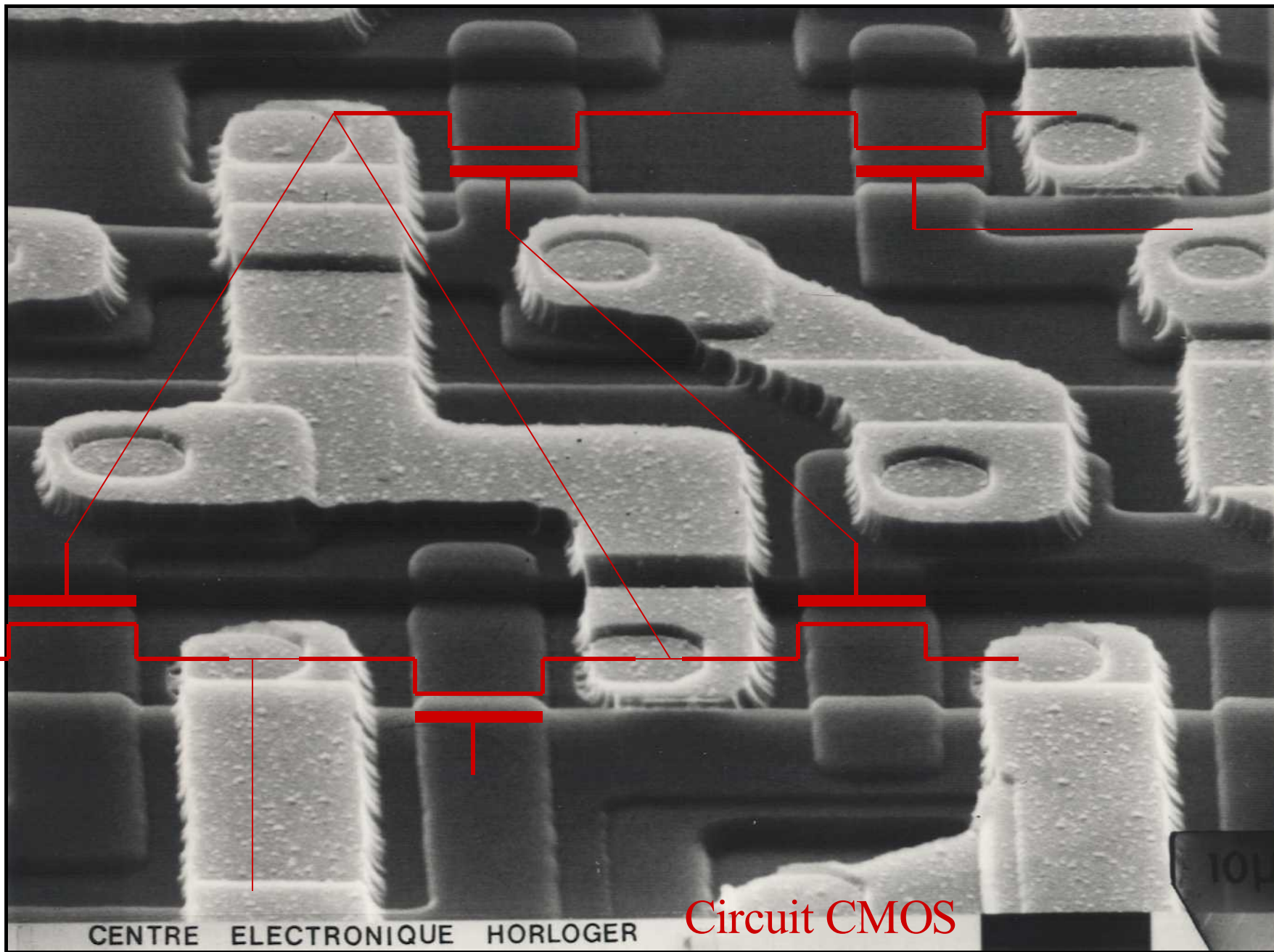
Aluminium

diffusion

CENTRE ELECTRONIQUE HORLOGER

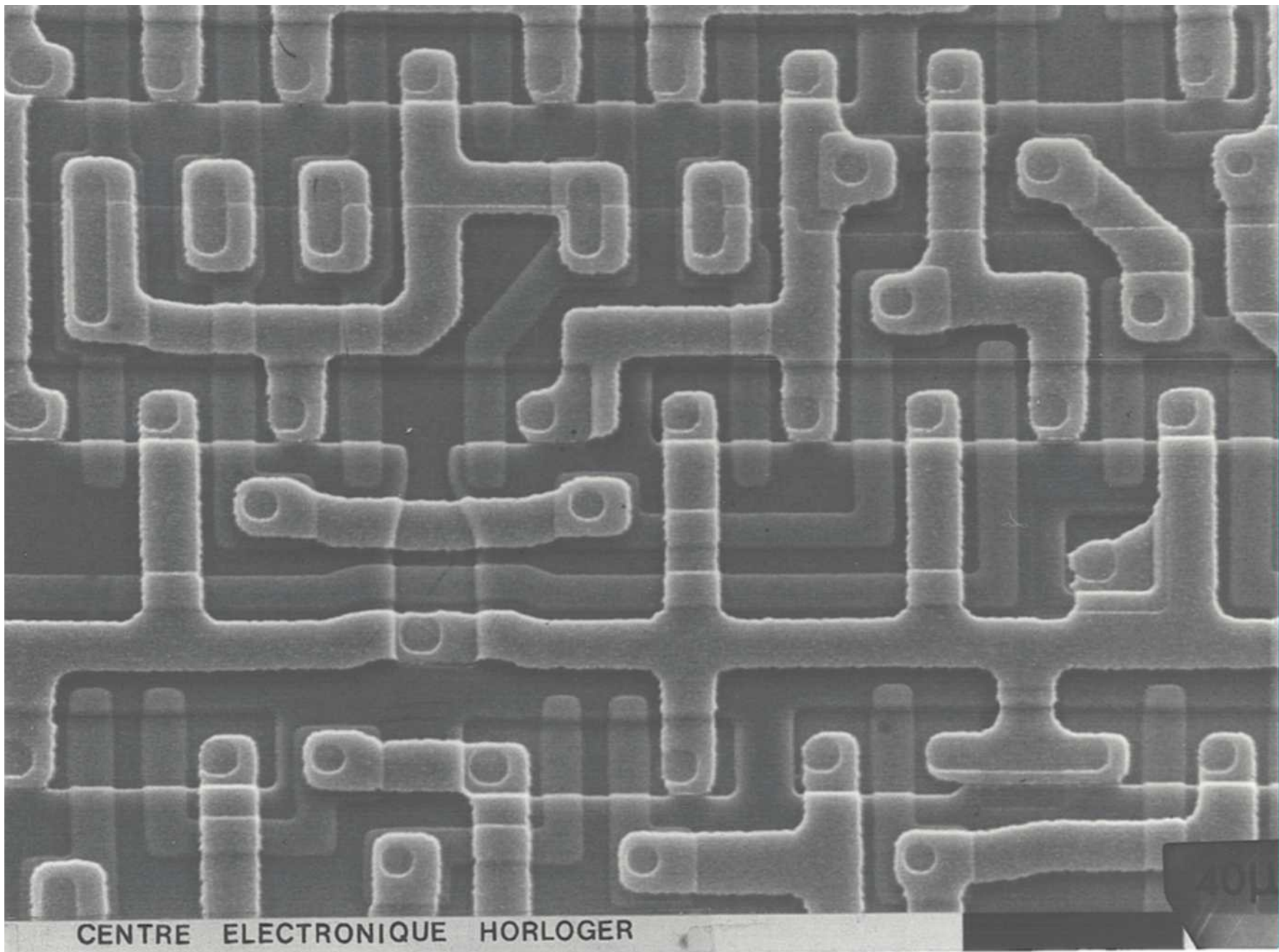
J.-C. MATHIEU

Circuit intégré



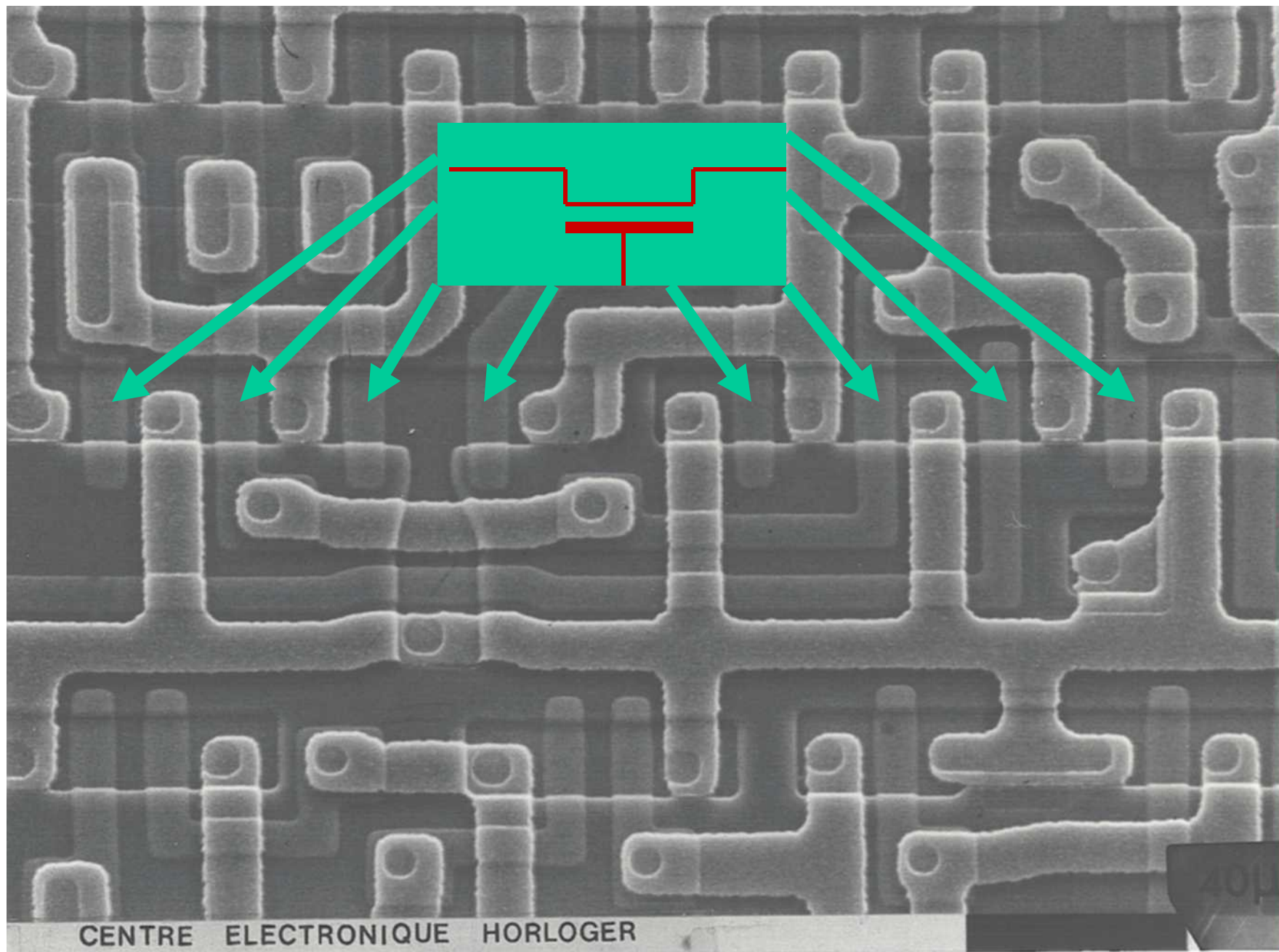
CENTRE ELECTRONIQUE HORLOGER

Circuit CMOS



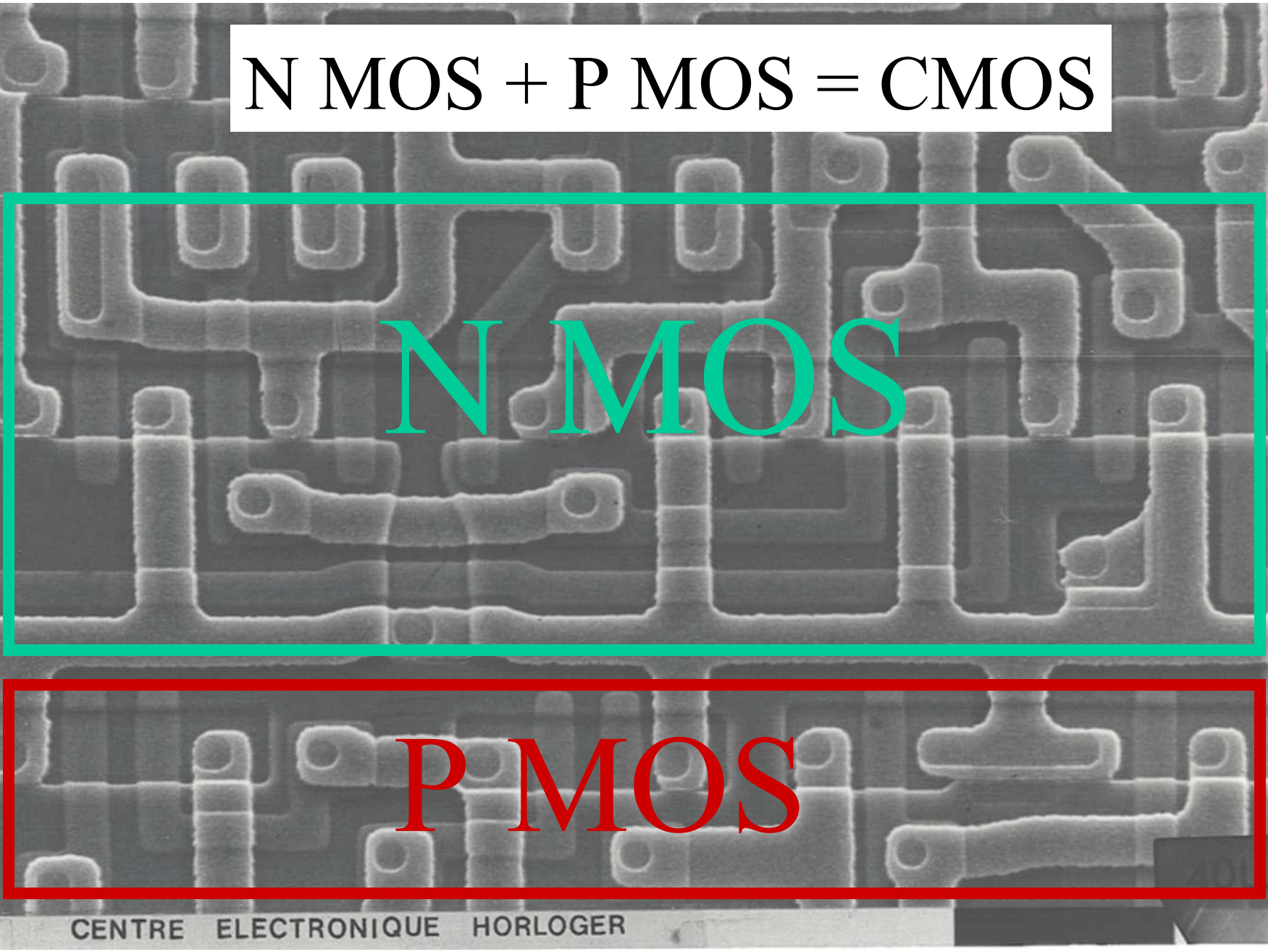
CENTRE ELECTRONIQUE HORLOGER

40µm



CENTRE ELECTRONIQUE HORLOGER

40µm

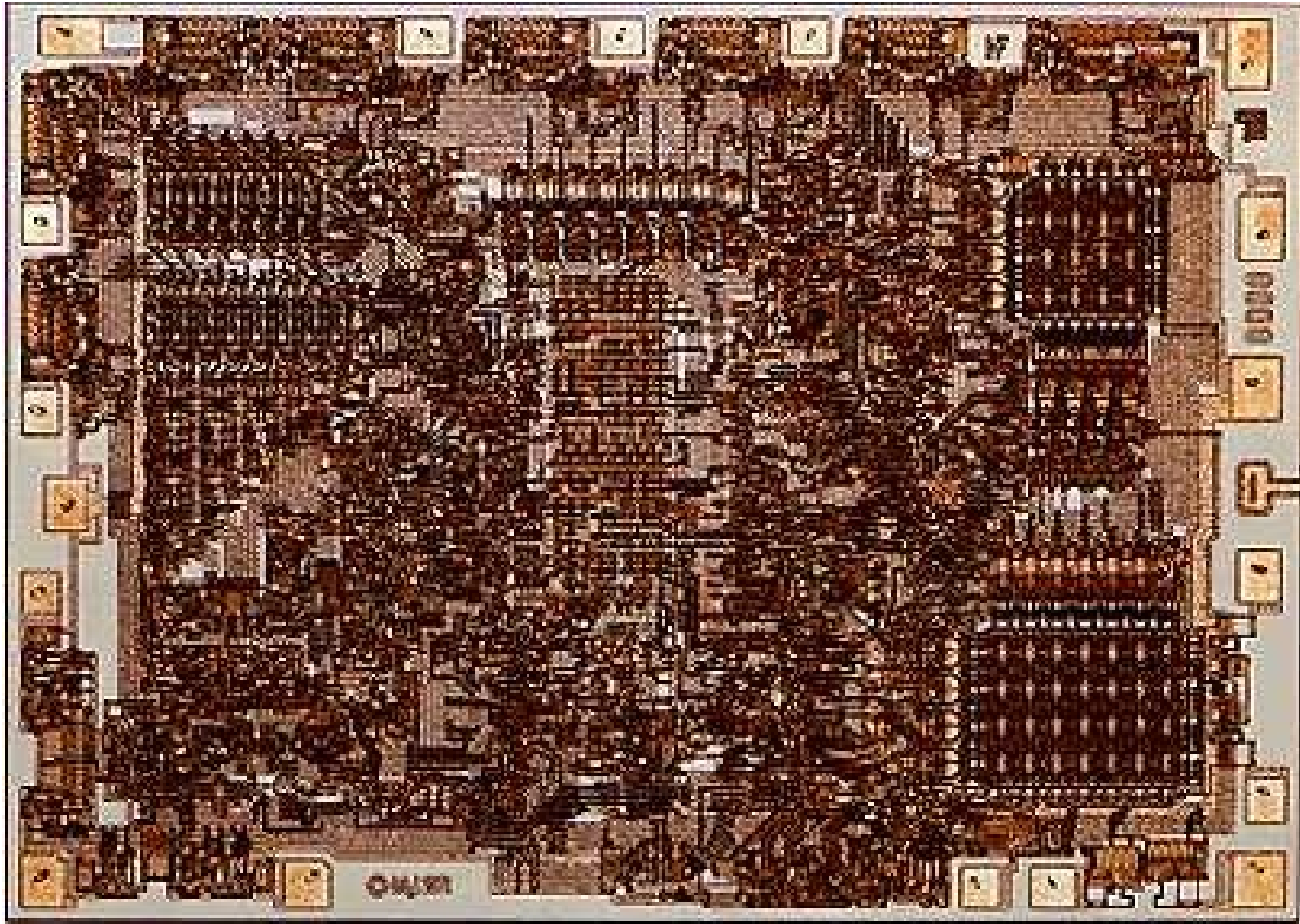
A scanning electron micrograph (SEM) of a CMOS integrated circuit. The image shows a complex network of metal interconnects, gates, and transistors. The background is a dark, textured surface, likely the silicon substrate. The metal lines are bright and form a dense, interconnected pattern. The text "N MOS + P MOS = CMOS" is overlaid at the top, and "NMOS" and "PMOS" are highlighted in green and red boxes respectively. At the bottom, the text "CENTRE ELECTRONIQUE HORLOGER" is visible.

$\text{N MOS} + \text{P MOS} = \text{CMOS}$

NMOS

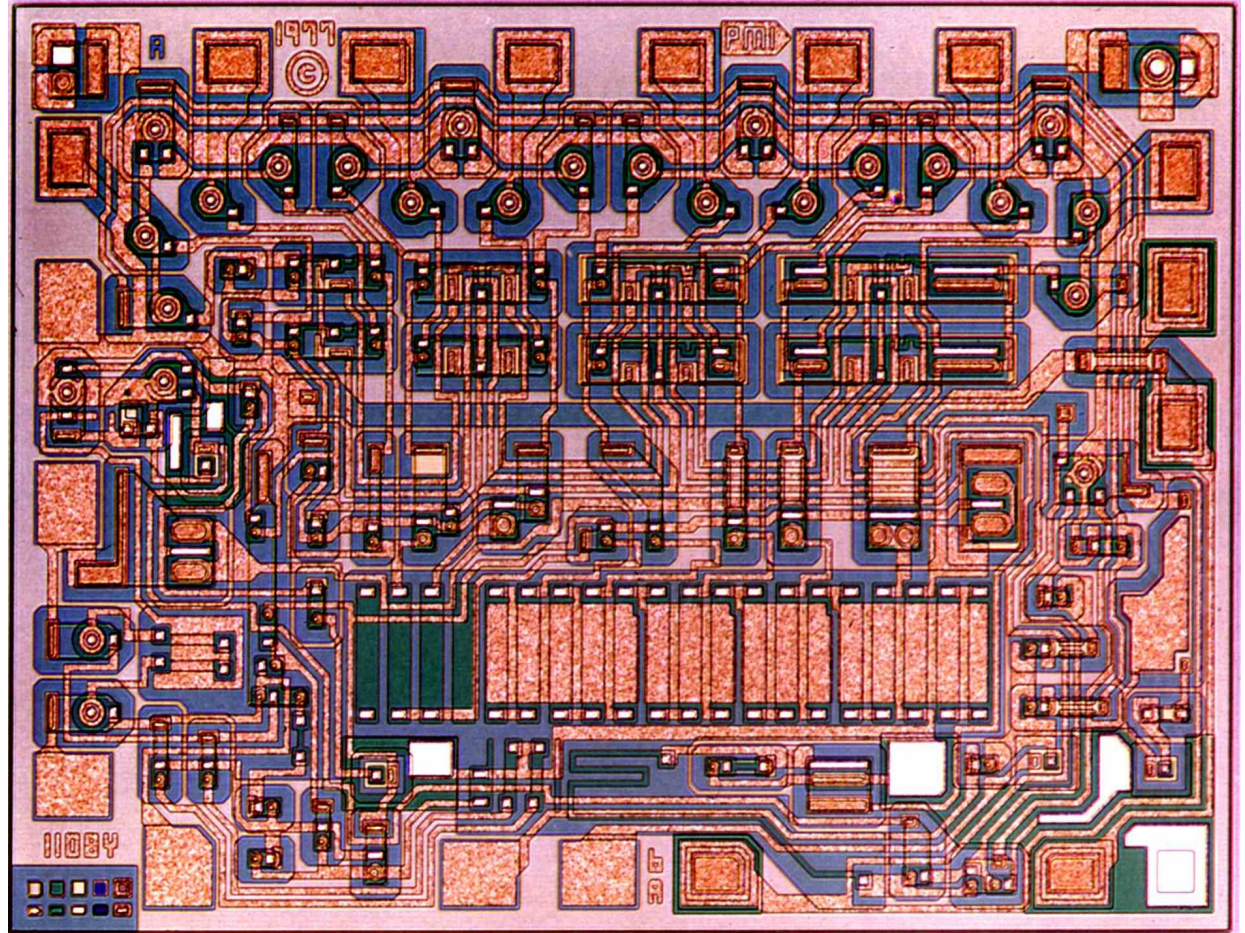
PMOS

1972 INTEL8008

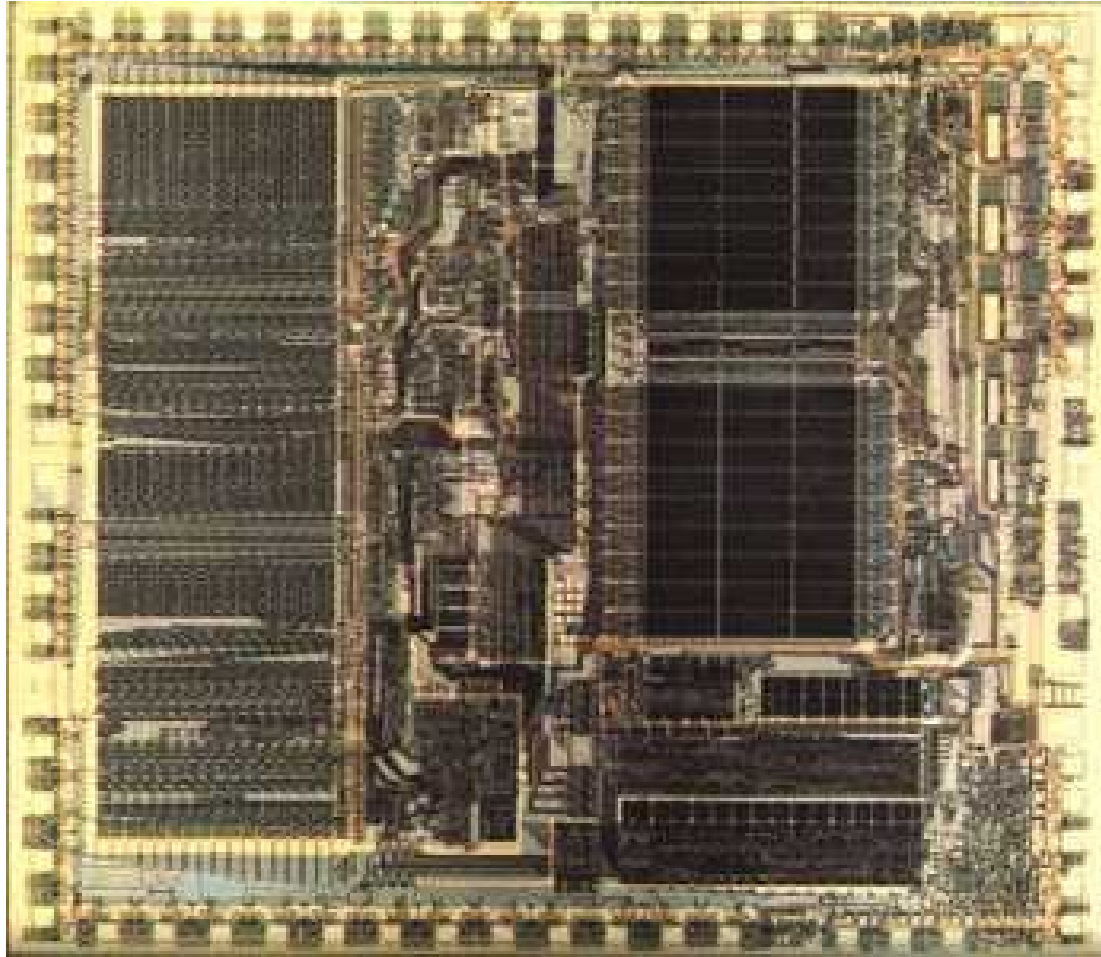


Convertisseur D/A

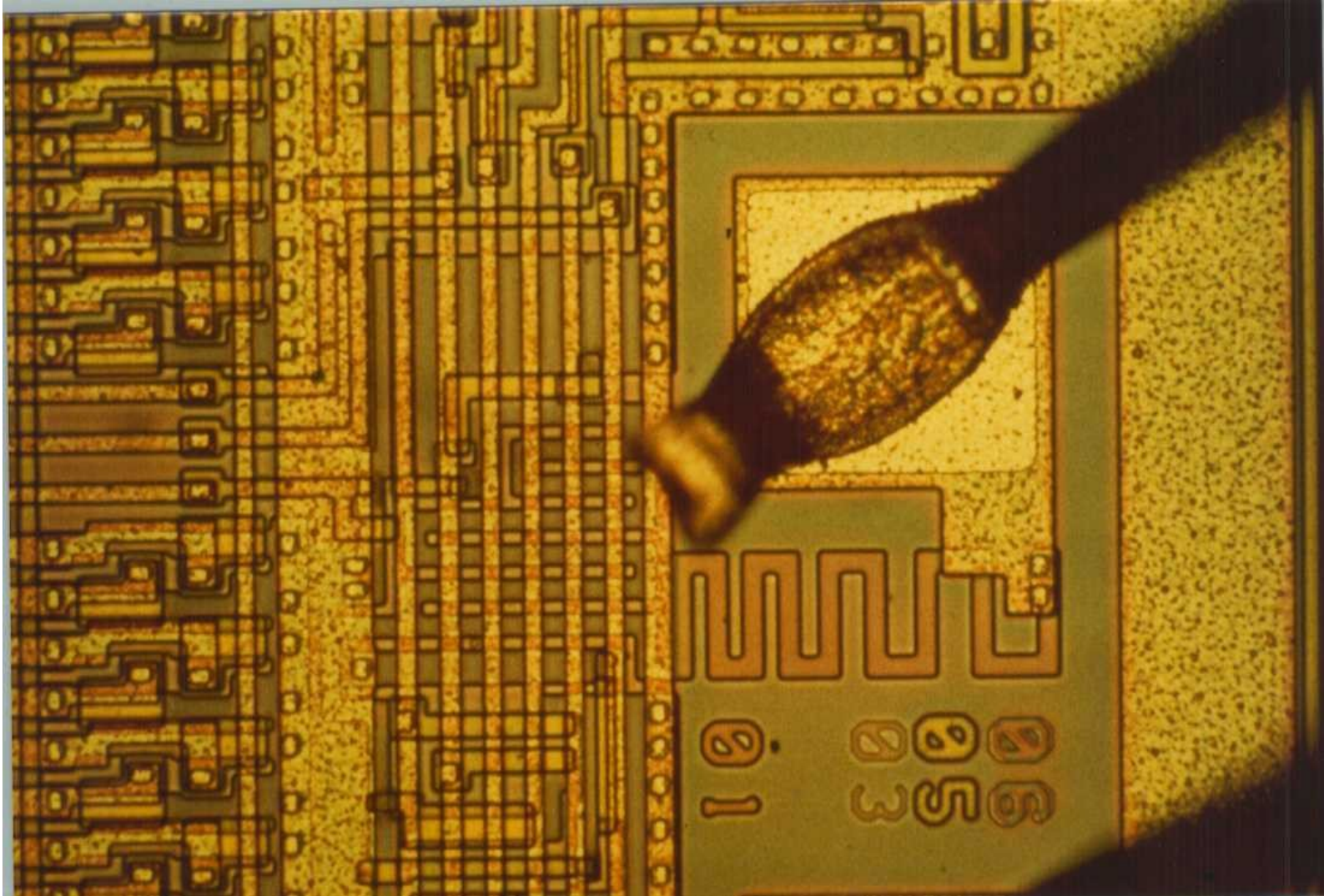
- DAC-08 de PMI
- 1974-77
- 1.55 x 2.15 mm,
- 100 Transistors
- 40 R
- 8 Bit, 5 MHz



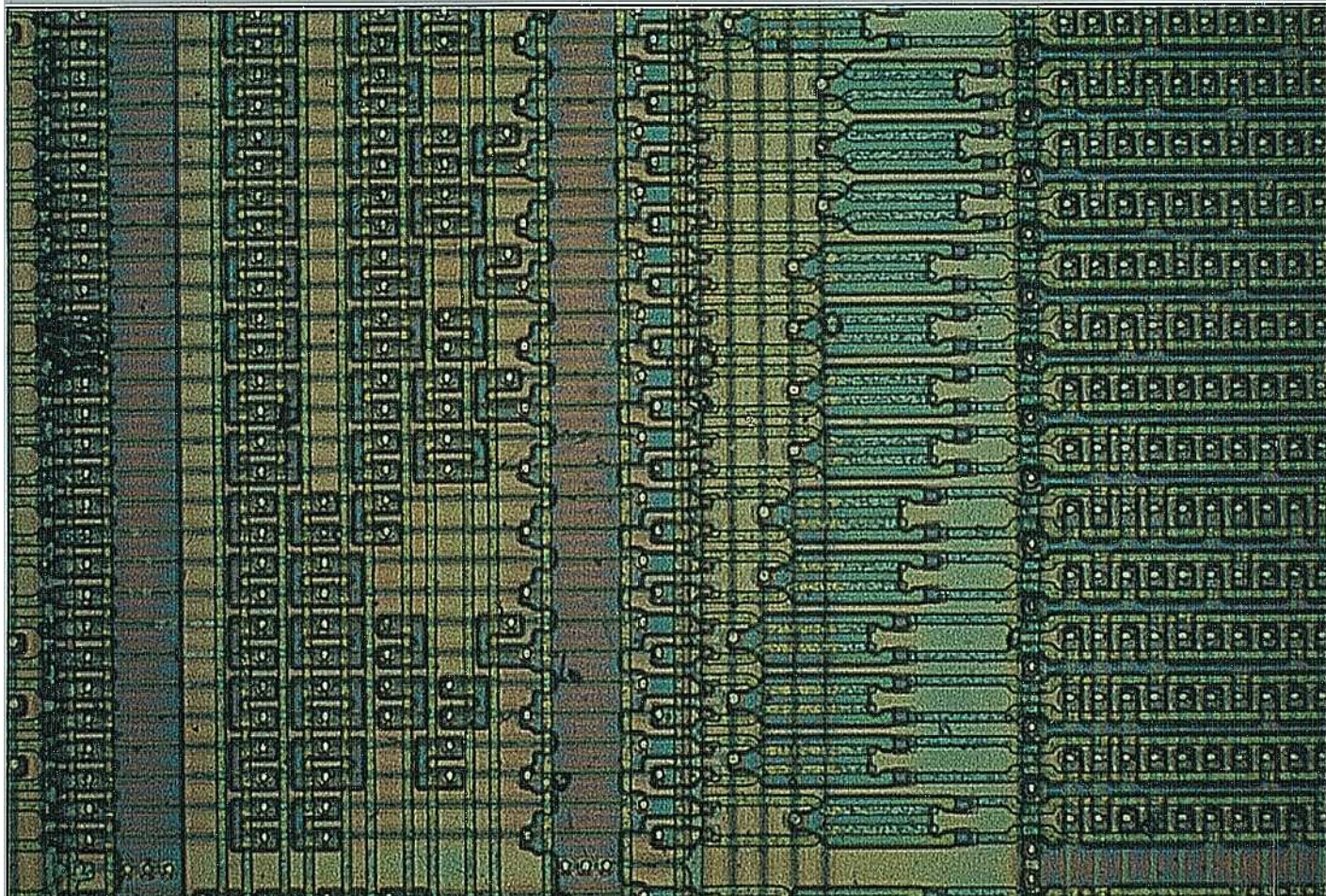
1979 M68000



M68000, detail of pad

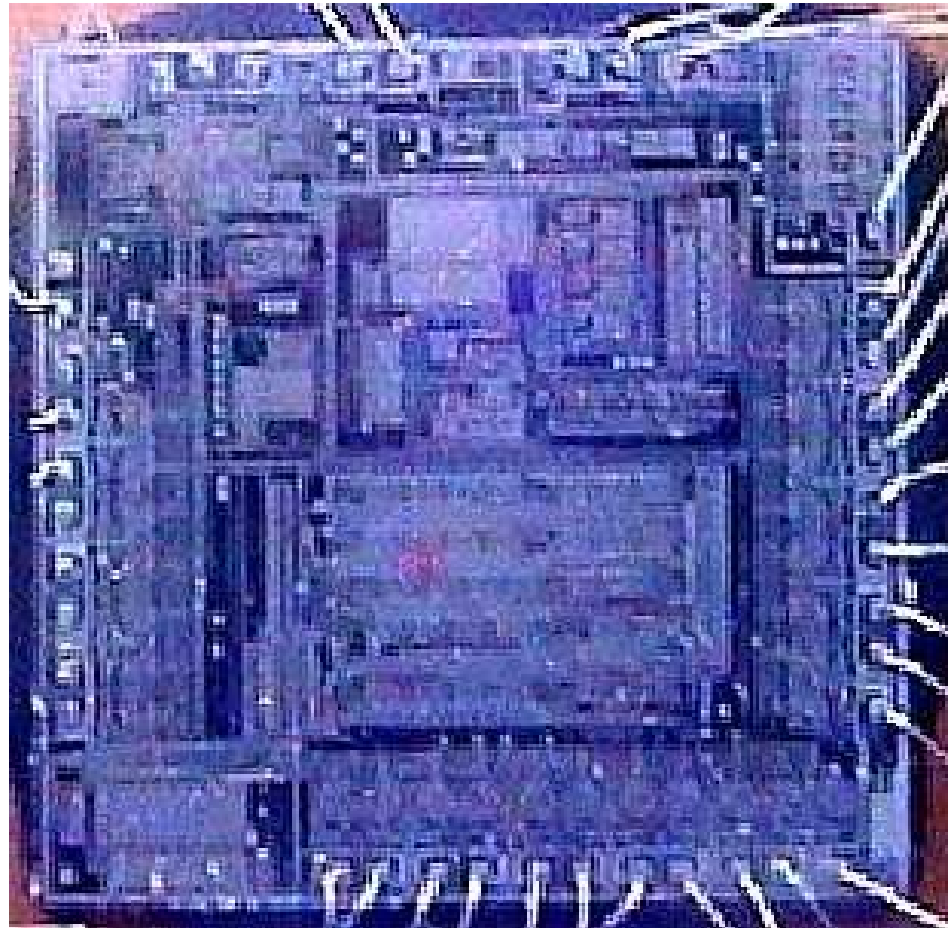


M68000, detail of ROM

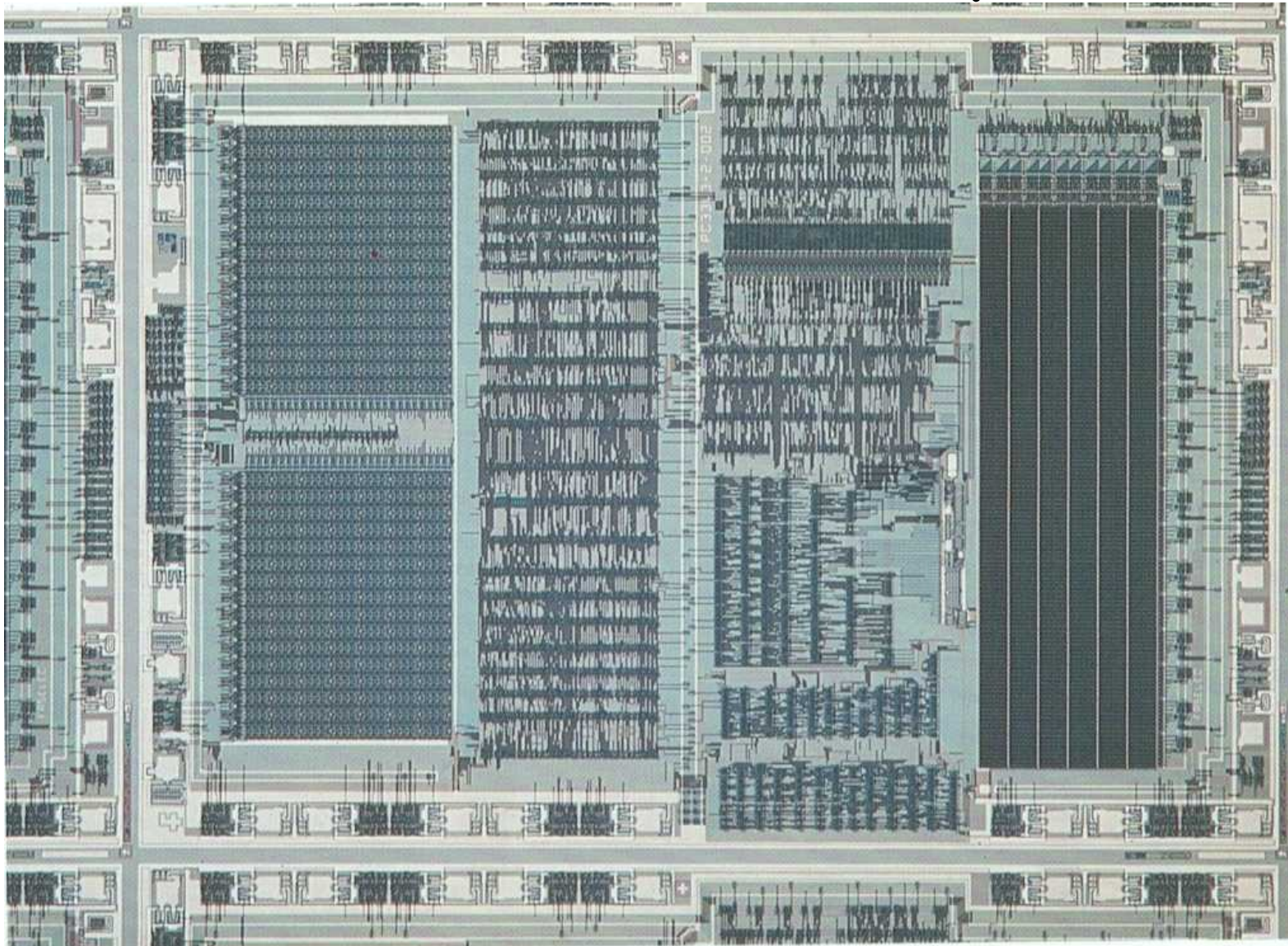


HCMOS 3 μ m (EM 1985)

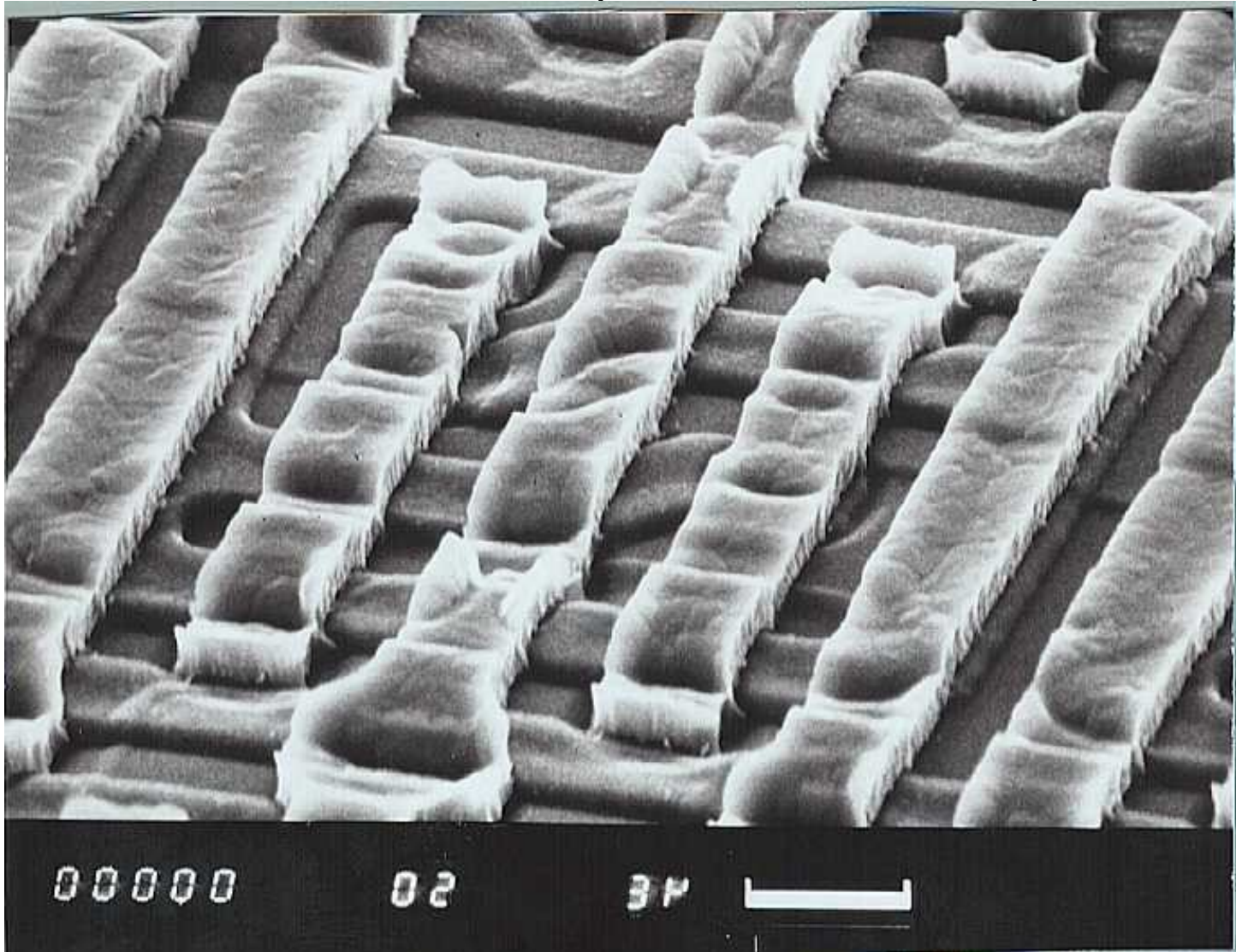
- Car clock



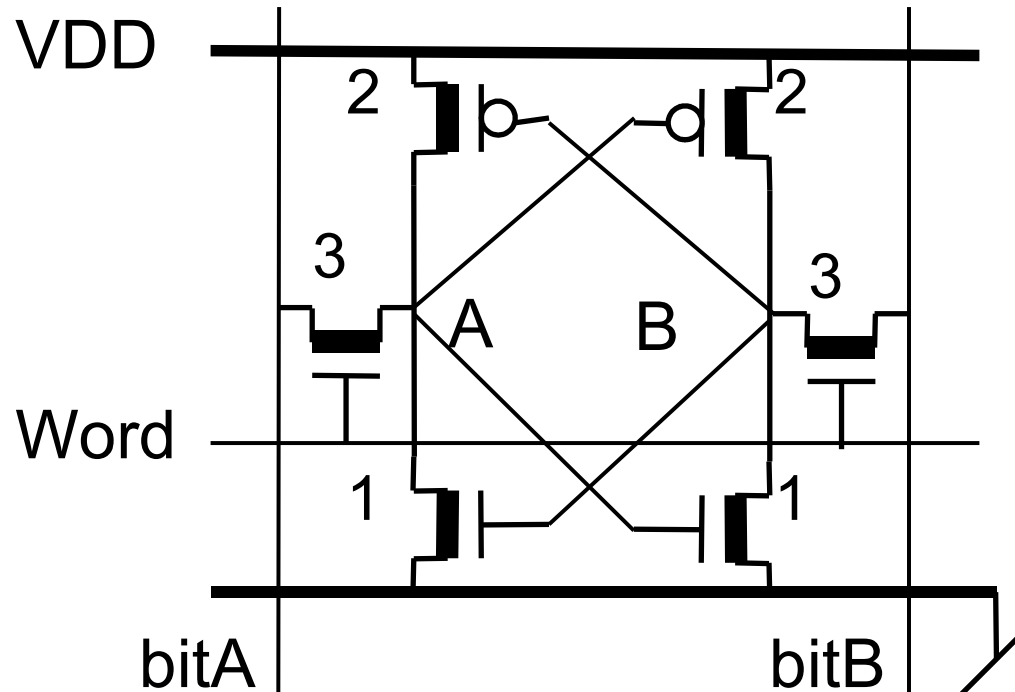
1987 SACMOS 3 μ m



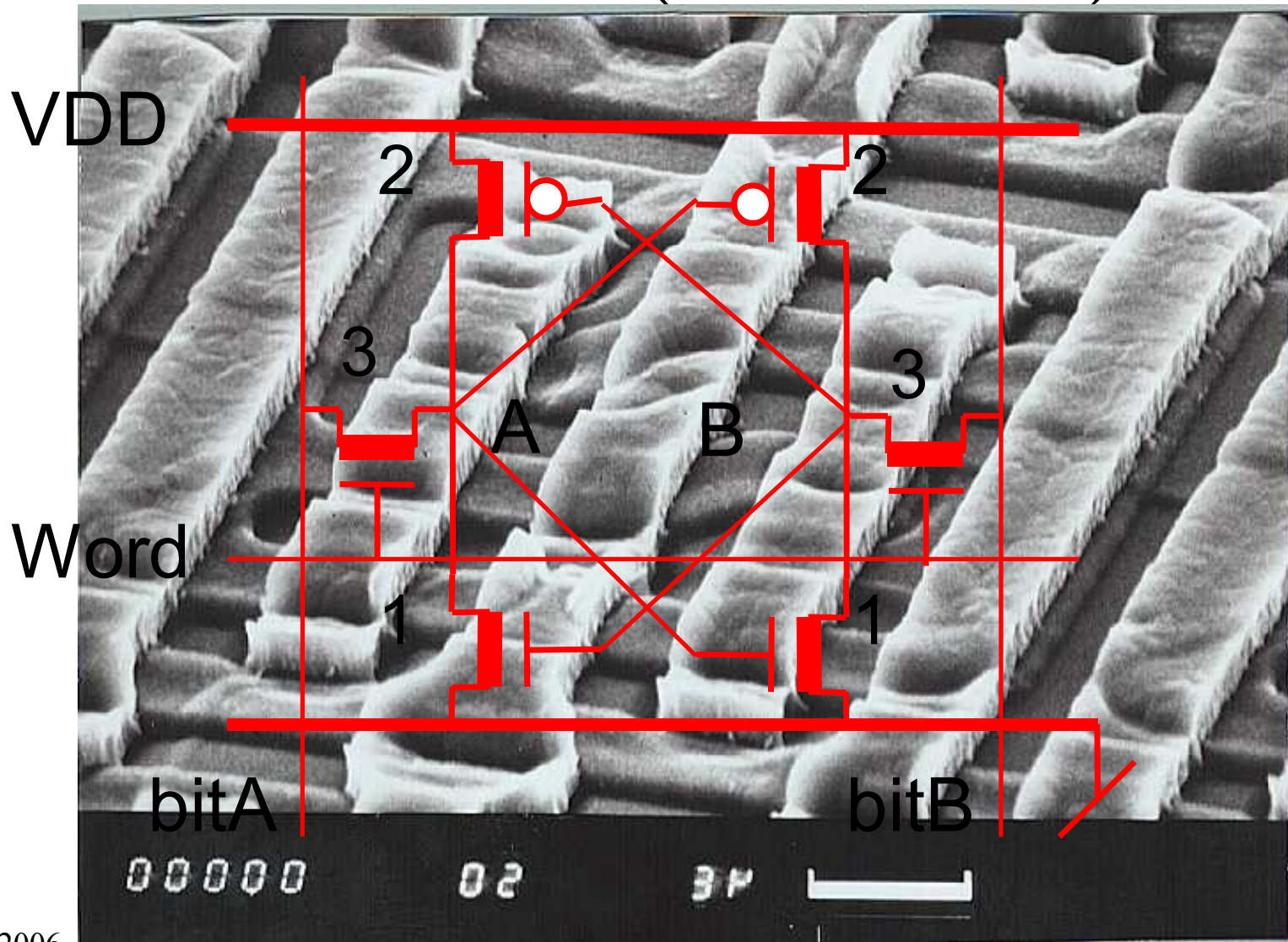
RAM cell (SACMOS)



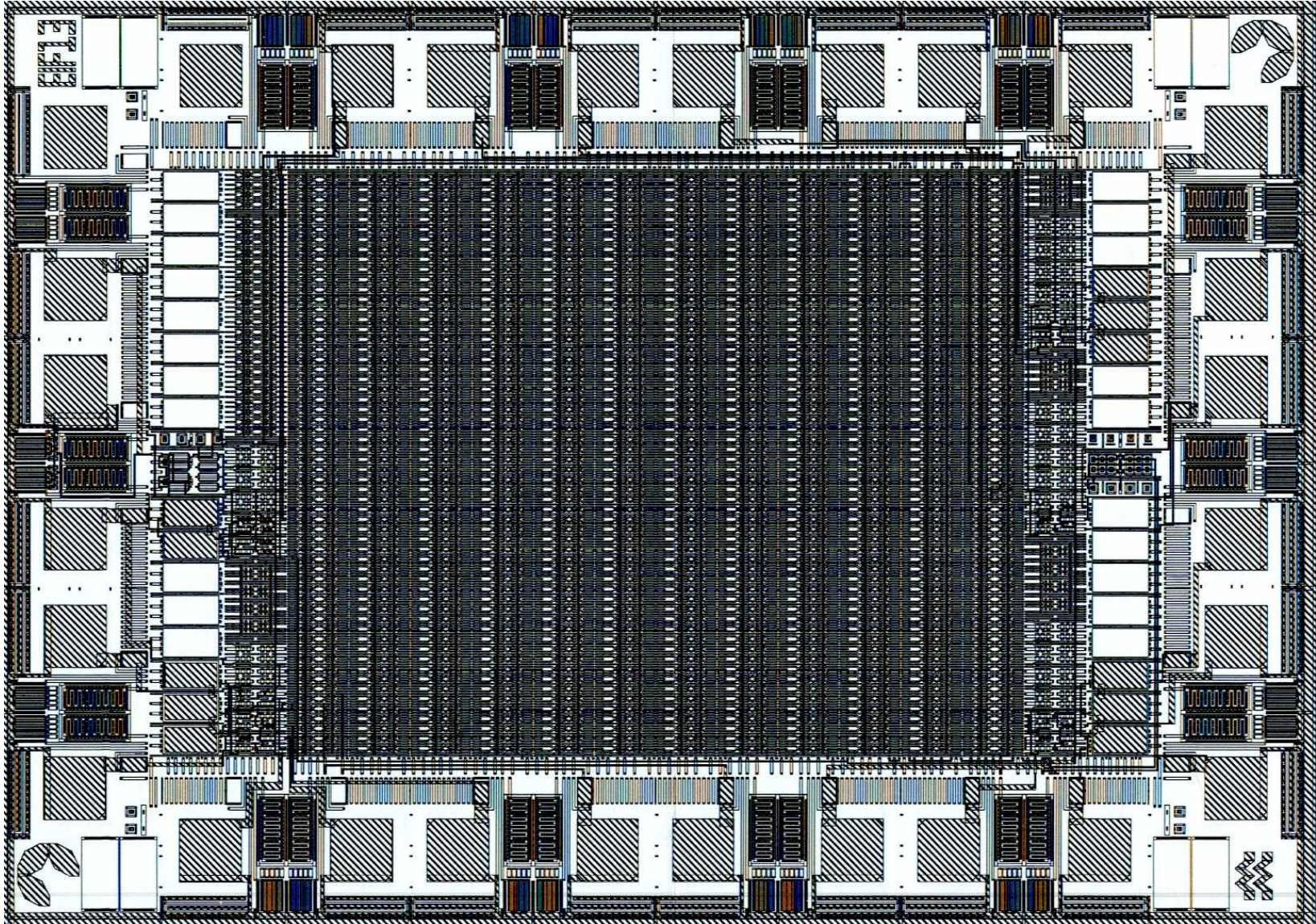
RAM statique (6 MOS)



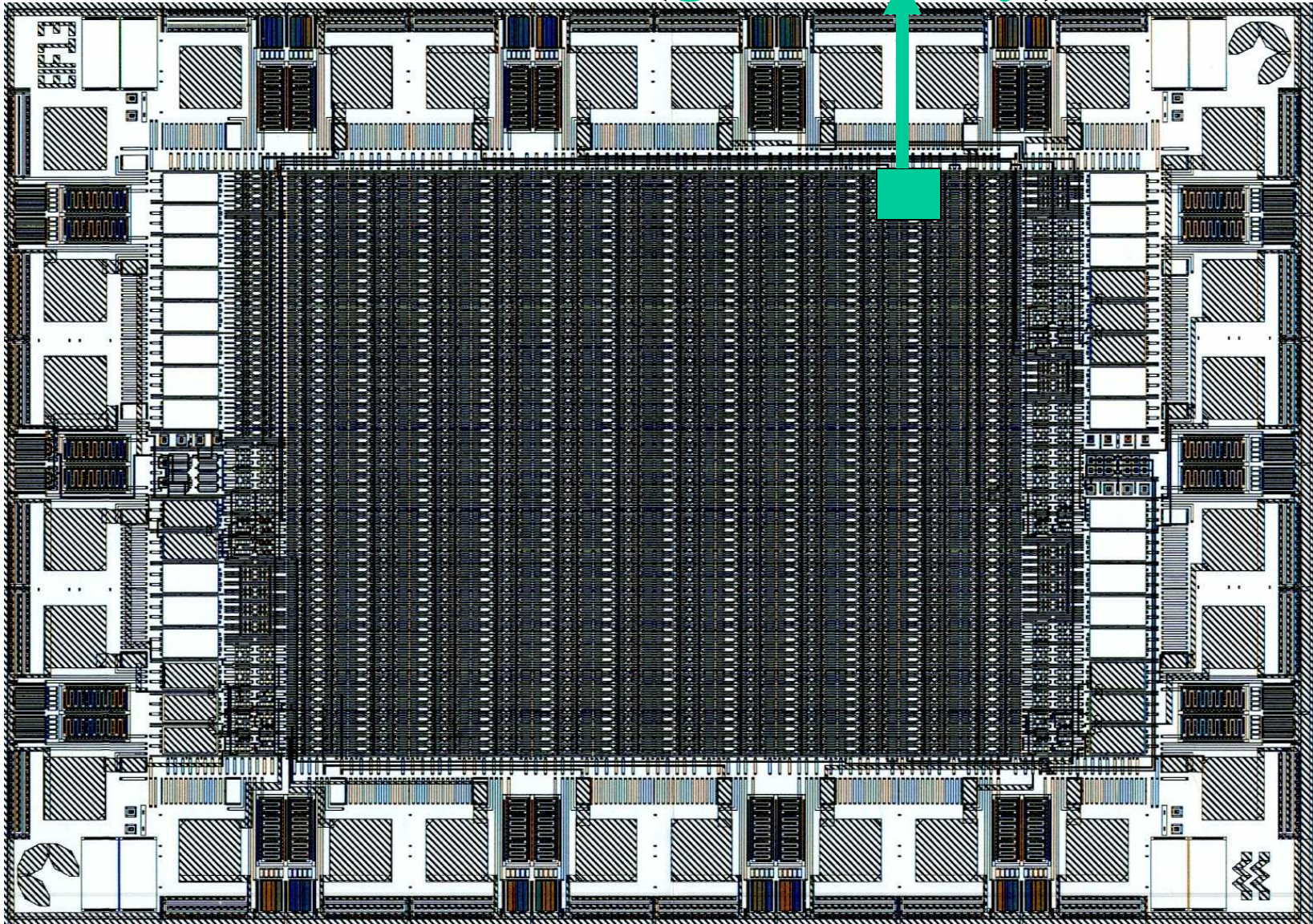
RAM cell (SACMOS)



MD100 (Faselec SAC 2 μ m)

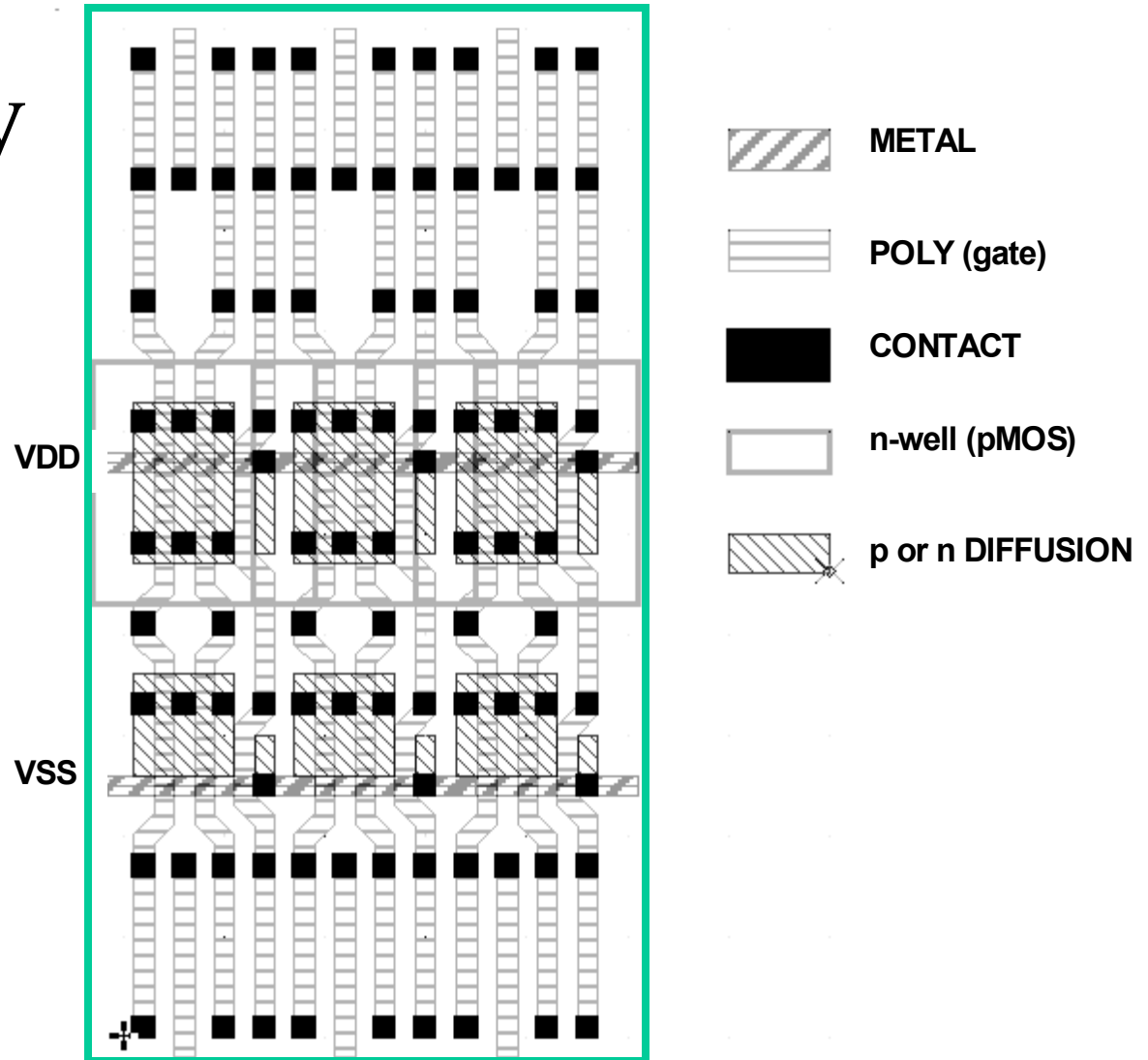


MD100 (gate array)



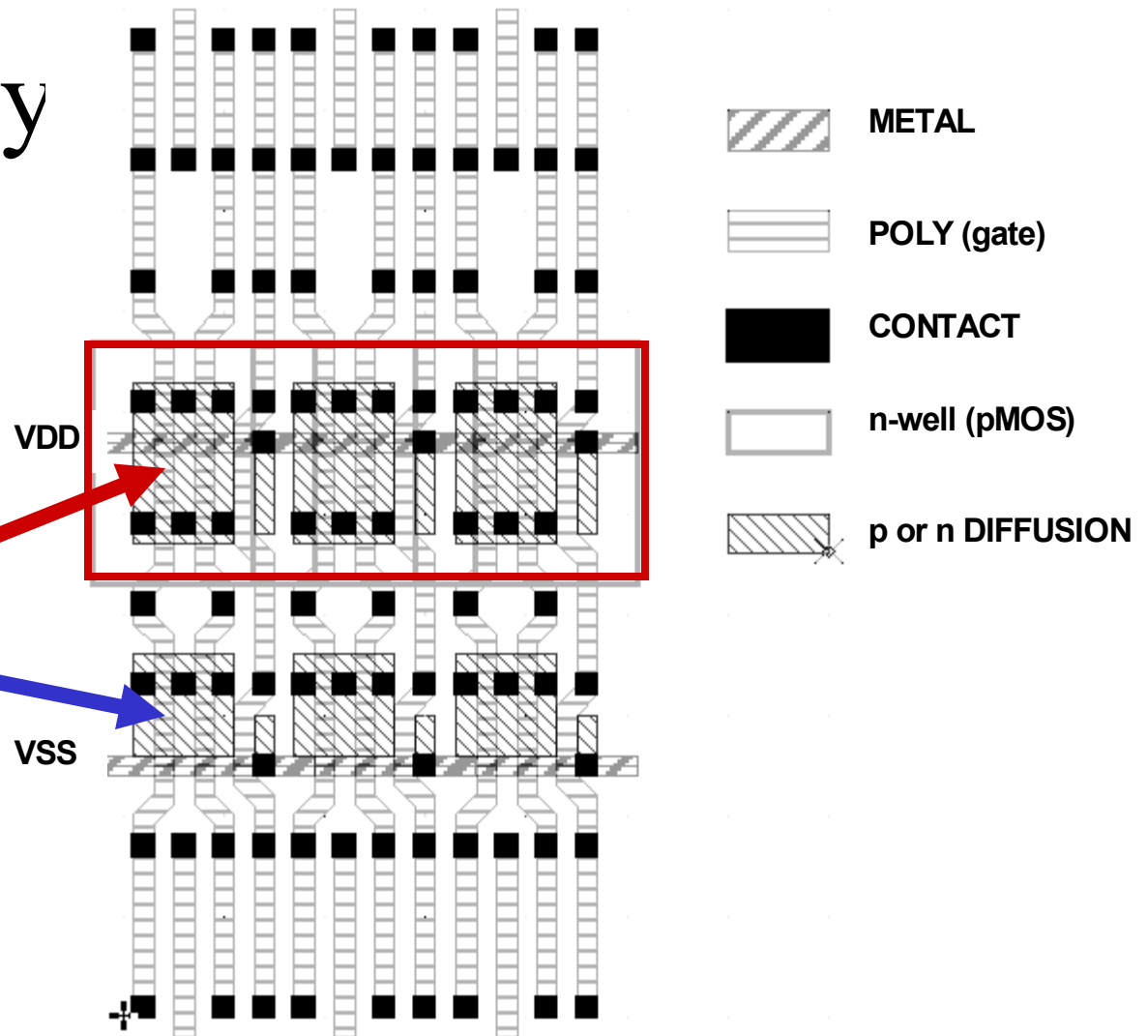
Gate Array

- MD100 cell
- programmation
- Masque métal

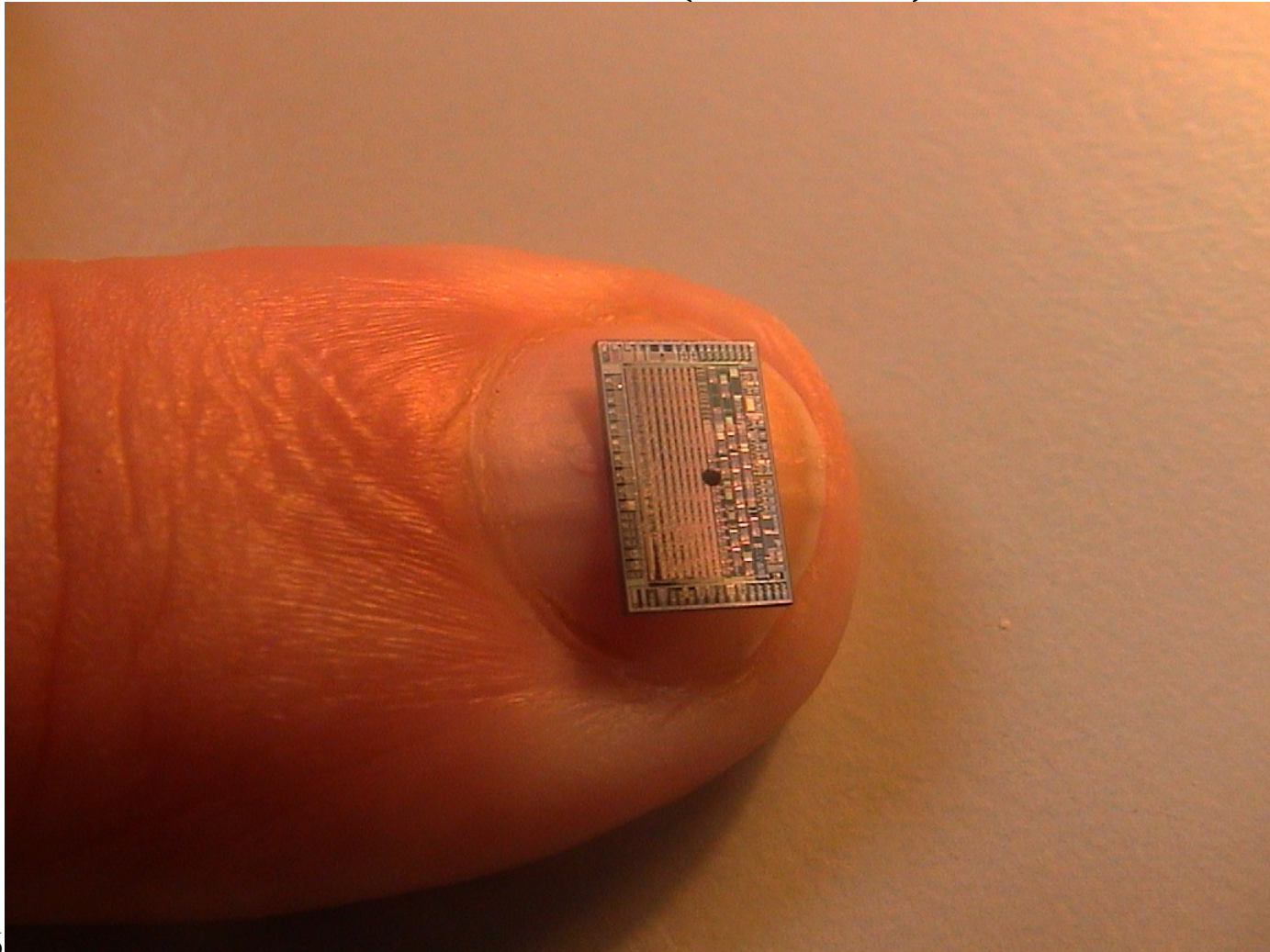


Gate Array

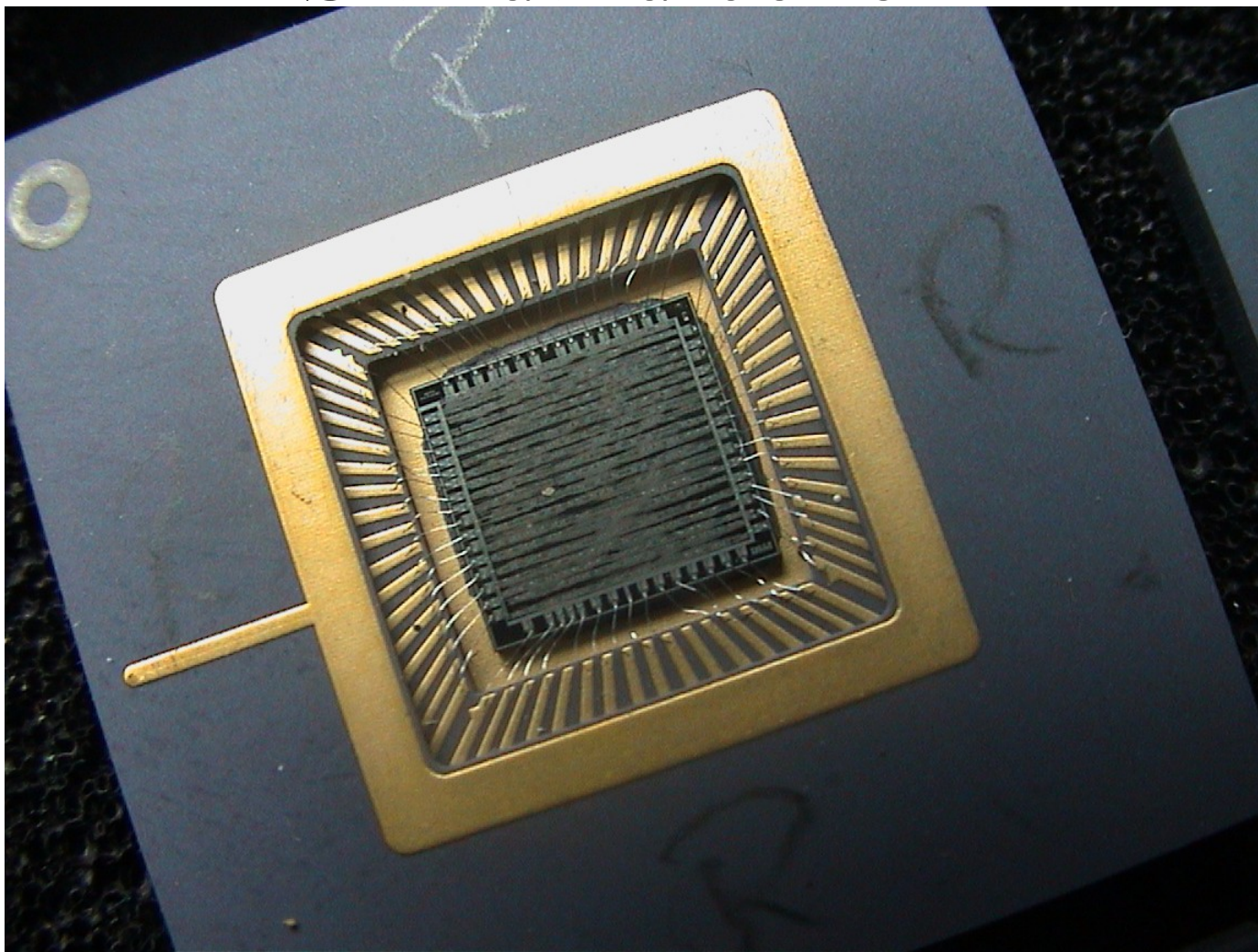
- MD100
- Metal
- 6 pMOS
- 6 nMOS



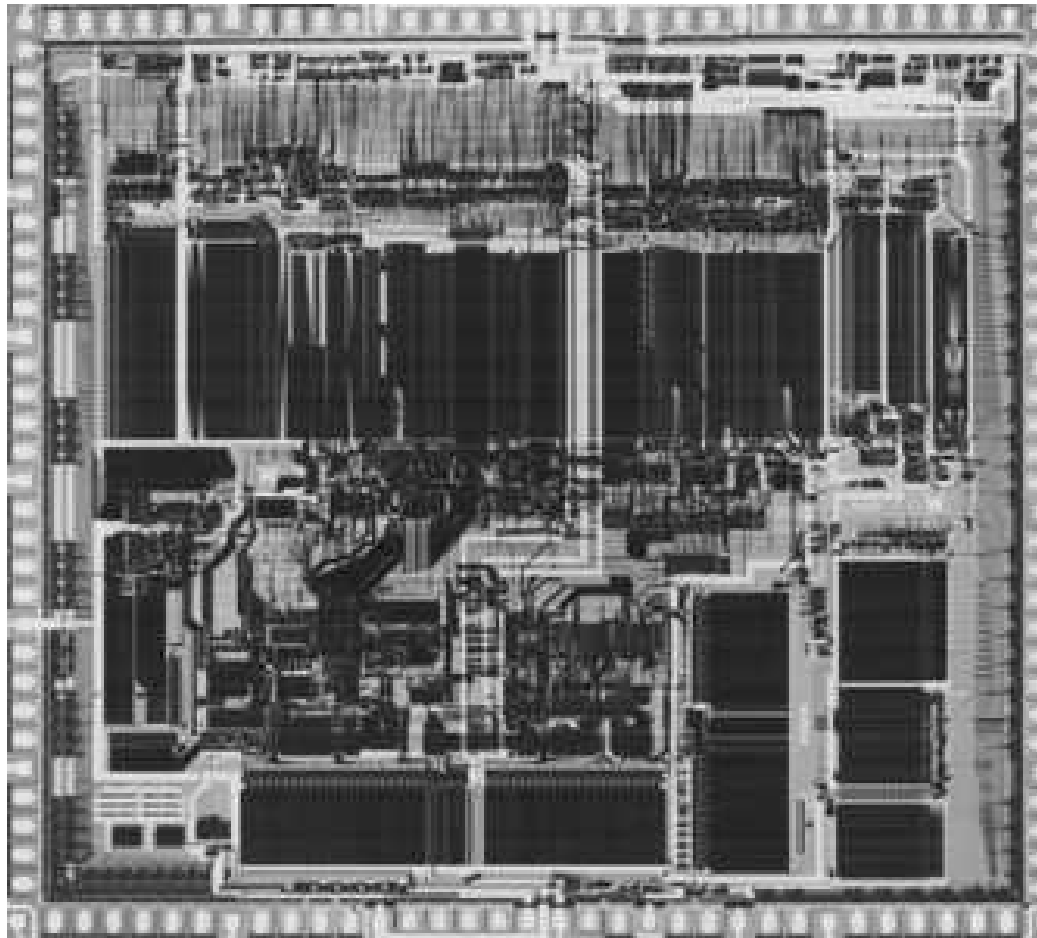
ASIC (1987)



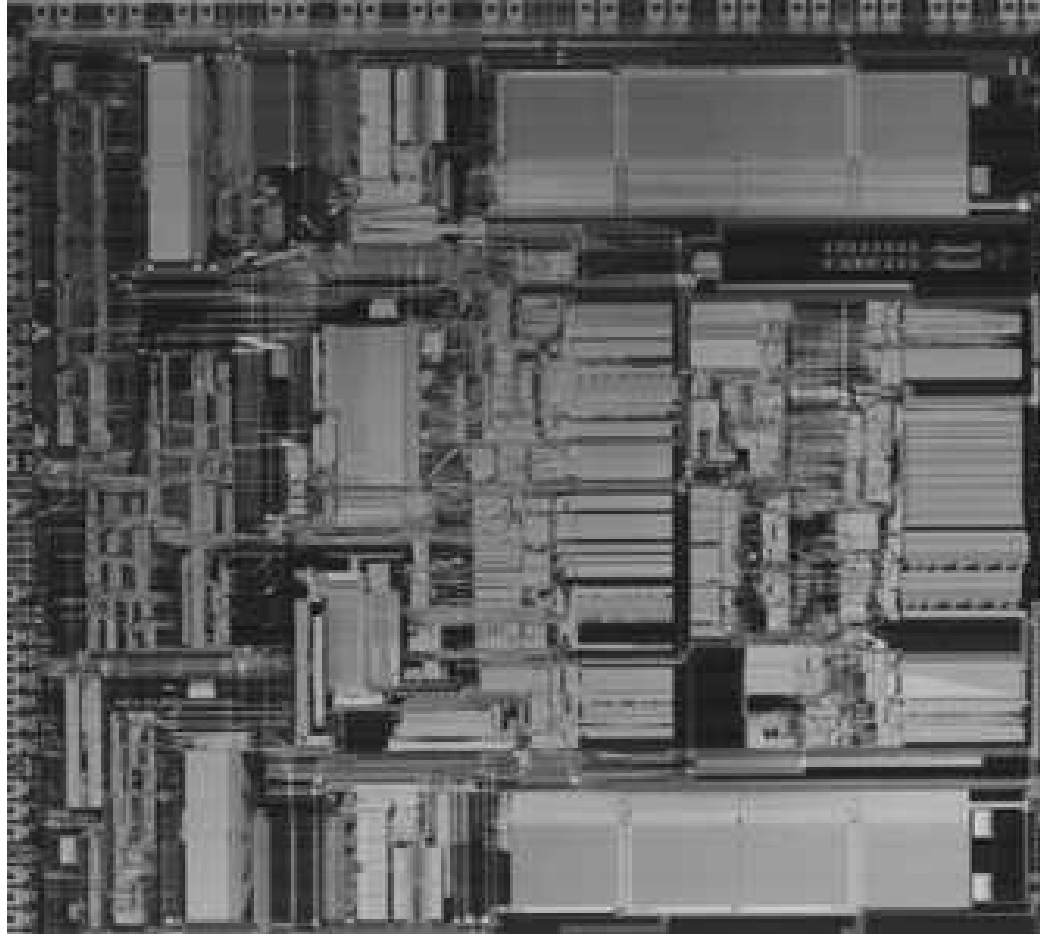
Standard cells



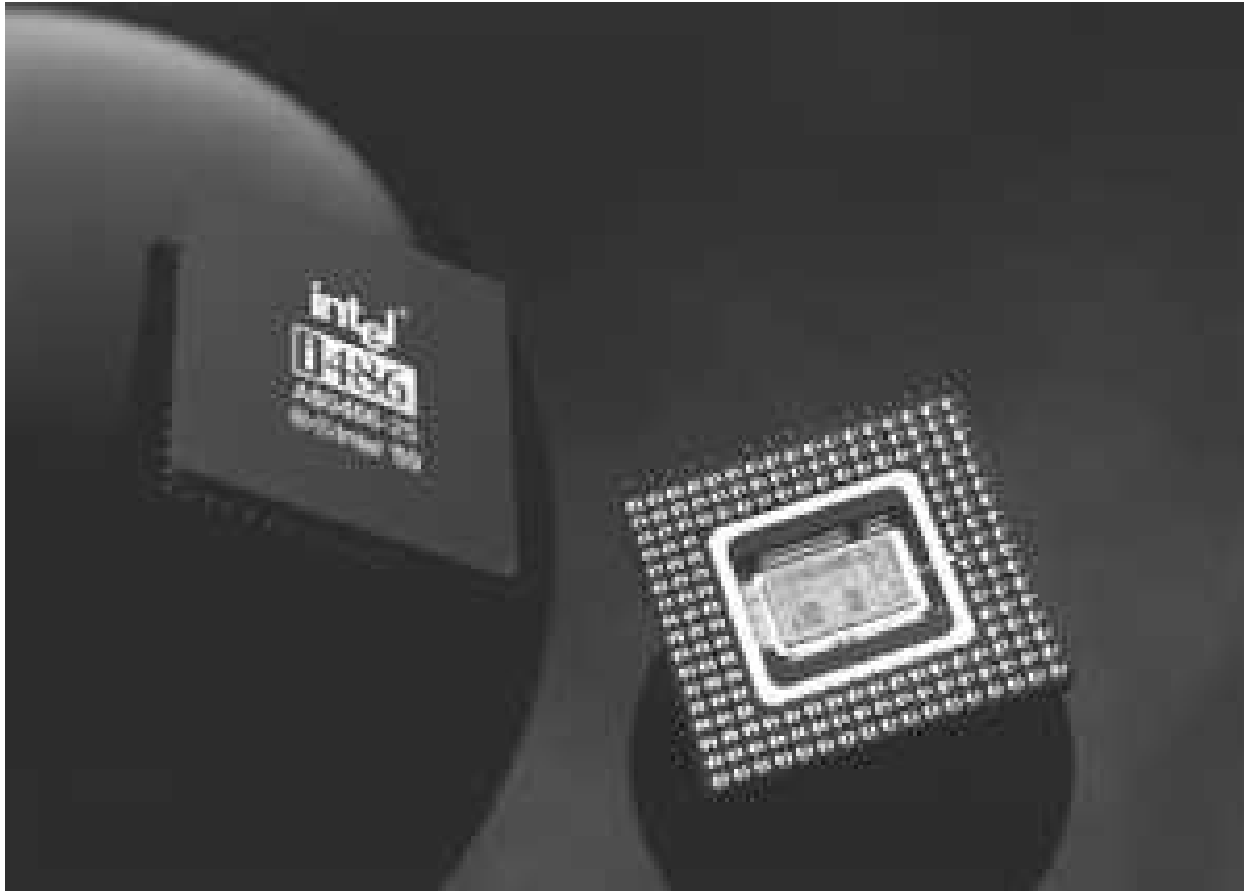
1987 M68030



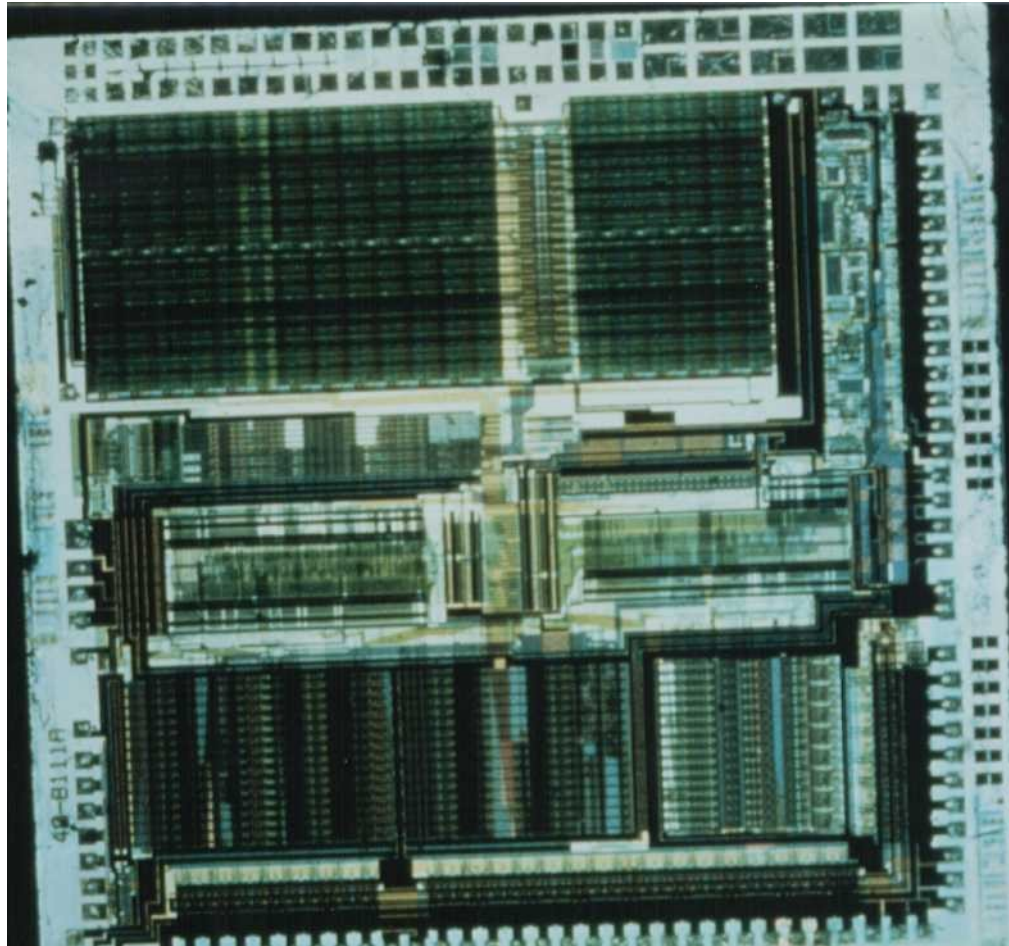
1989 M68040



1989 Intel 80486/i860



HP9000



Intel processors

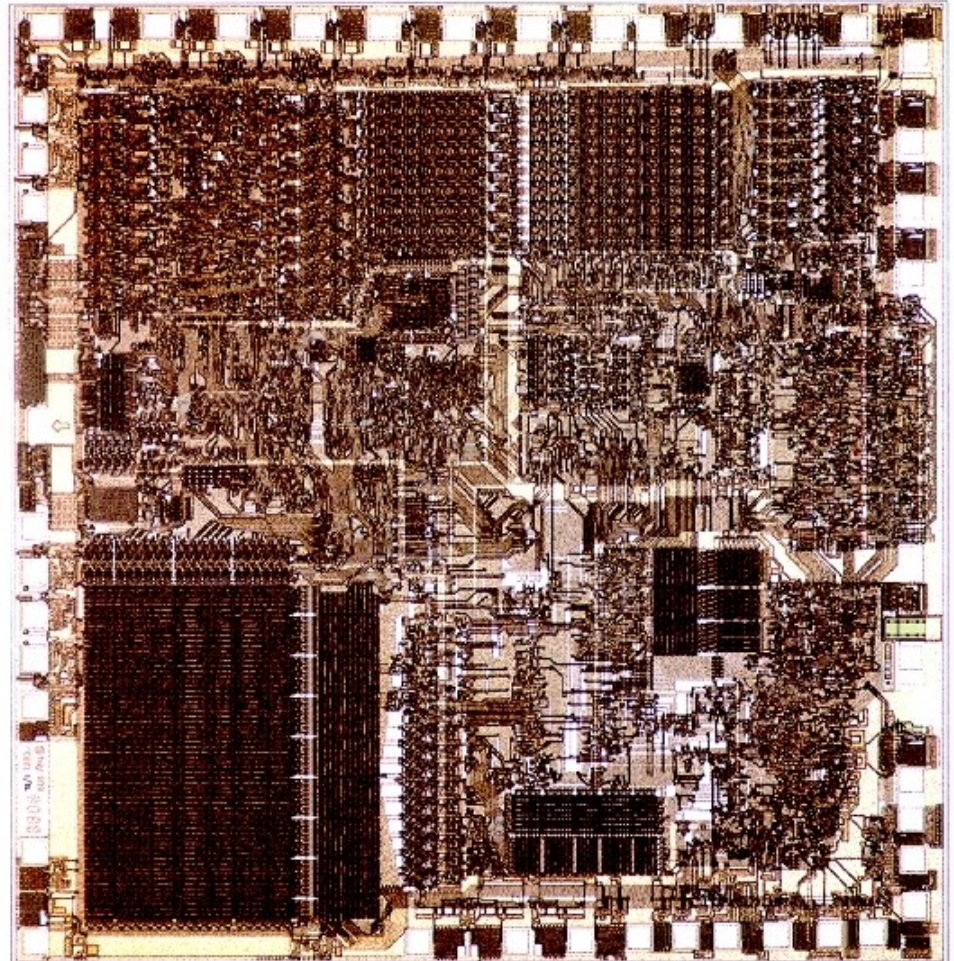
- 4004 (1971) bus 4 bits 108kHz 2k3-MOS 10u
- 8008 (1972) bus 8 bits 200kHz 3k5-MOS 10u
- 8088 (1979) bus 8 bits 1MHz 29K-MOS 3u
- I386 (1988) bus 16 bits 33MHz 275K-MOS 1u
- I486 (1989) bus 32 bits 50MHz 1.2M-MOS 0.8u
- Pentium (1993) 64 bits 66MHz 3.1M-MOS 0.8u
- Pentium 2 (97) 64 bits 300MHz 7.5M-MOS 0.35u
- Pentium 4 (00) 1.5GHz 42M-MOS 0.18u

Intel processors de 1971 à 2000

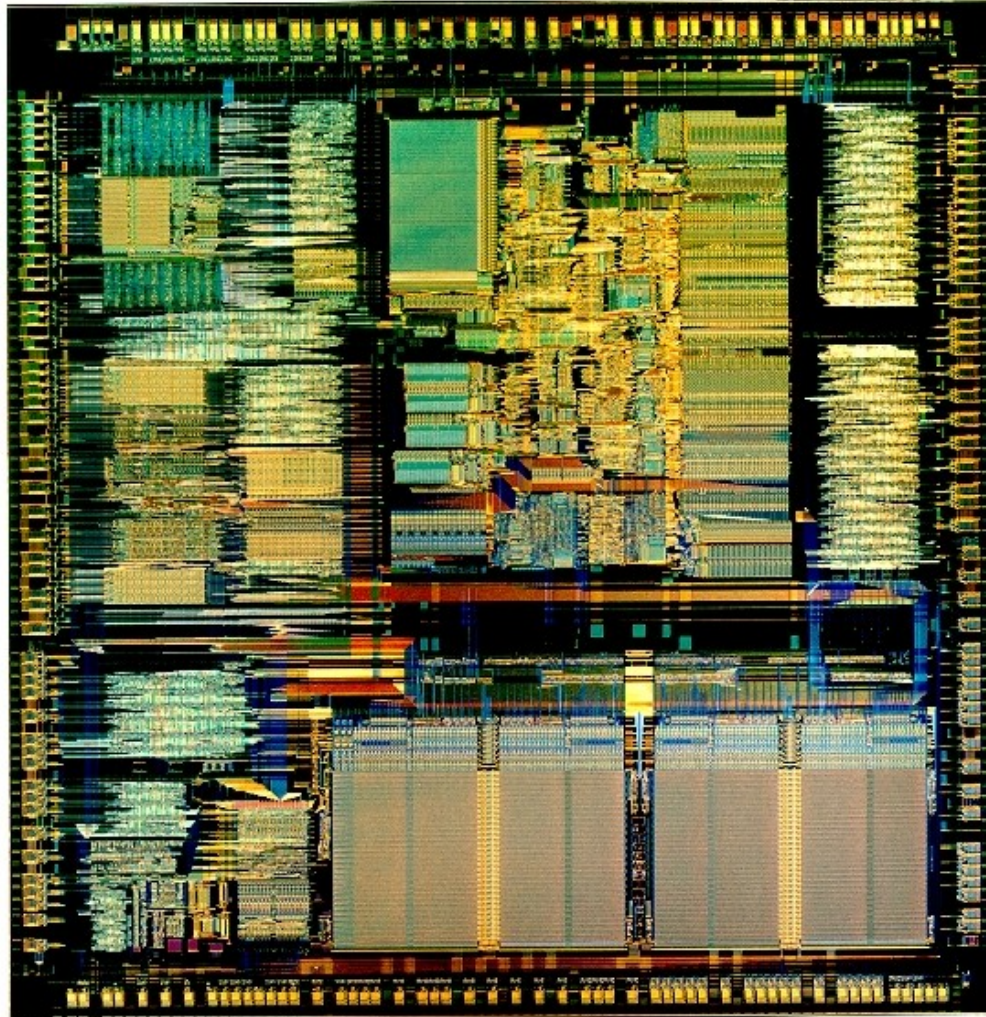
- BUS 4 à 64 bits
- Fréquence de 100 à 2G Hz
- Lignes de 10 à 0.1 micromètres
- Nb MOS de 2000 à 42 millions

1978: 8086-8088

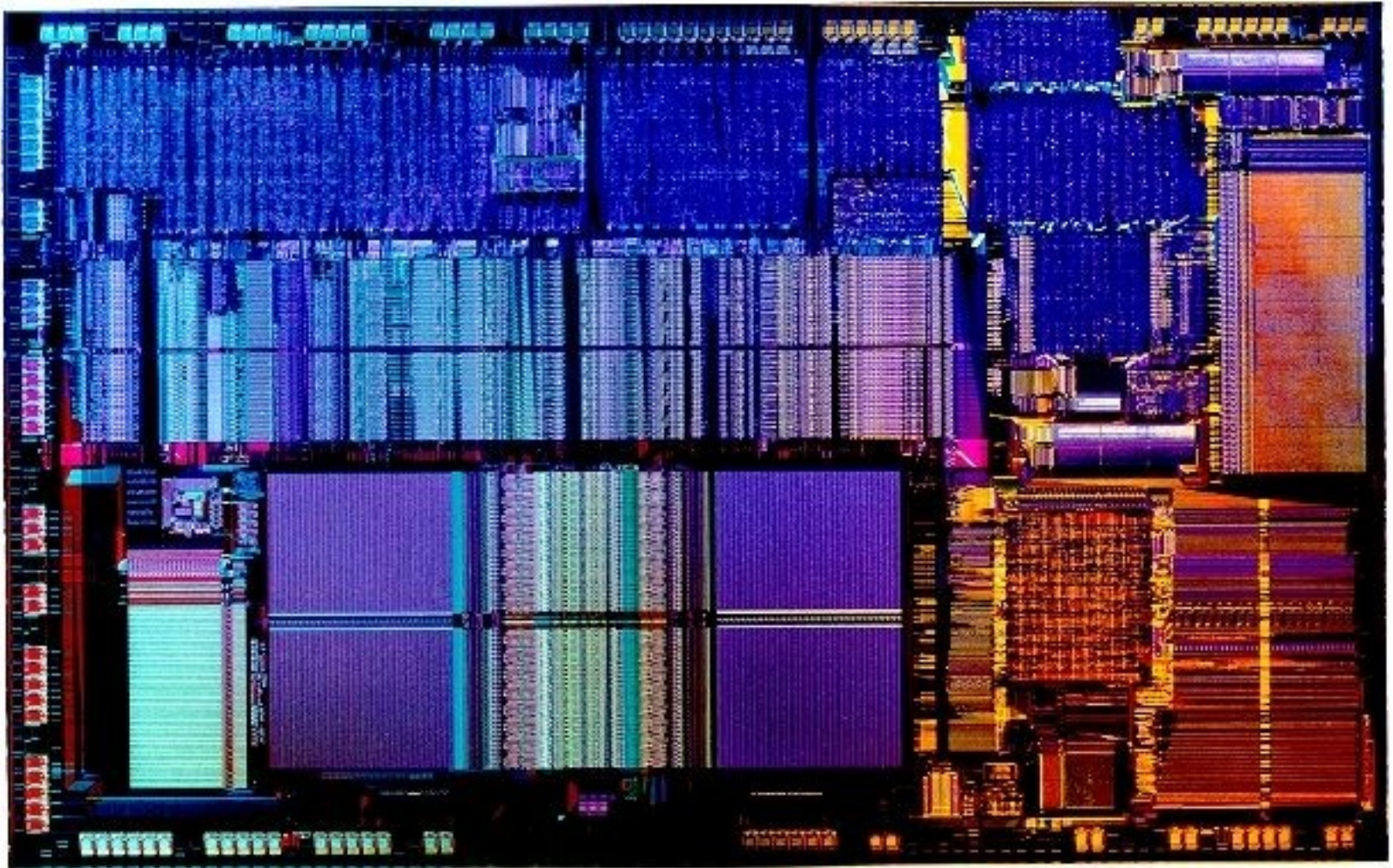
- Intel 8088
- the brains of IBM
- the IBM PC



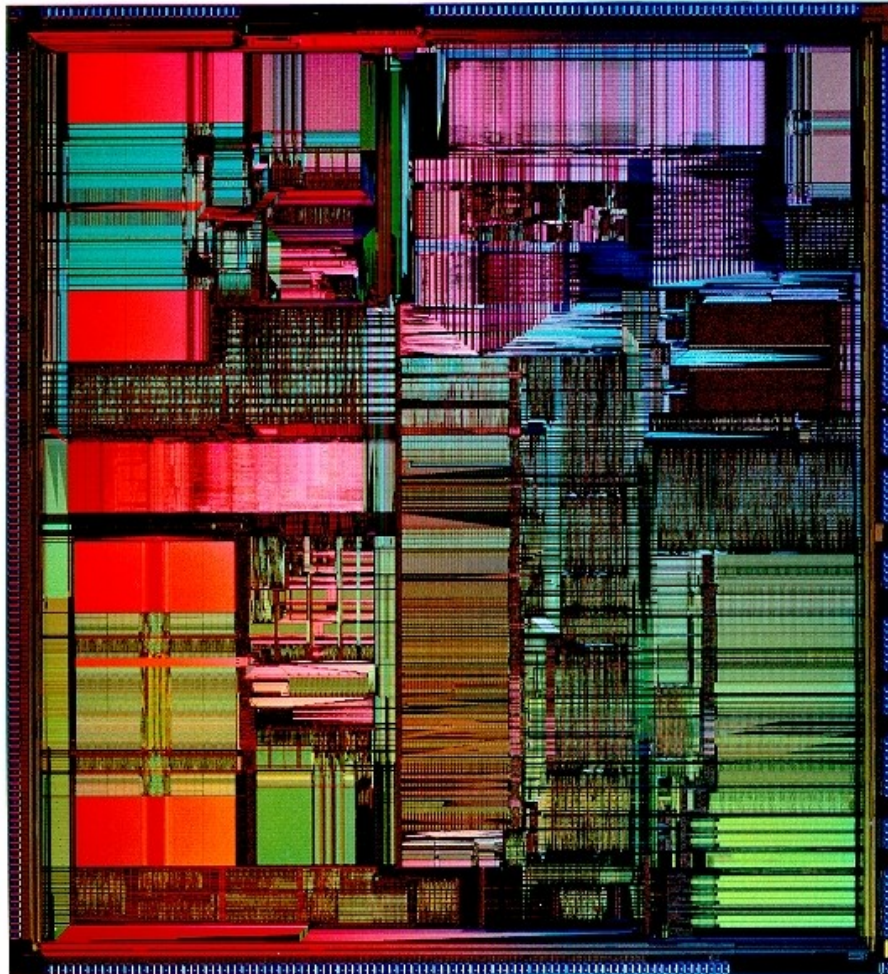
1985 Intel 386



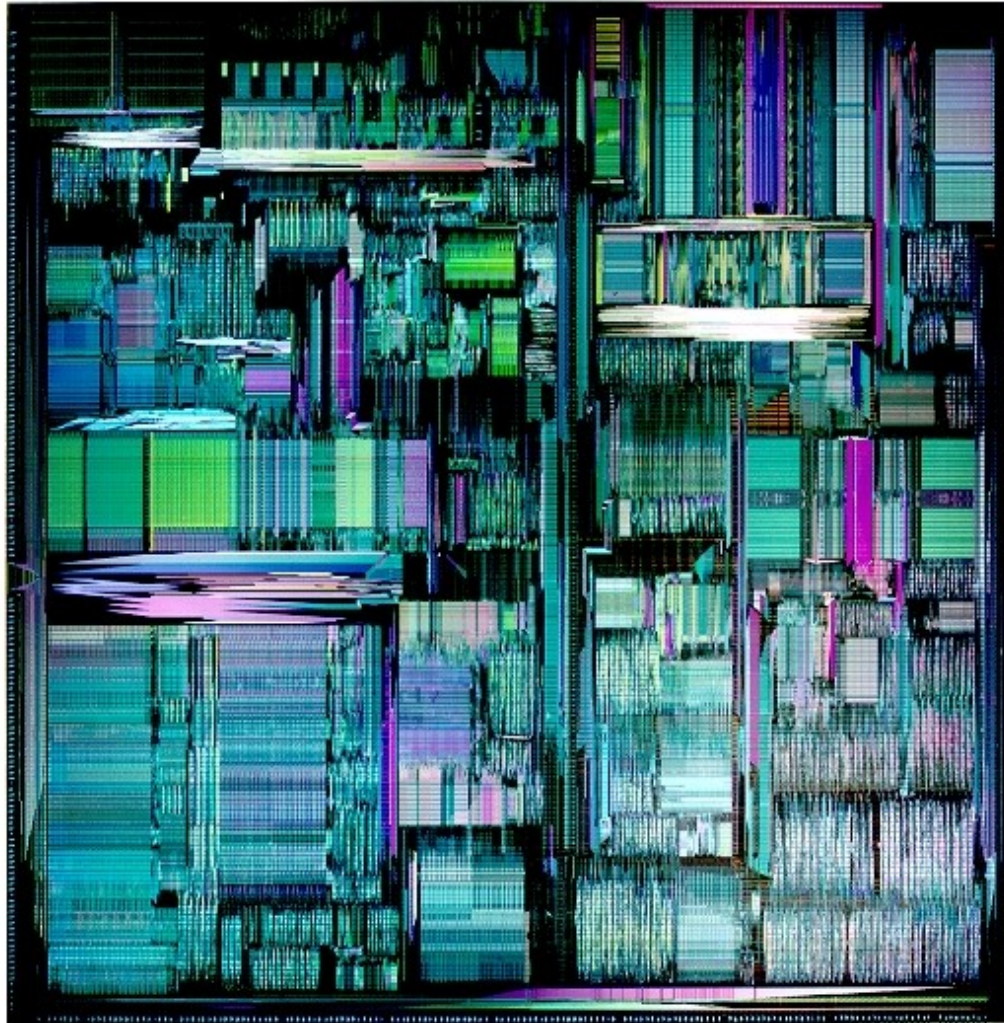
1989: Intel 486TM DX CPU



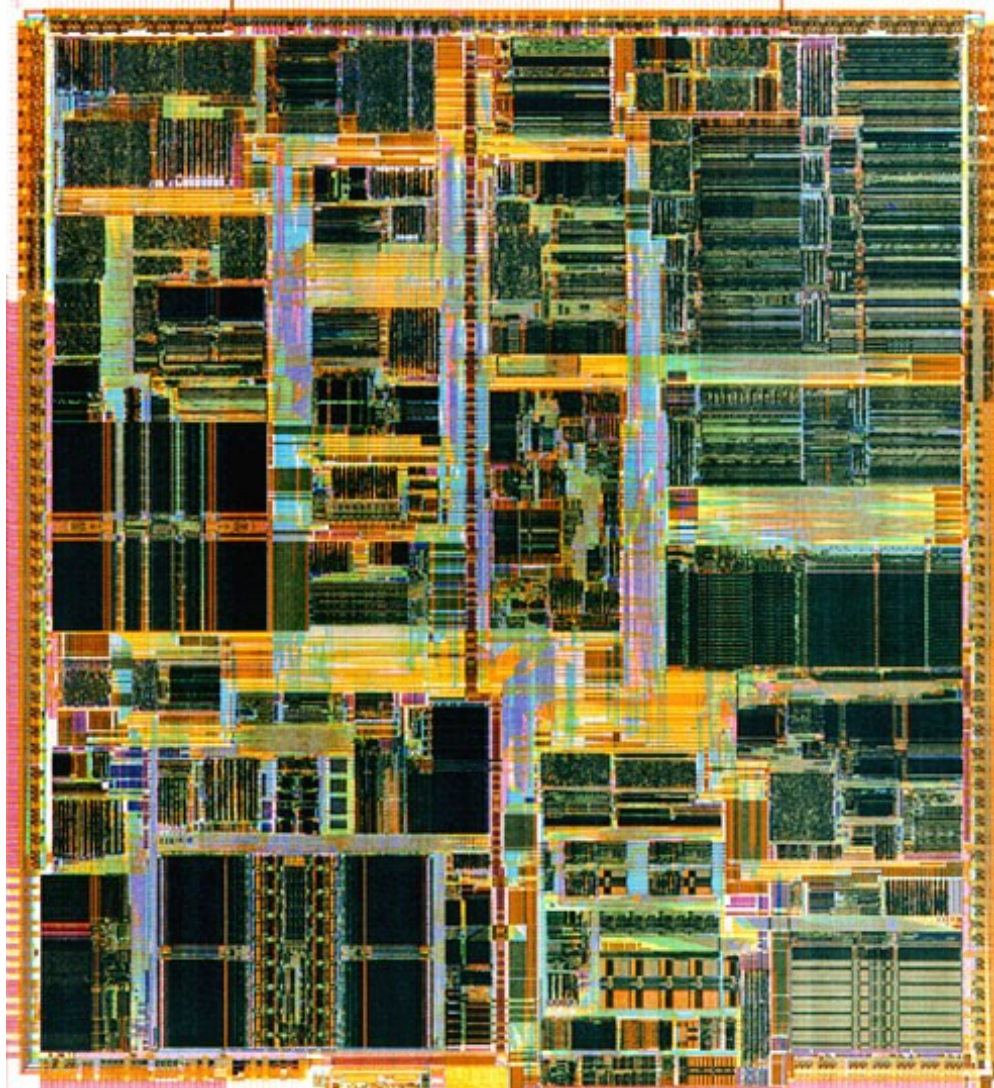
1992 Intel Pentium



1995 Intel Pentium pro

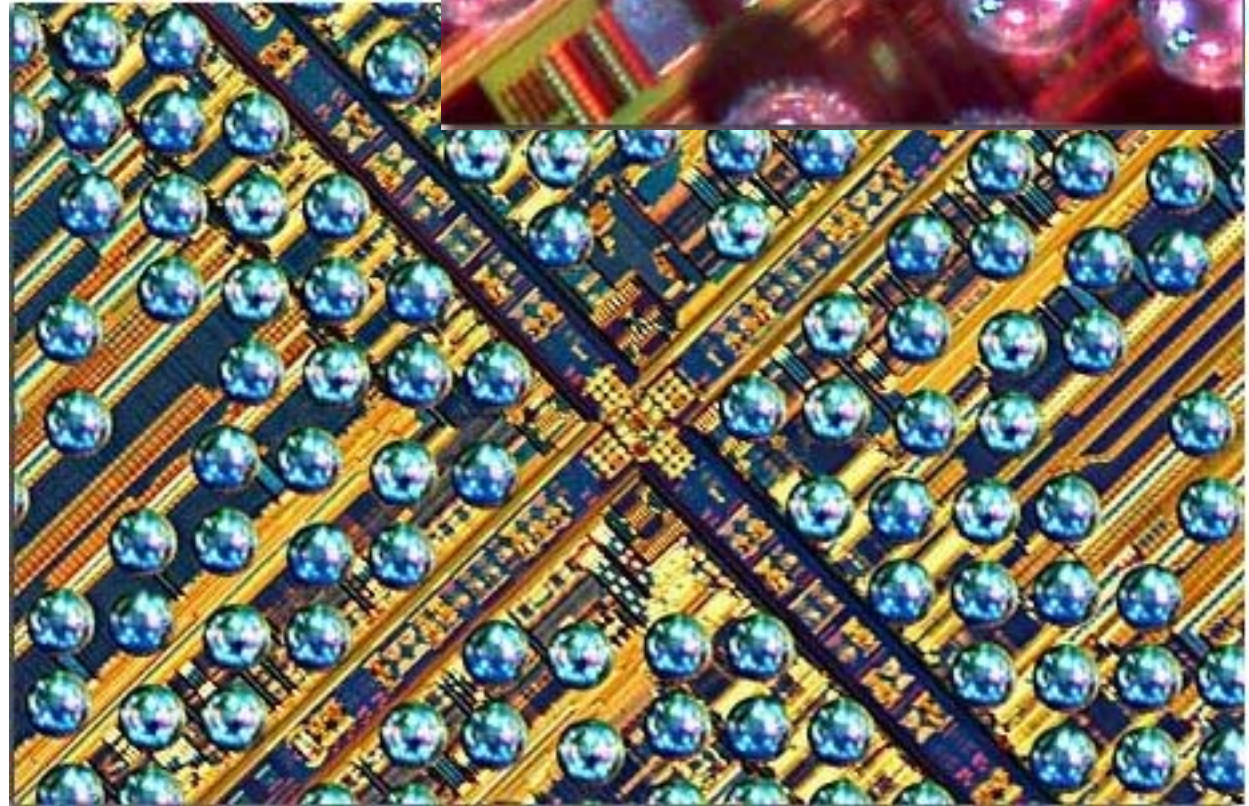


1997 Intel Pentium2

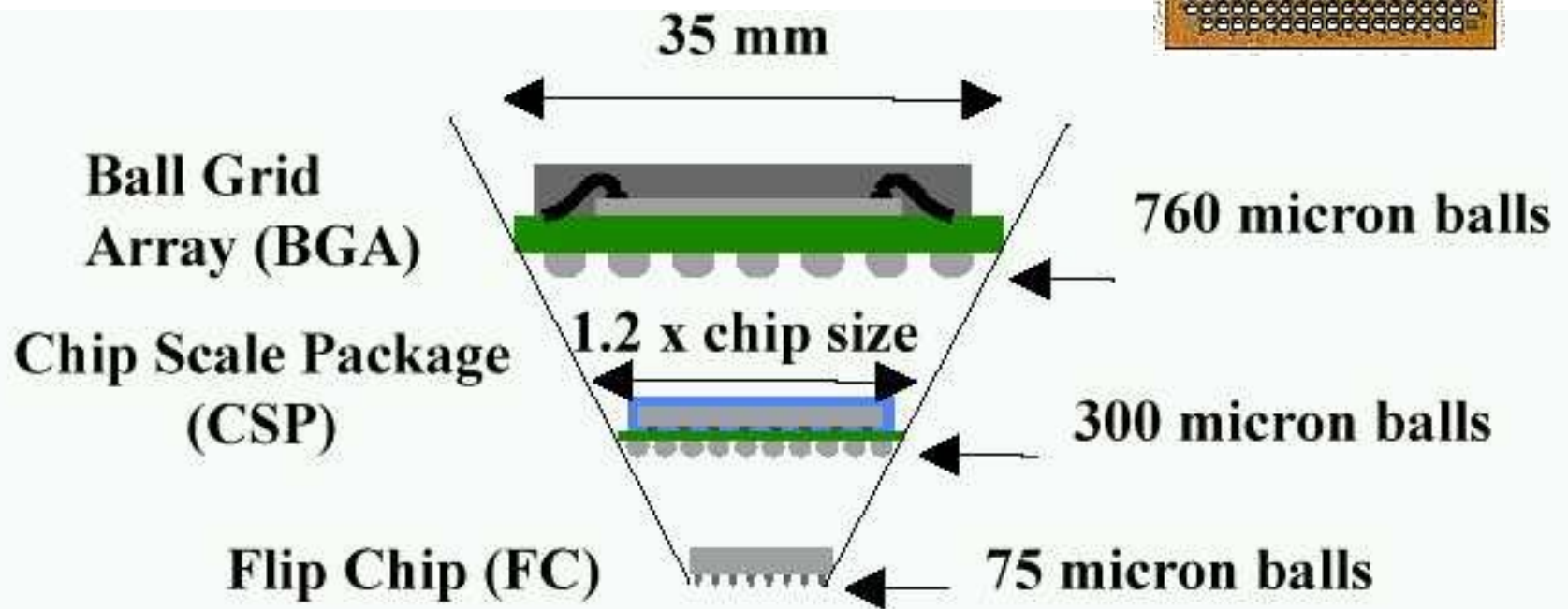
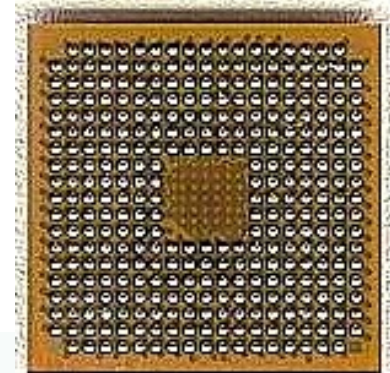


Pentium III

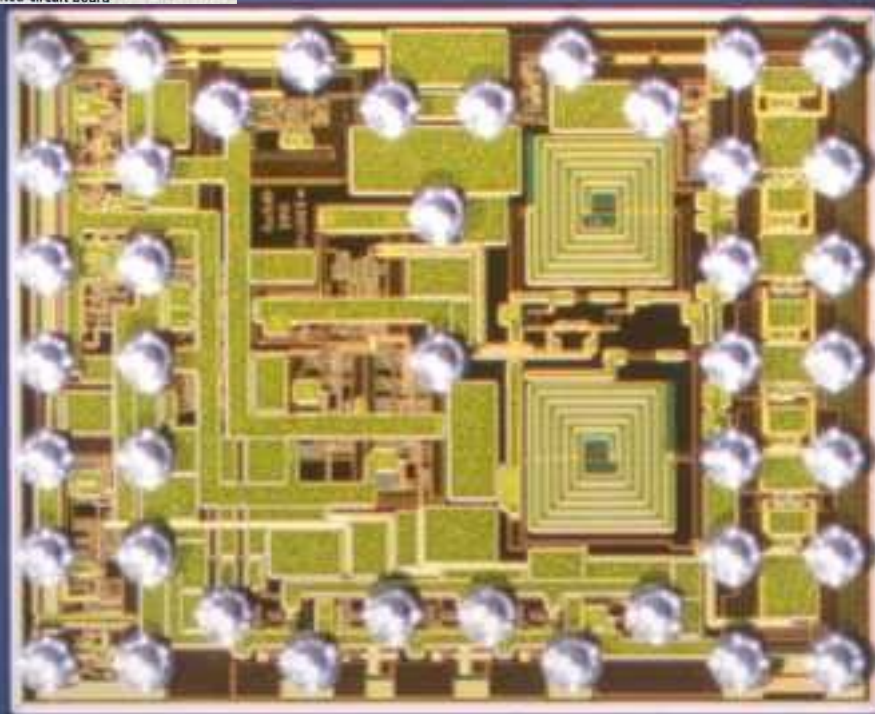
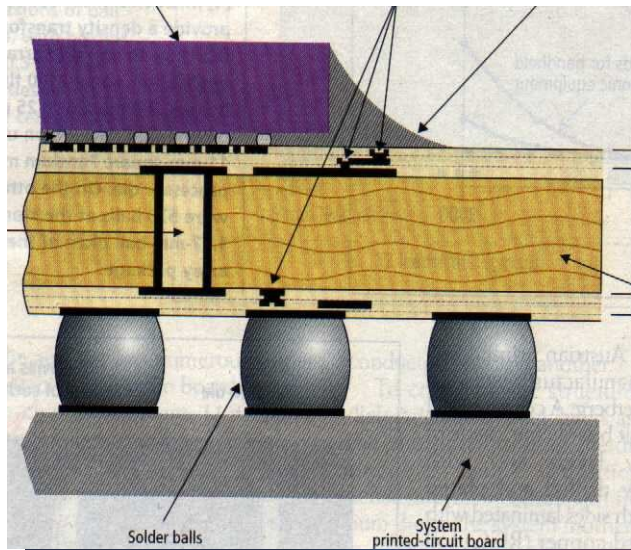
- Scribe
- solder



encapsulations

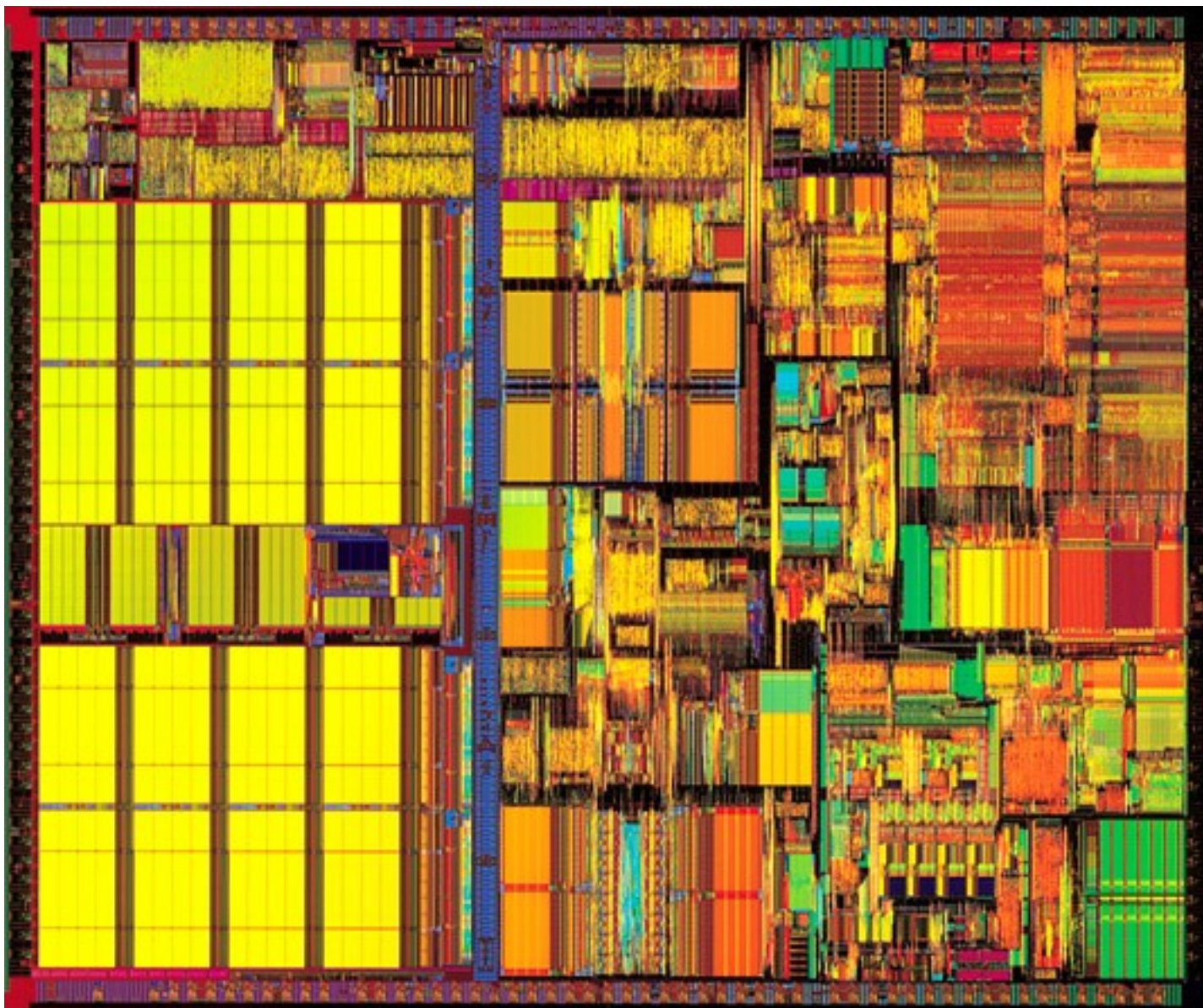


BGA



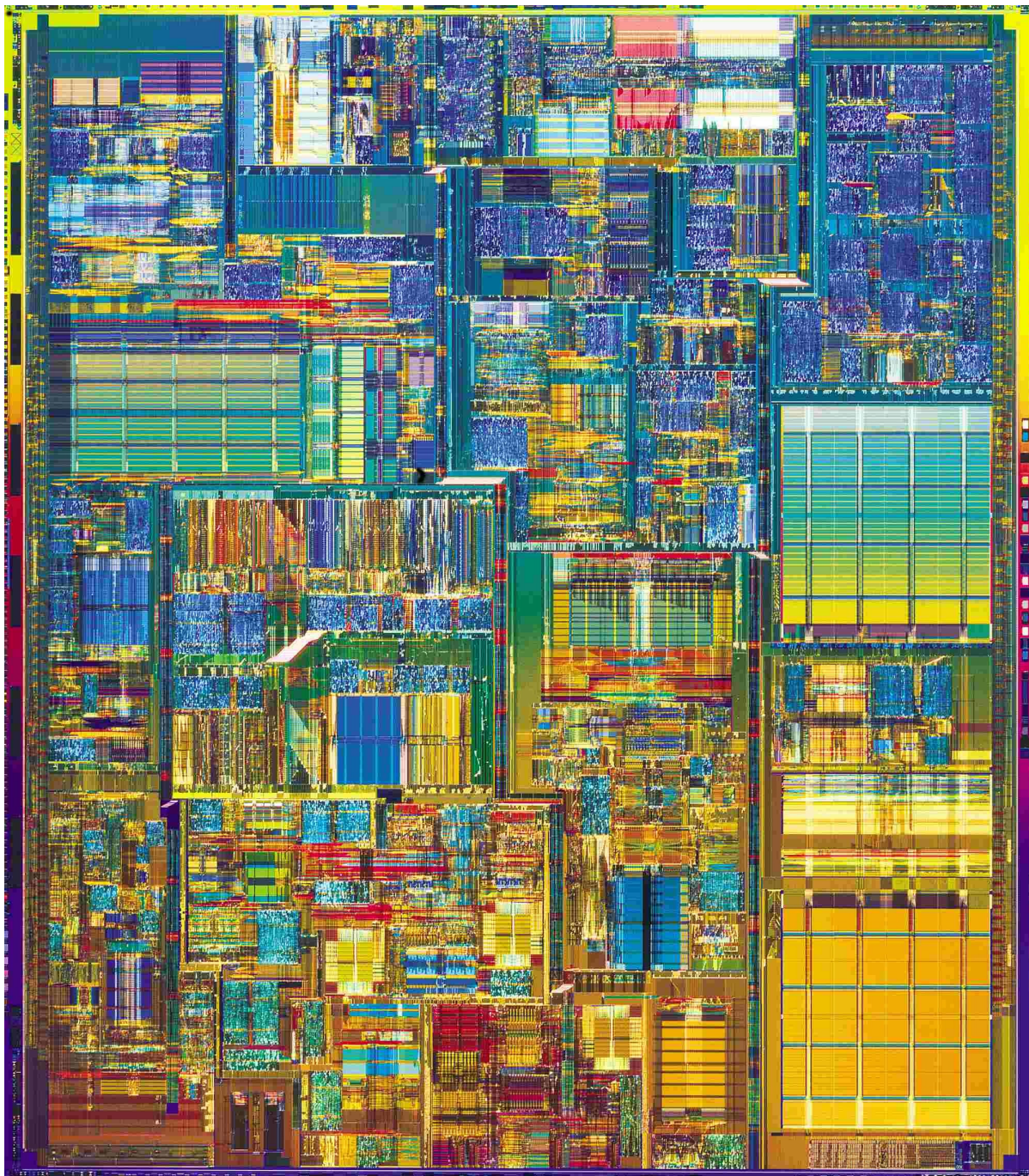
1999: Pentium® III Processor

- The Pentium® III processor features 70 new
- instructions--Internet Streaming SIMD extensions-- that
- dramatically enhance the performance of advanced imaging,
- 3-D, streaming audio, video and speech recognition
- applications. It was designed to significantly enhance Internet
- experiences, allowing users to do such things as browse
- through realistic online museums and stores and download
- high-quality video. The processor incorporates **9.5 million**
- **transistors**, and was introduced using **0.25-micron**
- technology.

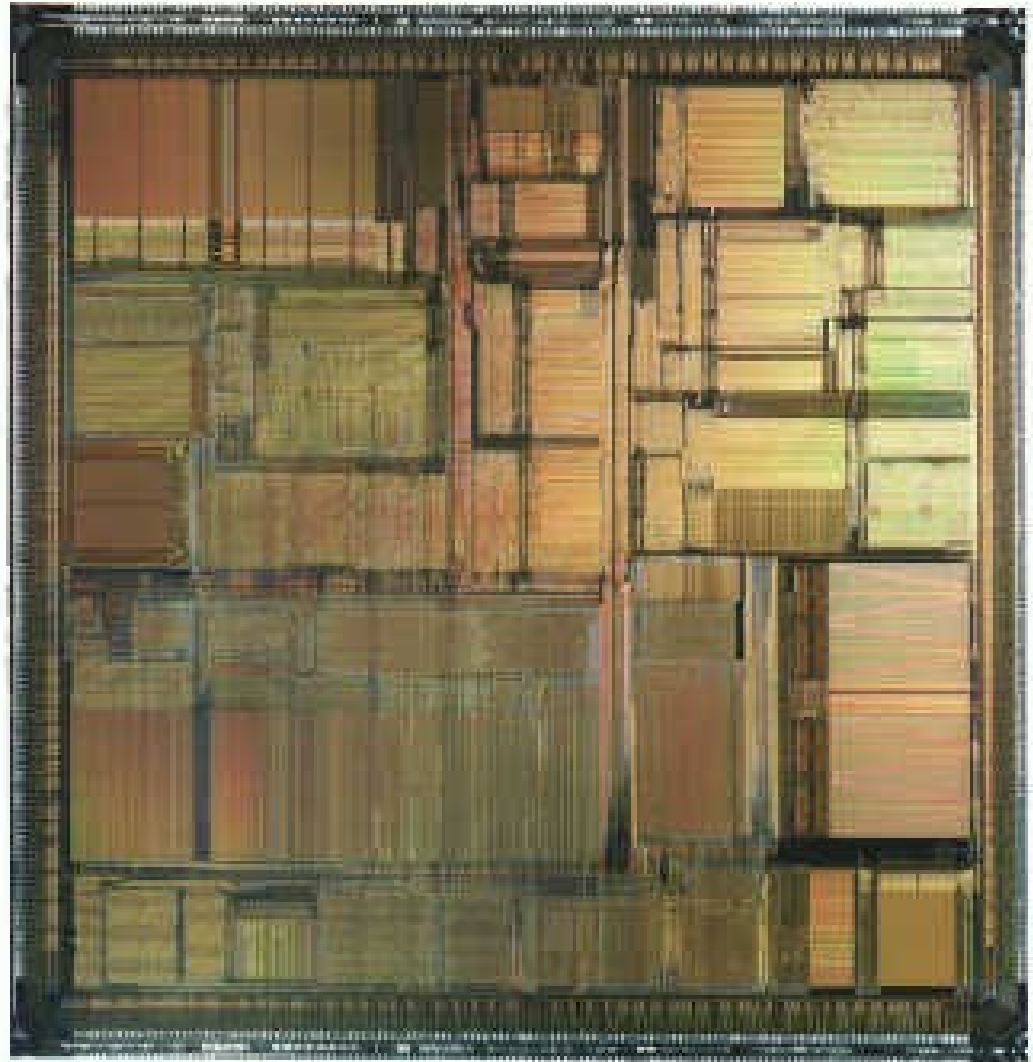


2000: Pentium® 4 Processor

- Users of Pentium® 4 processor-based PCs can create
- professional-quality movies; deliver TV-like video via the
- Internet; communicate with real-time video and voice; render
- 3D graphics in real time; quickly encode music for MP3
- players; and simultaneously run several multimedia
- applications while connected to the Internet. The processor
- debuted with **42 million transistors** and circuit lines of **0.18**
- **microns**. Intel's first microprocessor, the 4004, ran at 108
- kilohertz (108,000 hertz), compared to the Pentium® 4
- processor's initial speed of **1.5 gigahertz** (1.5 billion hertz). If
- automobile speed had increased similarly over the same
- period, you could now drive from San Francisco to New York
- in about 13 seconds.

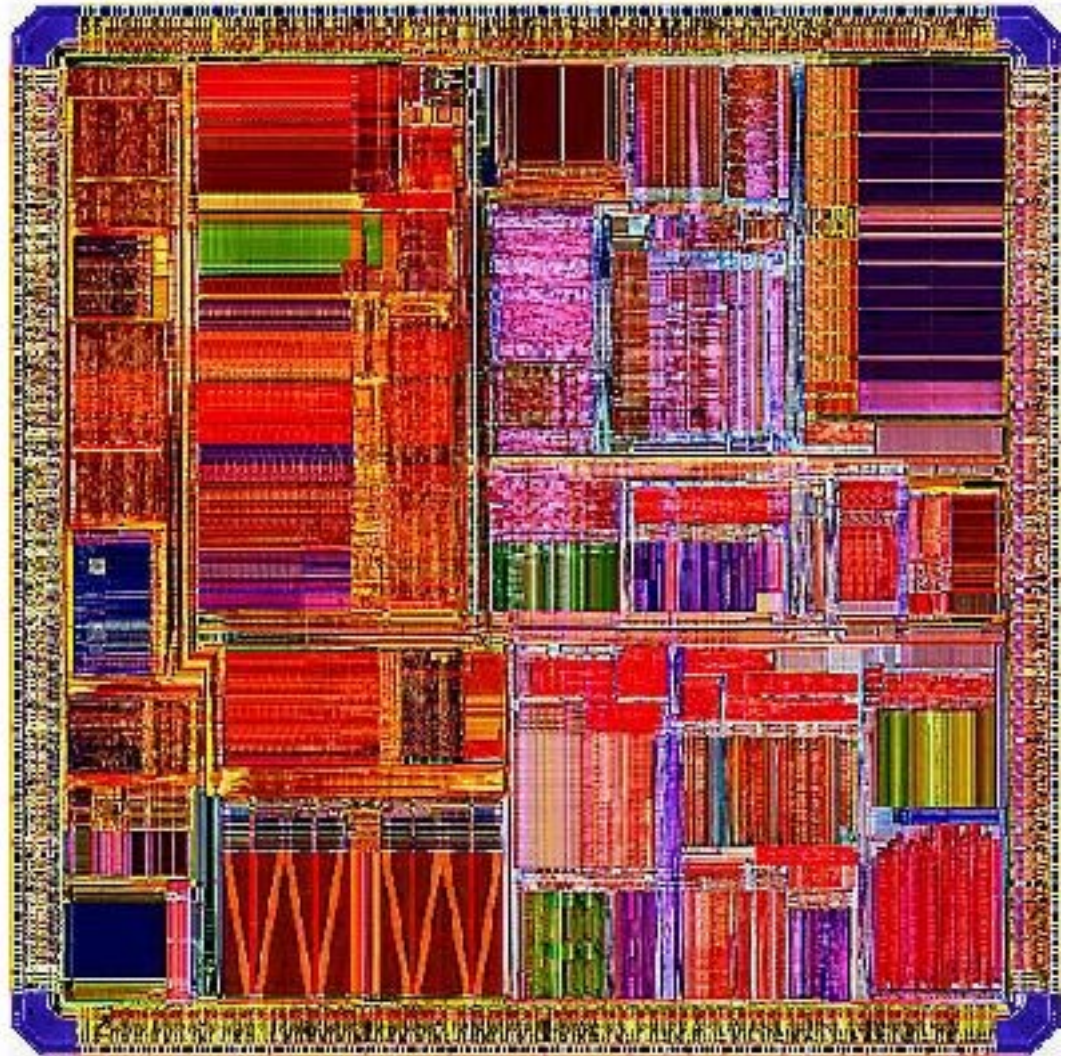


Ultra Sparc

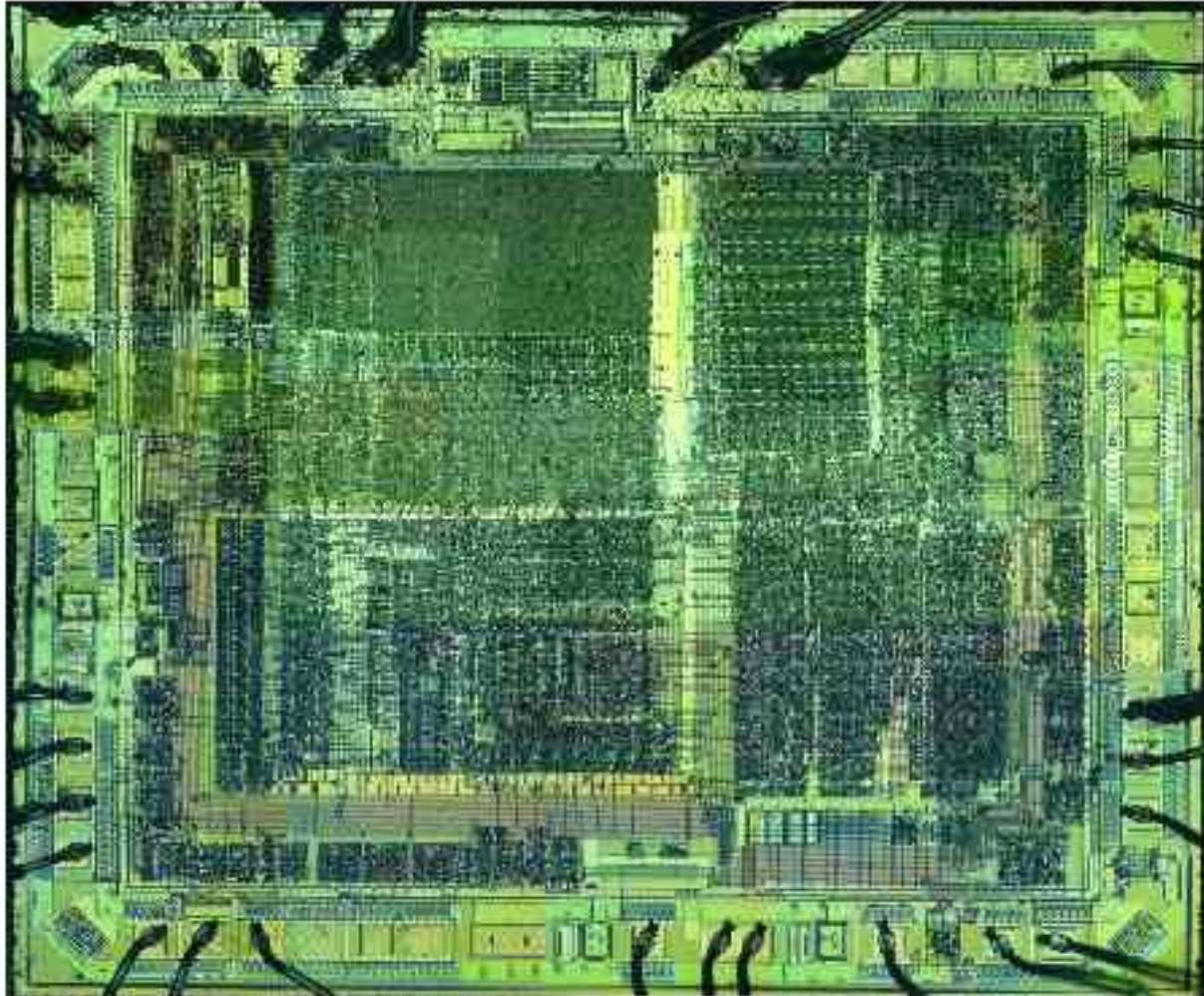


2006

UltraSPARC



Microcontrôleur PIC16C62A / JW

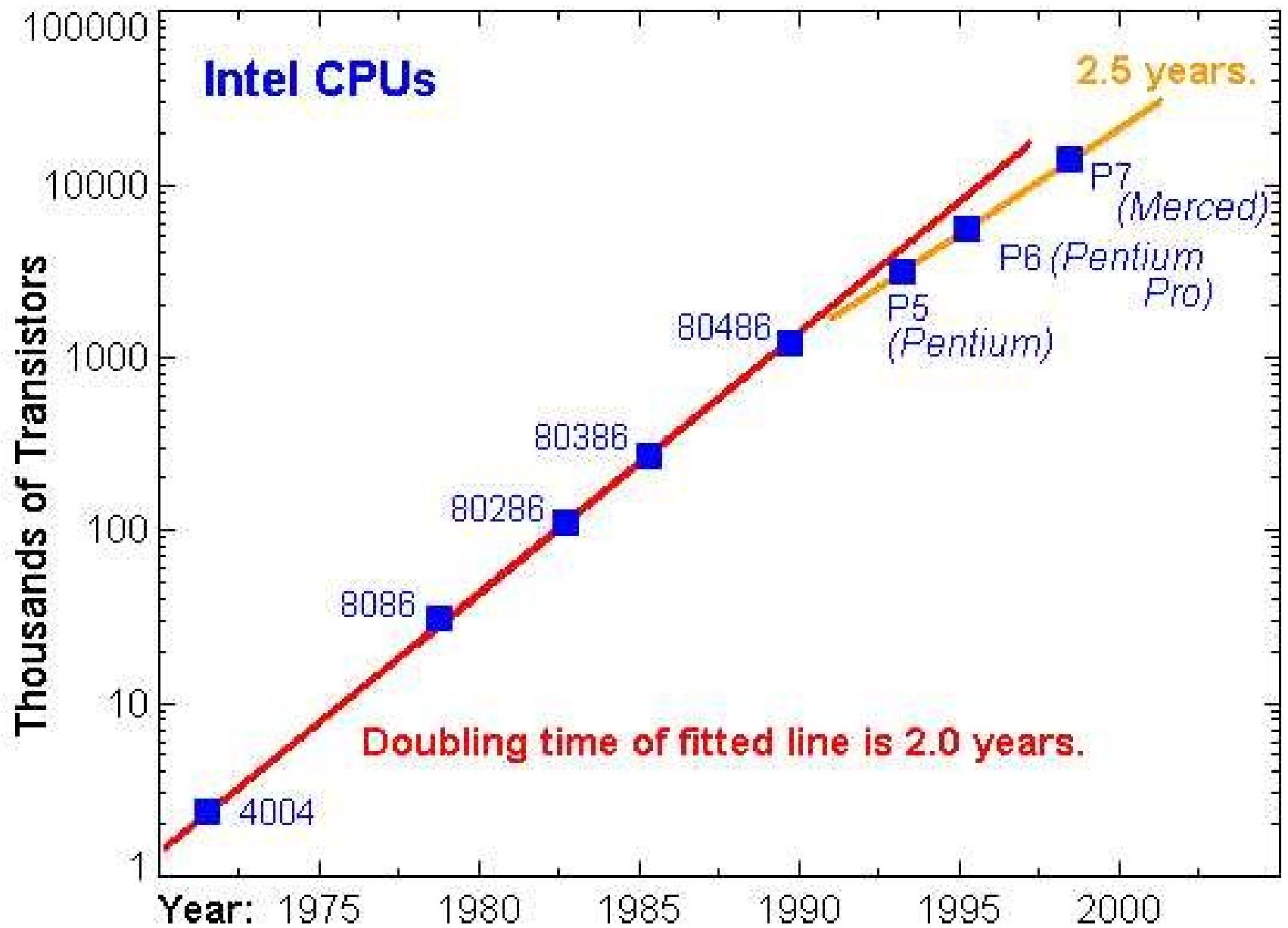


Projet de Semaines X
10. octobre 2002

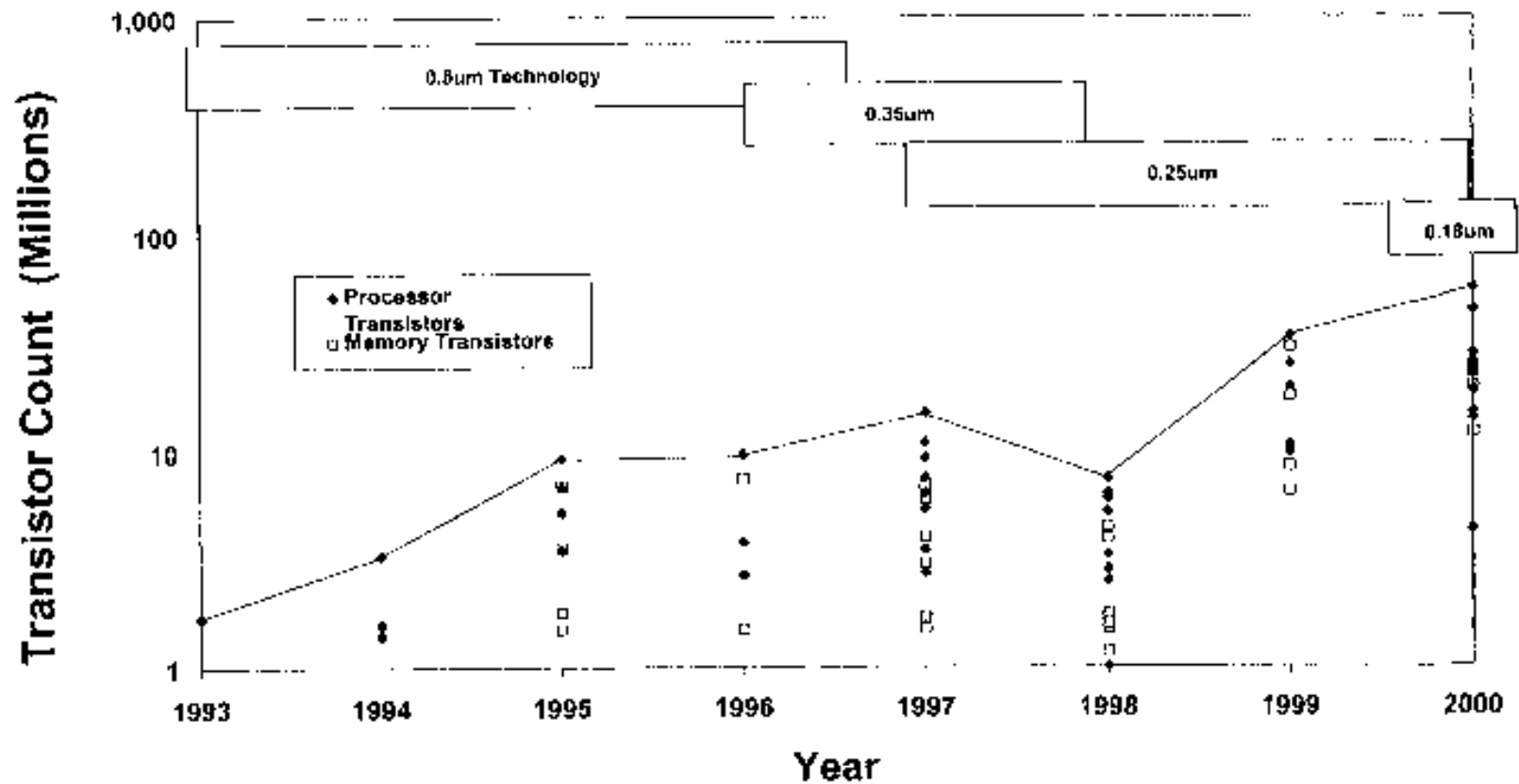
Carbonyo Rahy
Encadré par J.-C. Martin

A l'aide de Riadh Ghazal et Christoph Sudan

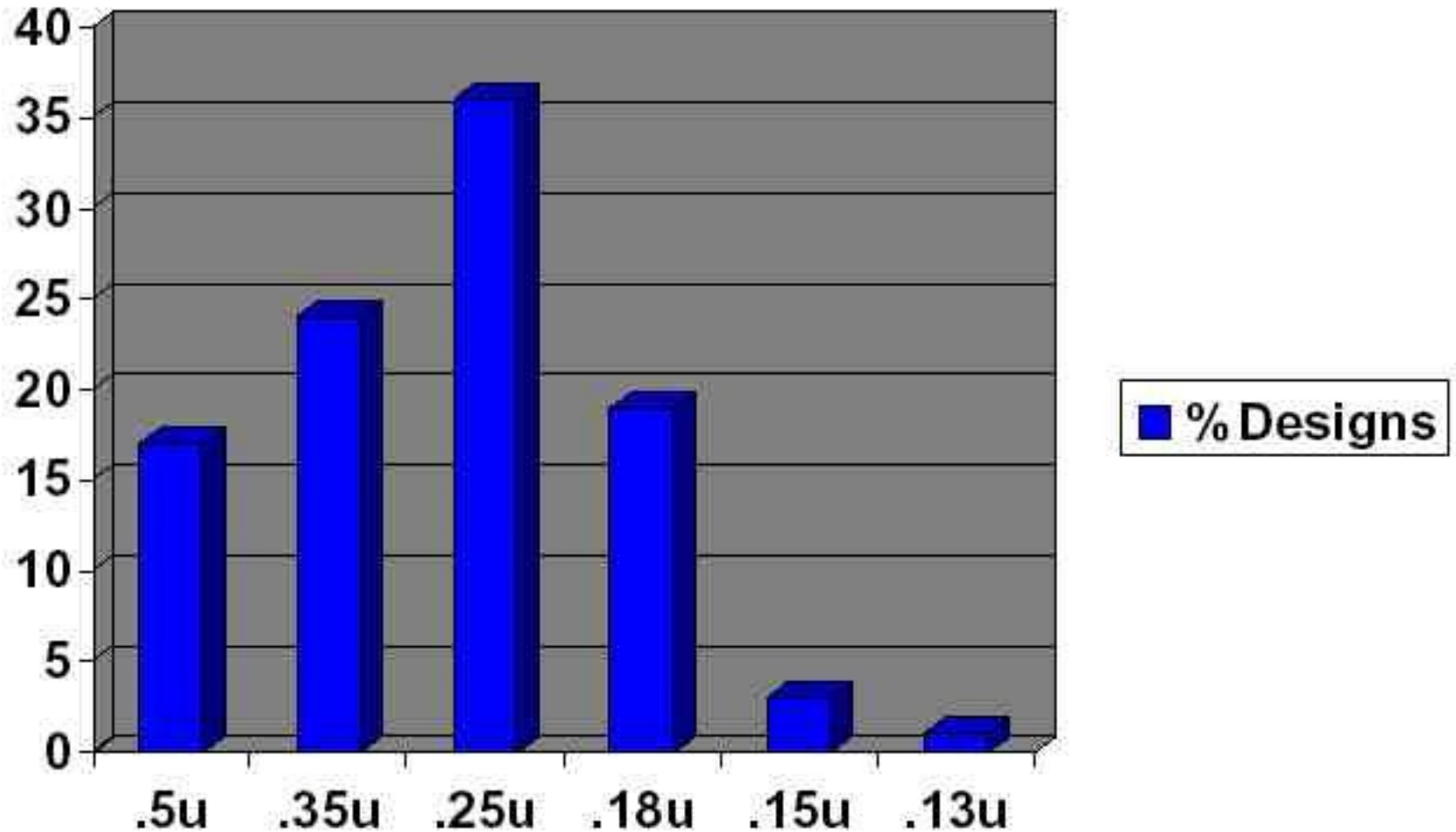
Moore's law



MICROPROCESSORS: Transistor Count vs Year

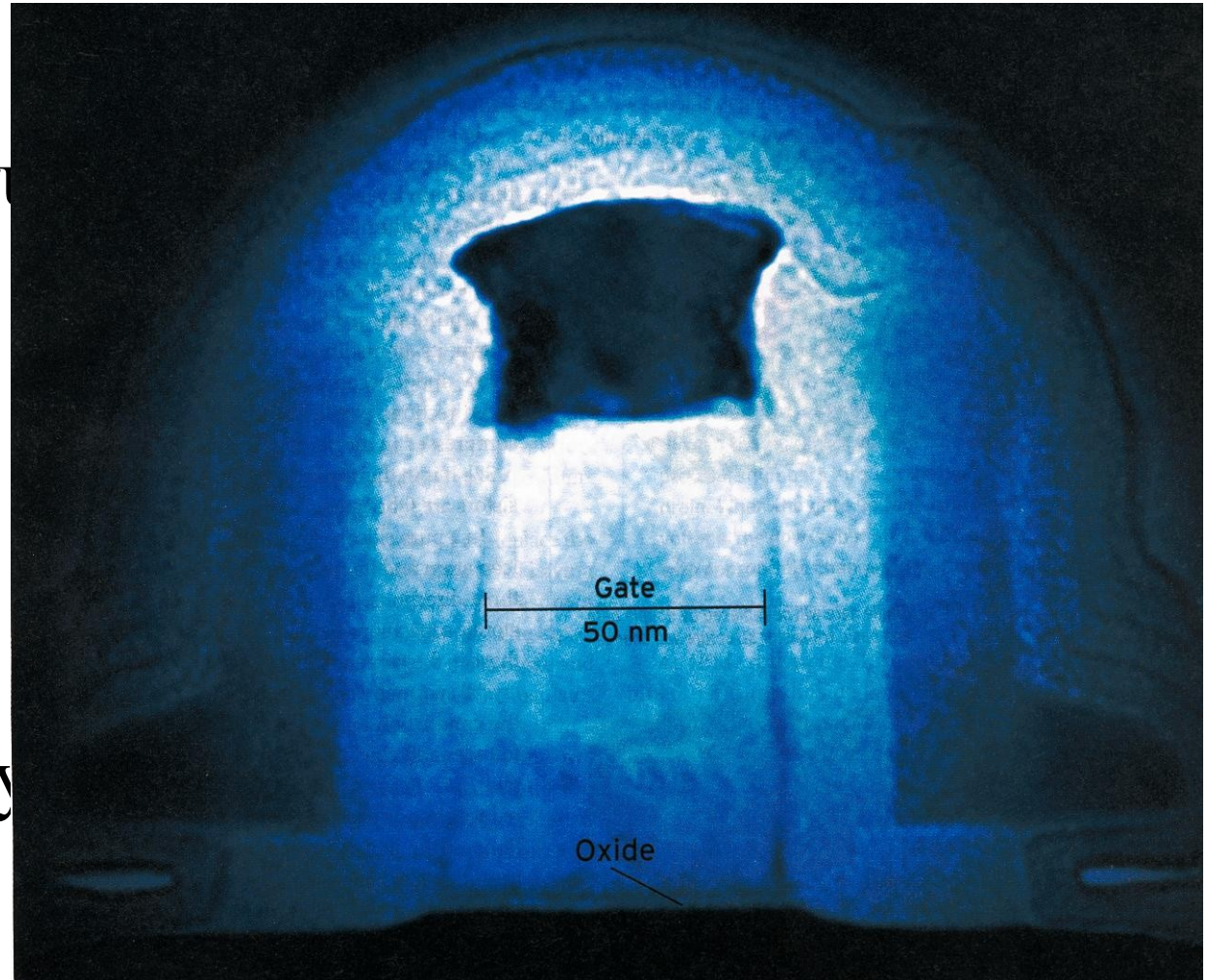


Transistor size in 2000

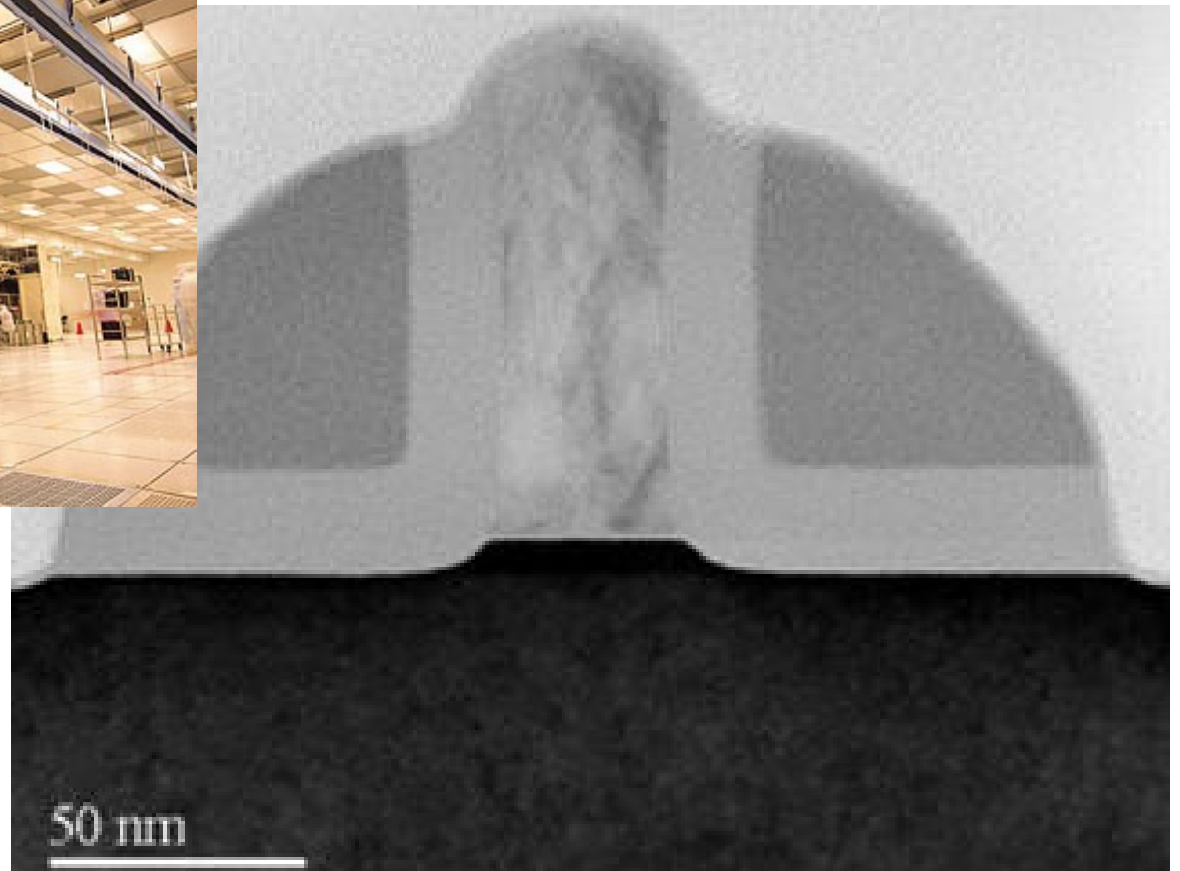


Nano MOS

- IEEE Spectrum
- oct. 2002
- Intel
- prod. 2003
- $L=50\text{nm}$
- $t_{ox}=5$ at. Lay

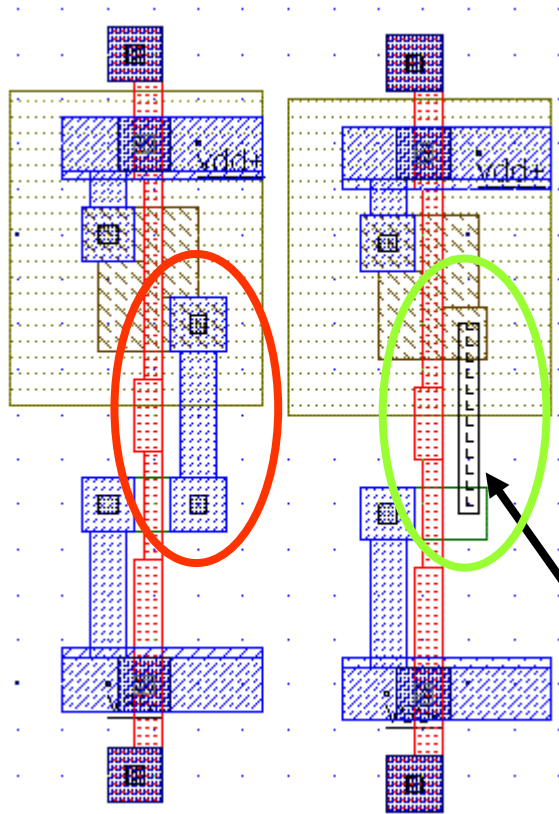


Méga usines pour nm !

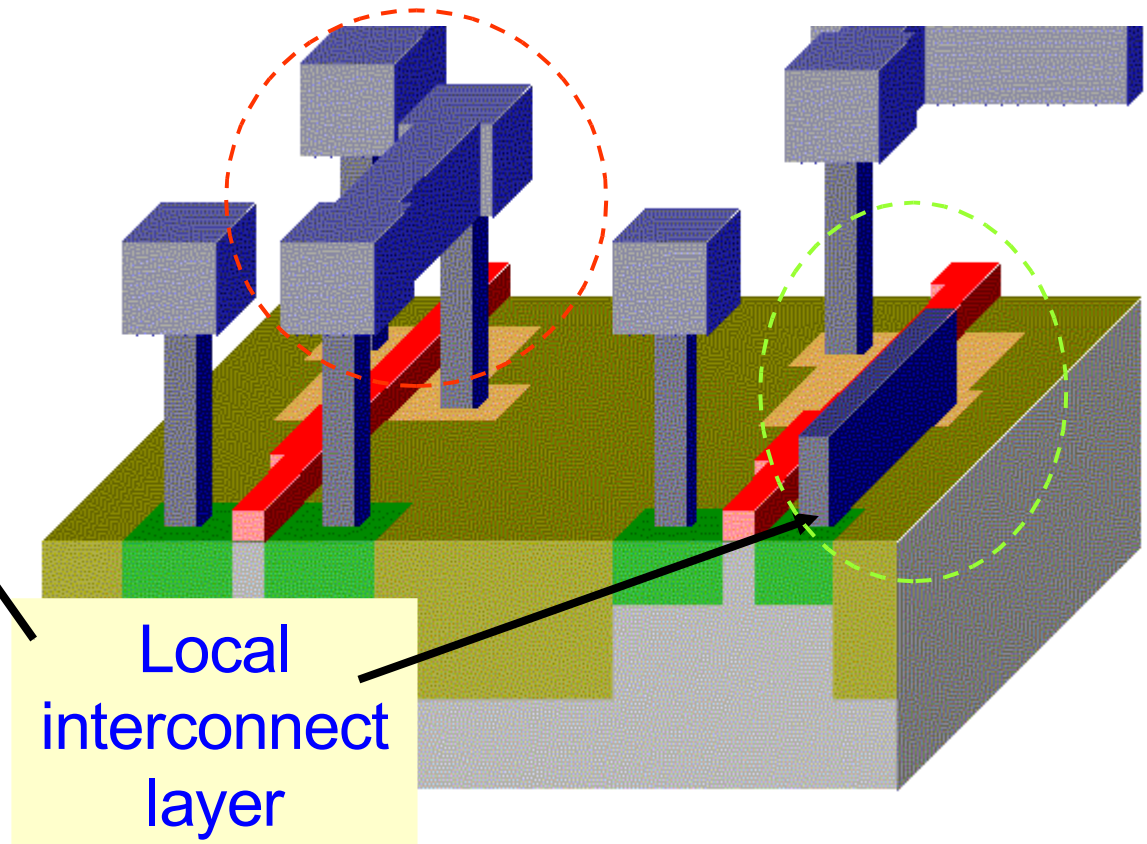


Multi metal

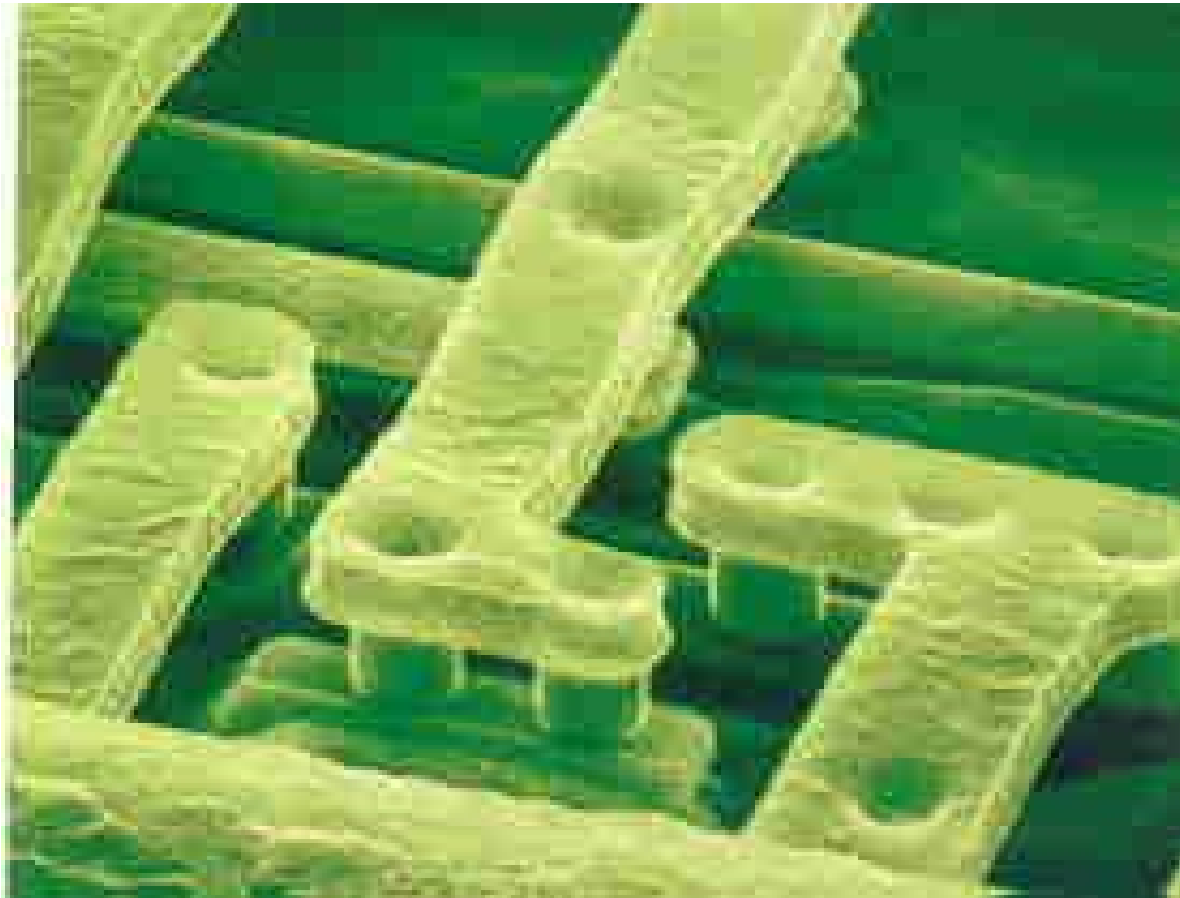
Ultra Deep Submicron features



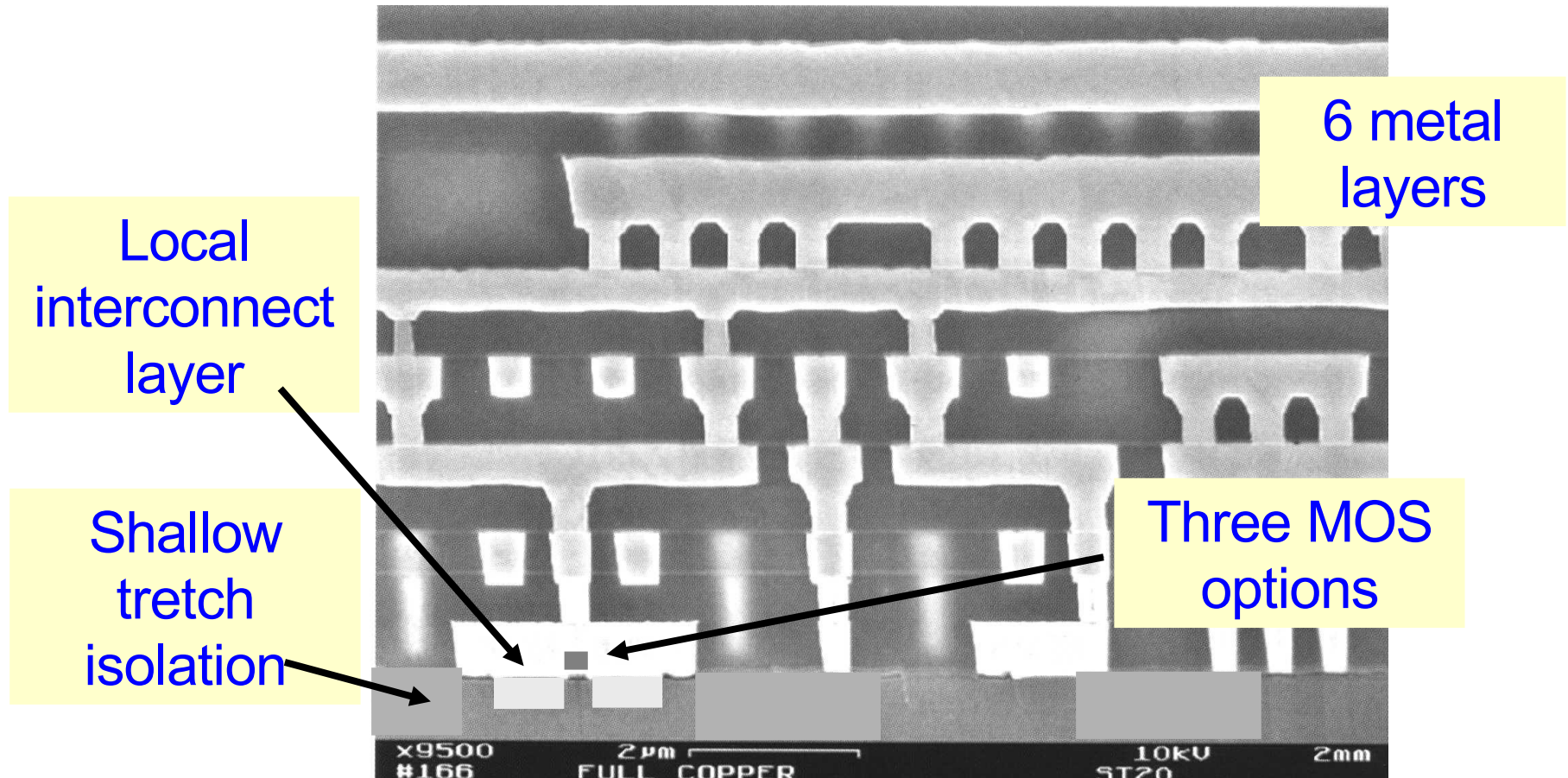
Traditional link
nMOS/pMOS



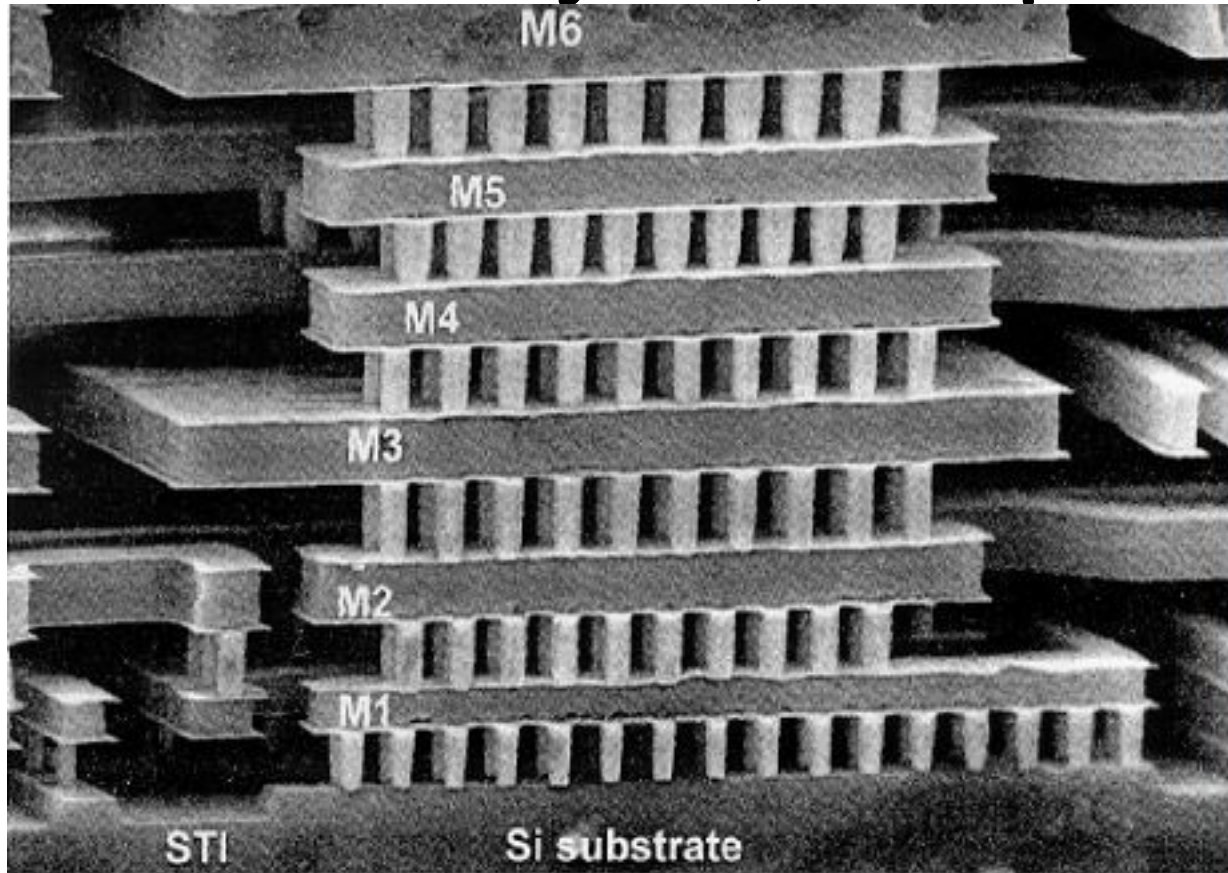
EPR0M 4M (see via)

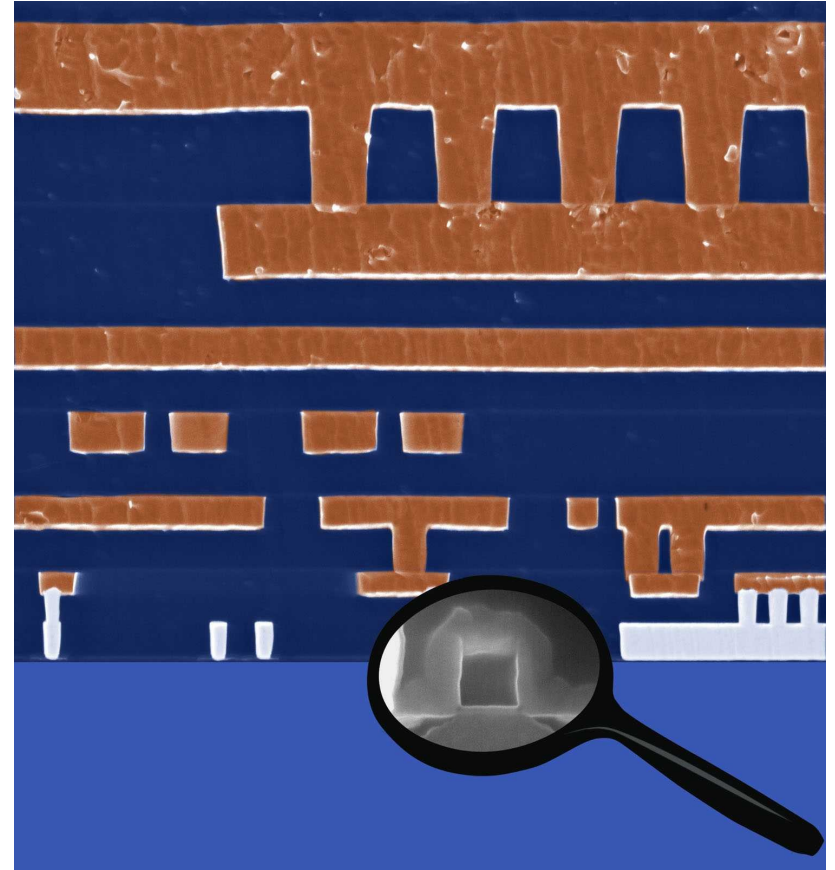
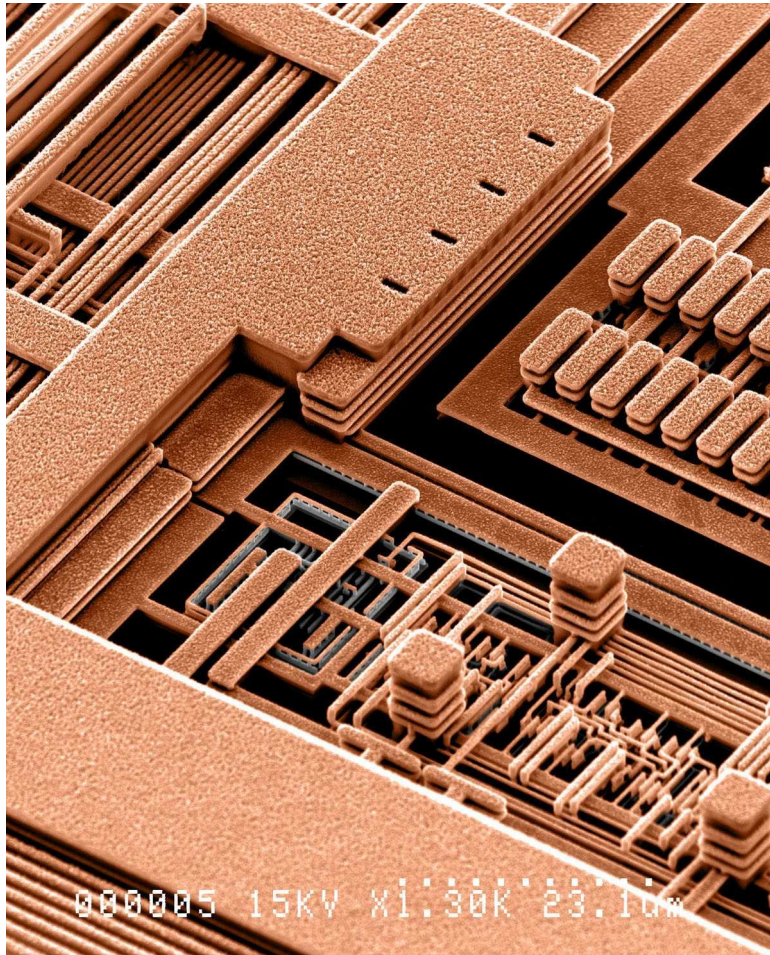


Ultra Deep Submicron features



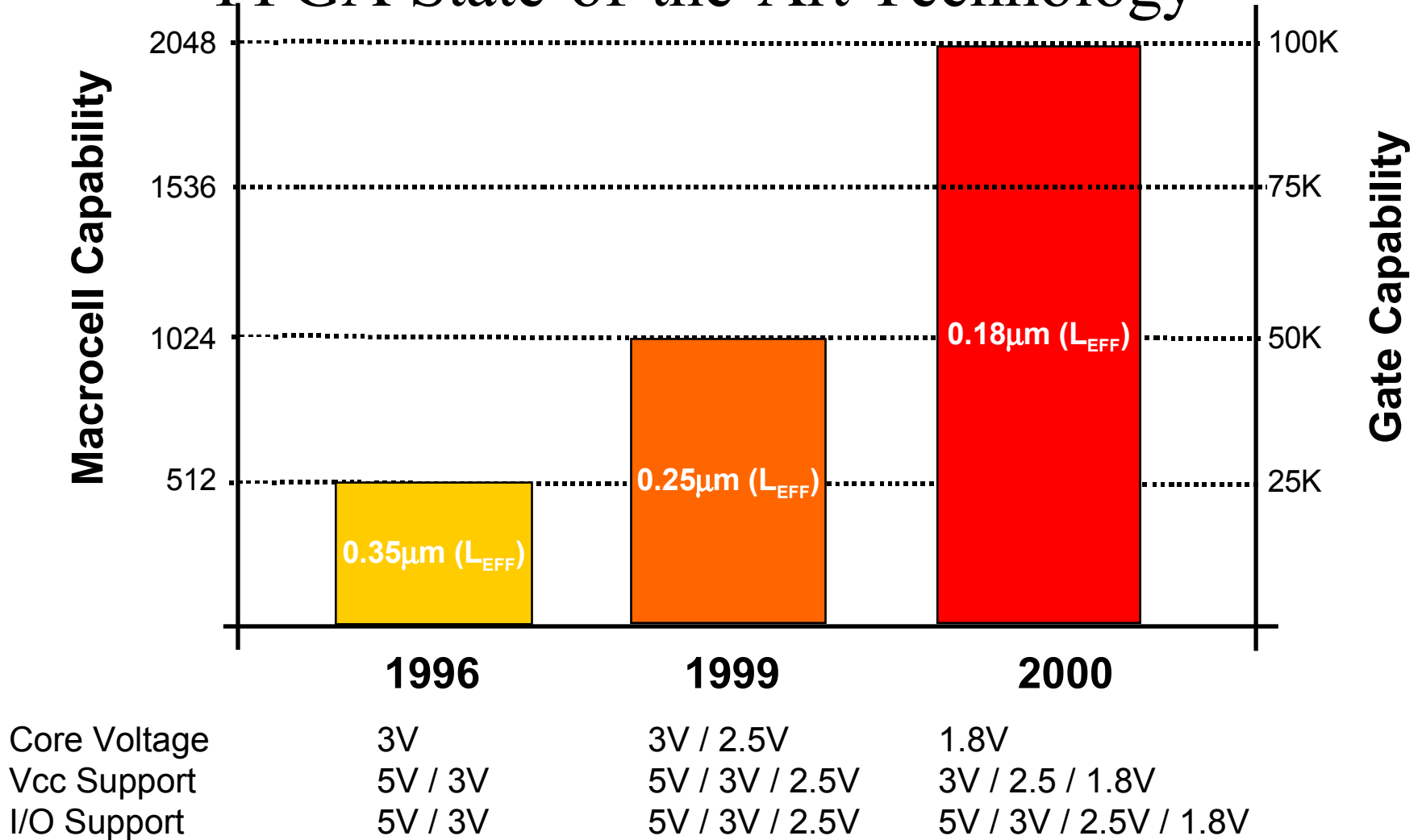
6 metal layers, 0.25 μm



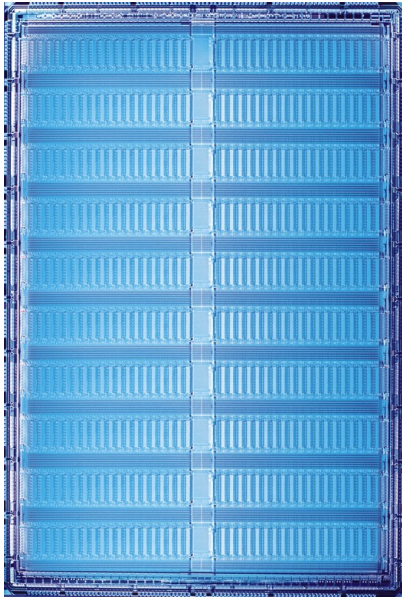


FPGA

FPGA State-of-the-Art Technology

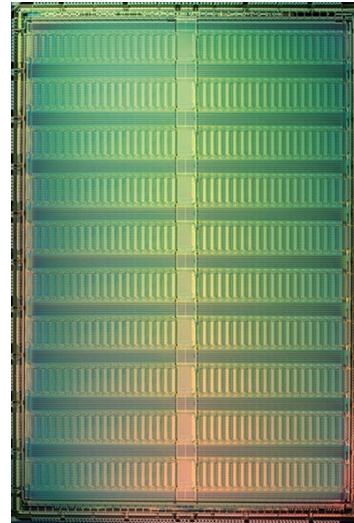


Evolution of fabrication (Altera)



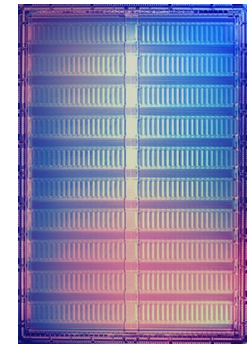
EPF10K50

0.6-Micron
Triple-Layer Metal



EPF10K50

0.5-Micron
Triple-Layer Metal



EPF10K50A

0.35-Micron
Quad-Layer Metal

Relative
Die Size:

1.0

0.78

0.32

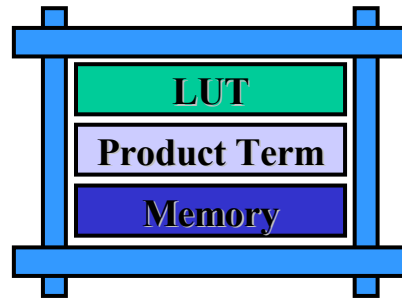
2006

J.-C. Martin

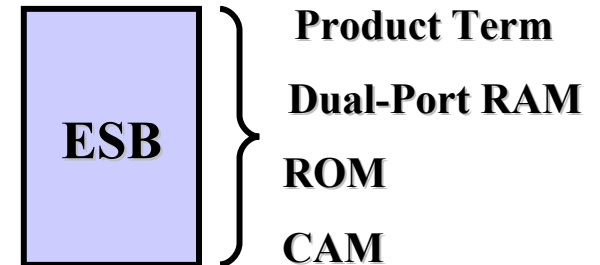
104

APEX Architectural Innovation

MultiCore™ Architecture



Embedded System Block (ESB)



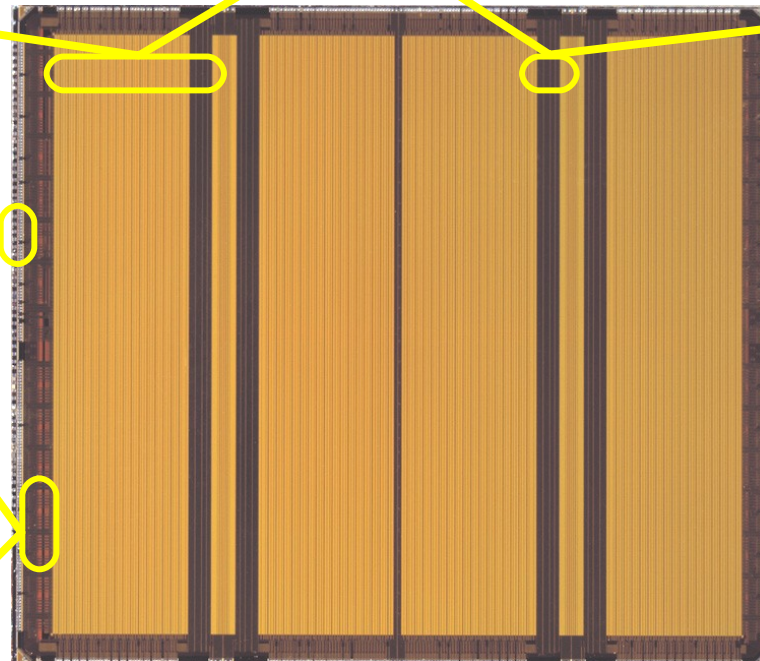
I/O Features

LVDS
MultiVolt I/O
GTL+
CTT

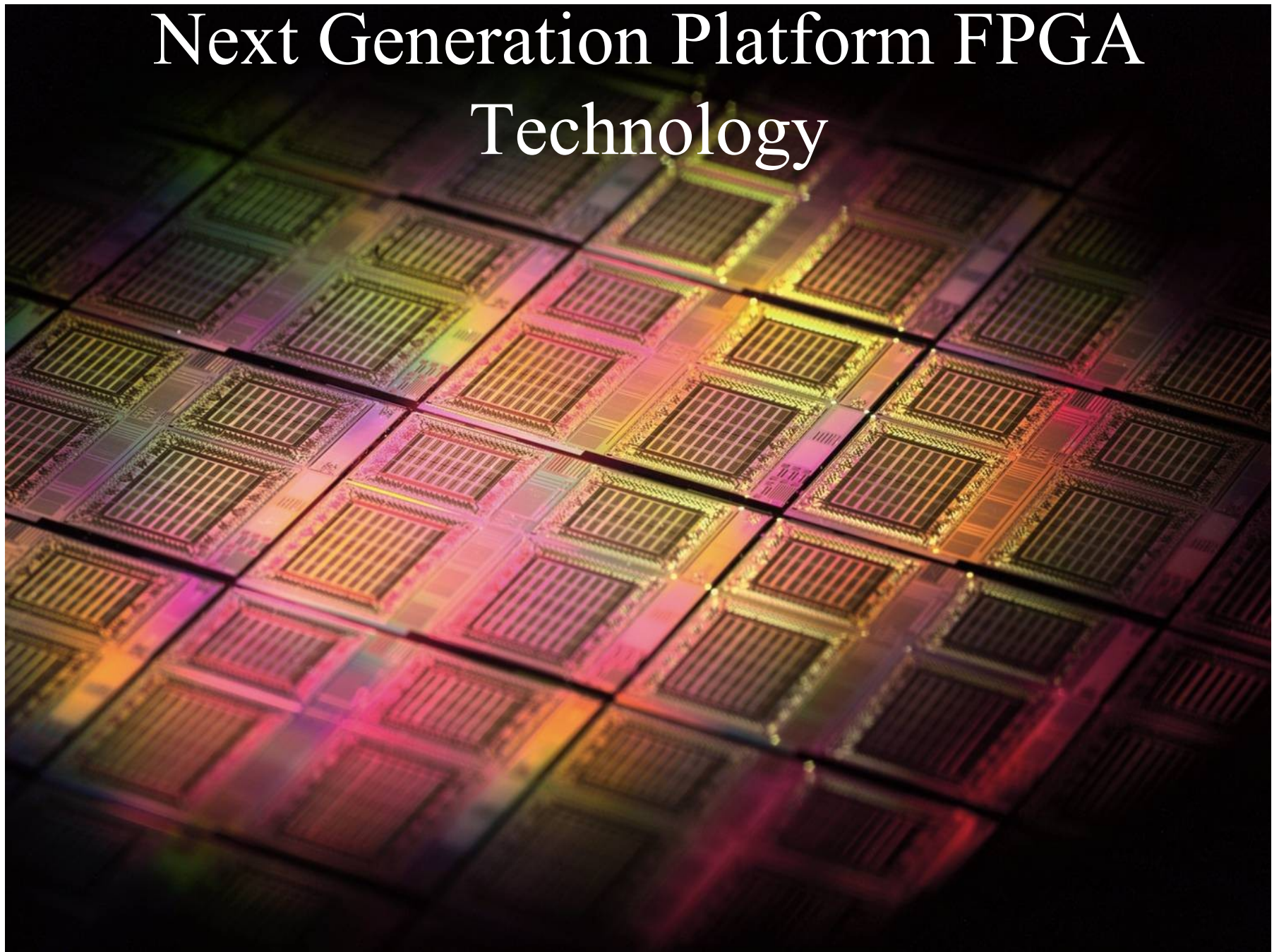
AGP
SSTL-3/-2
HSTL

Clock Management

Up to 4 PLLs
ClockShift™ Circuitry
ClockBoost™ Circuitry
ClockLock™ Circuitry



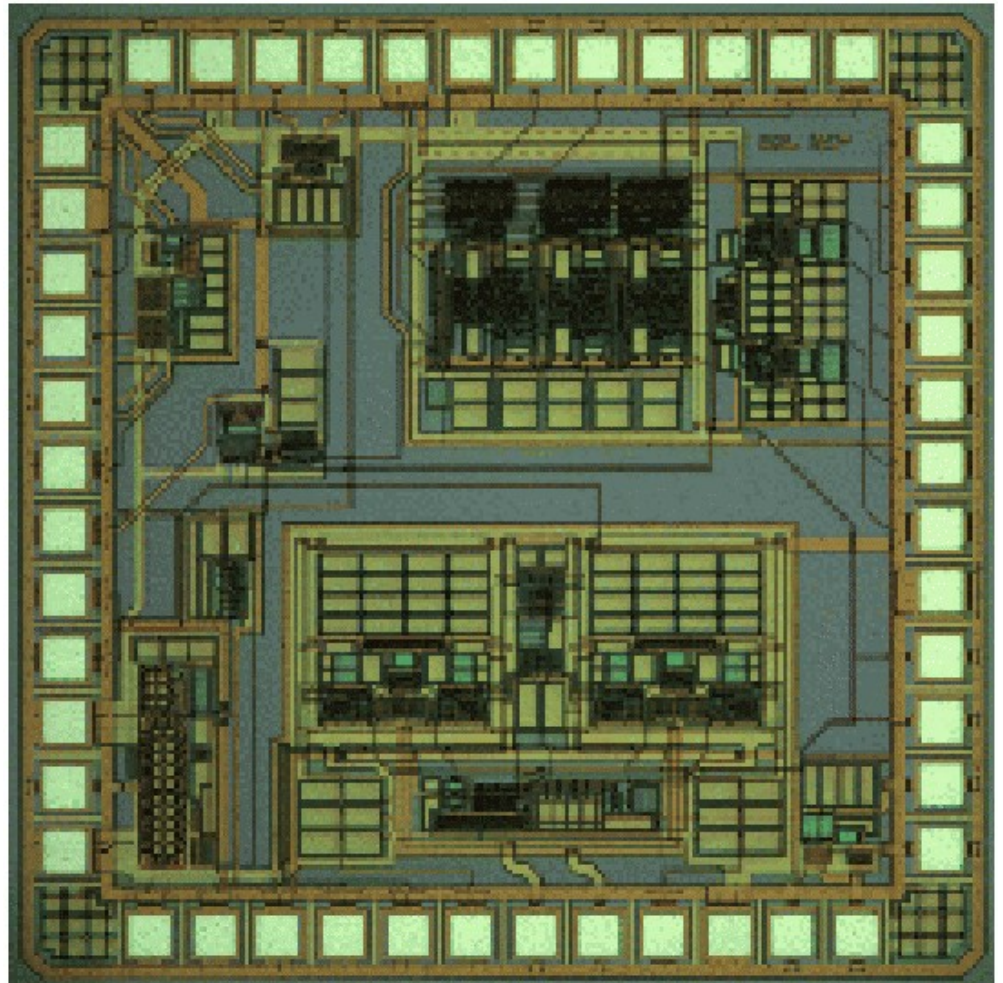
Next Generation Platform FPGA Technology



Phone

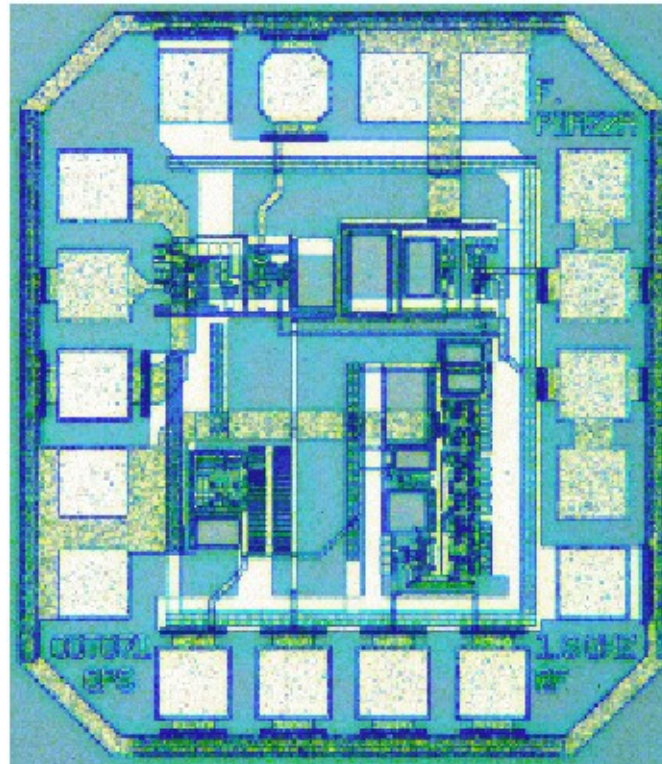
Tchip Semiconductor SA

GSM transceiver 0.25uCMOS



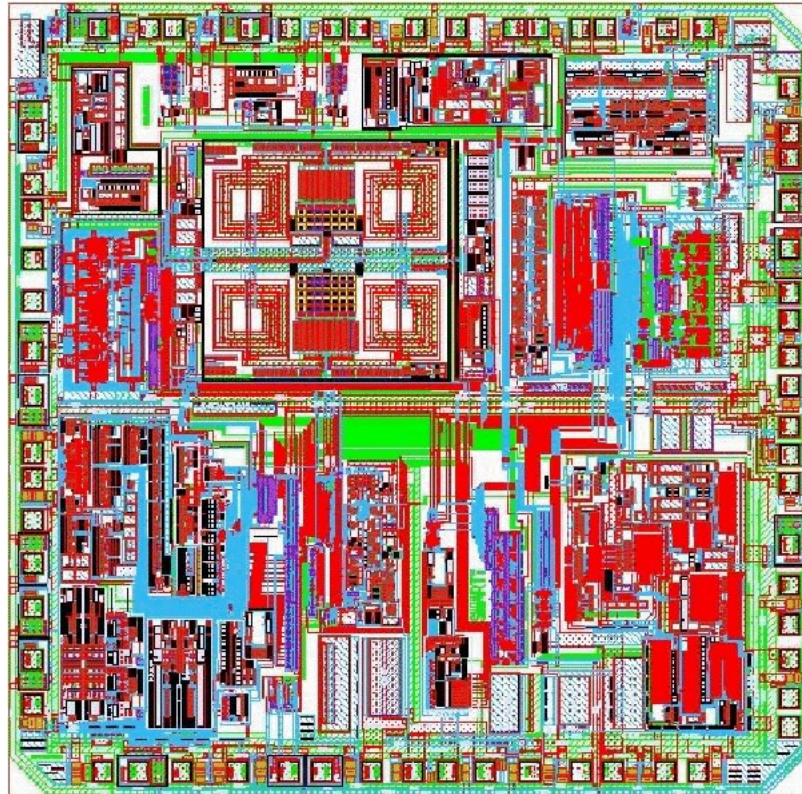
Tchip Semiconductor SA

- GPS receiver front end, 1 μ m BiCMOS



BiCMOS

- GSM transceiver (12 000 composants, Infineon TLD2000)



IC in Switzerland

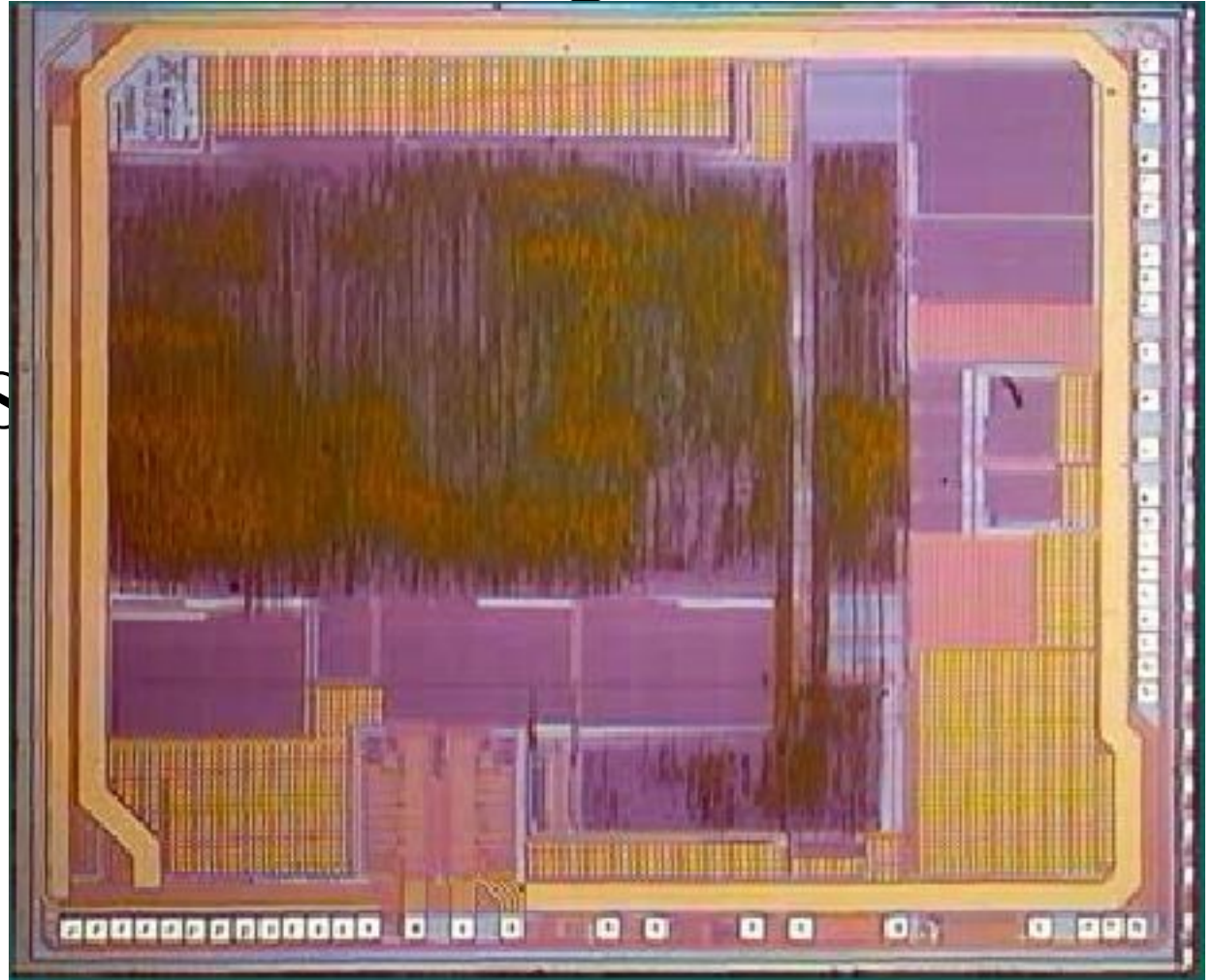
Neuchâtel (EM, CSEM)





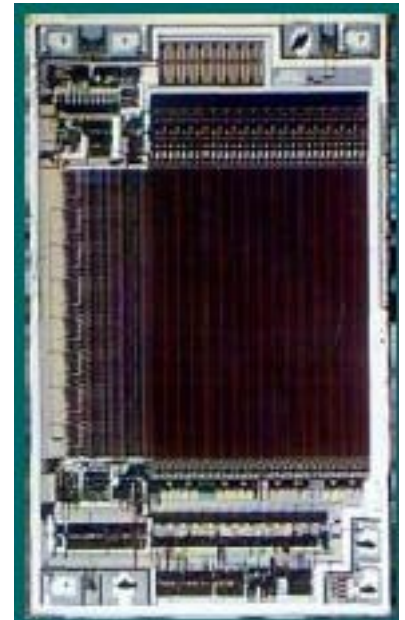
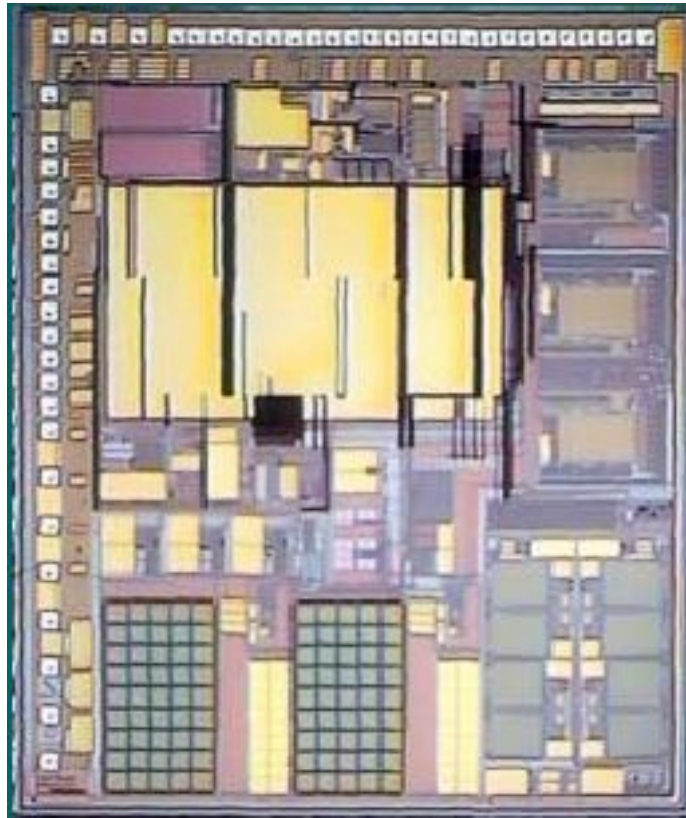
PHONAK, digital

- $0.25\mu\text{m}$
- 20mm^2
- 1.3M MOS
- 2.5MHz
- 1V
- $720\mu\text{W}$

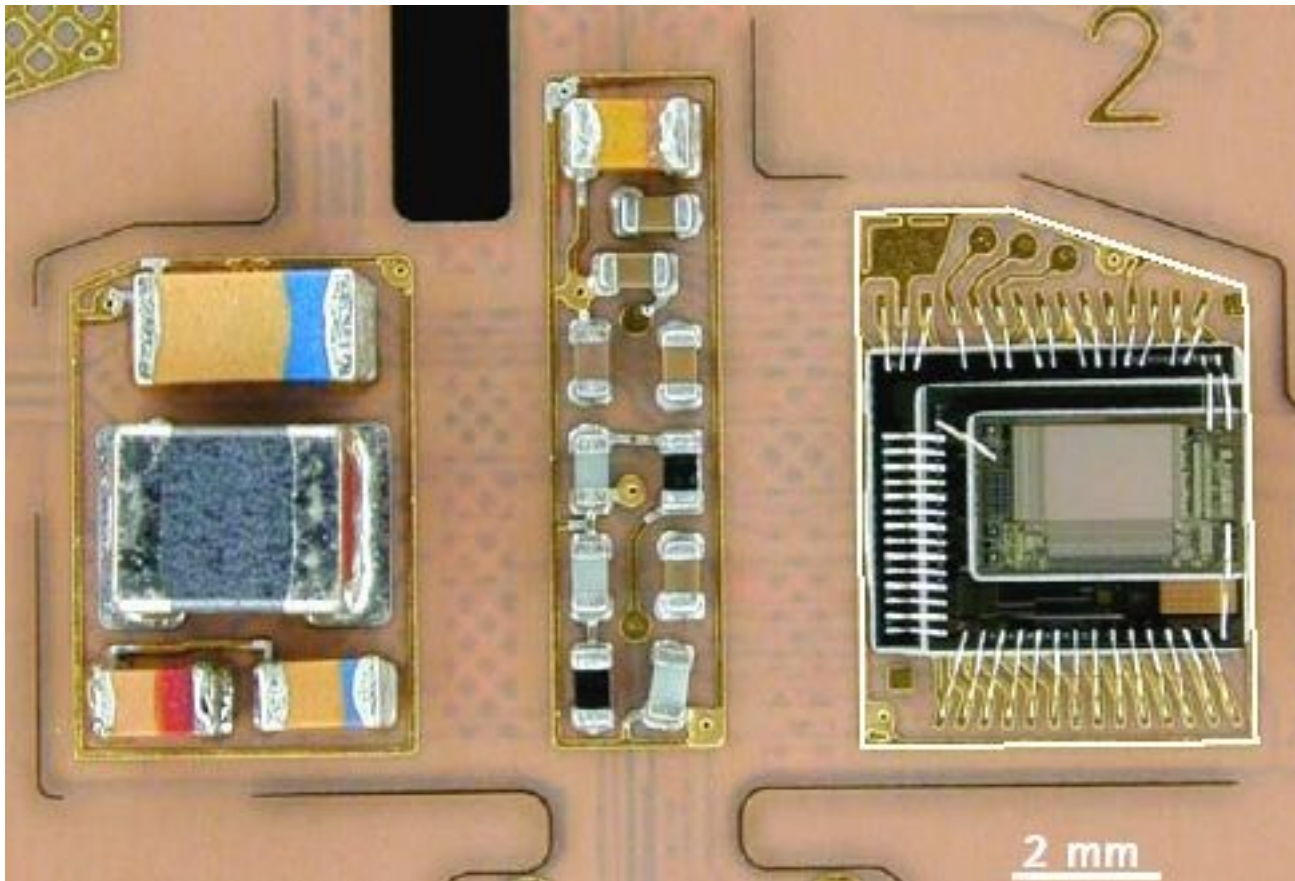


Phonak, analog et EEPROM

- A/D
- D/A
- EEPROM

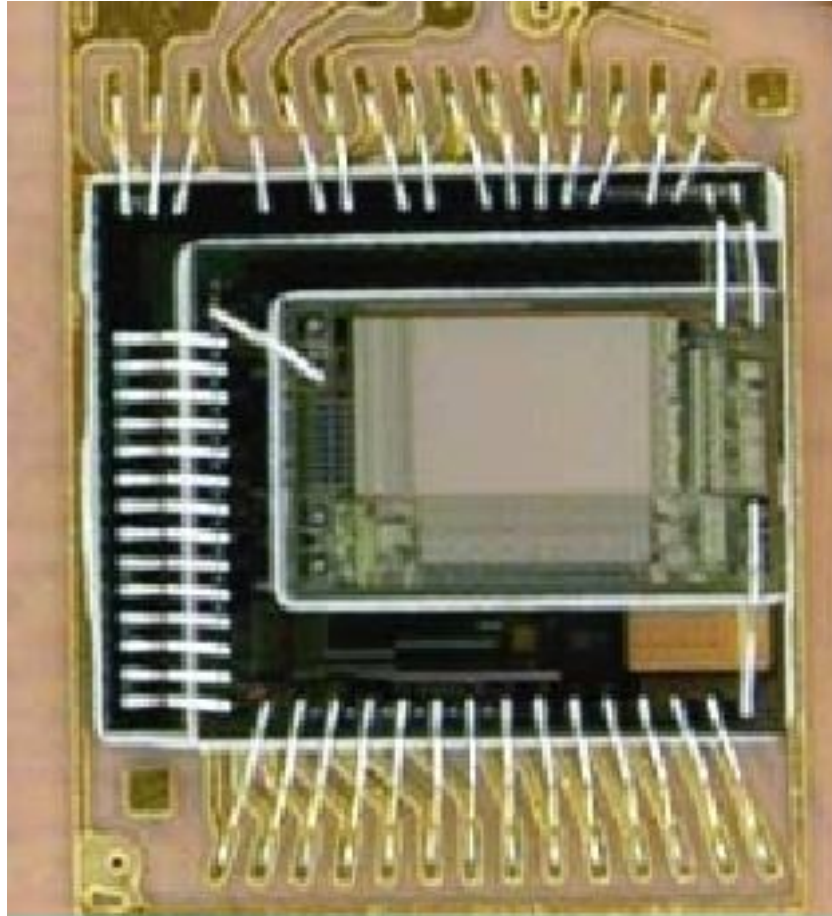


Phonak, PCB



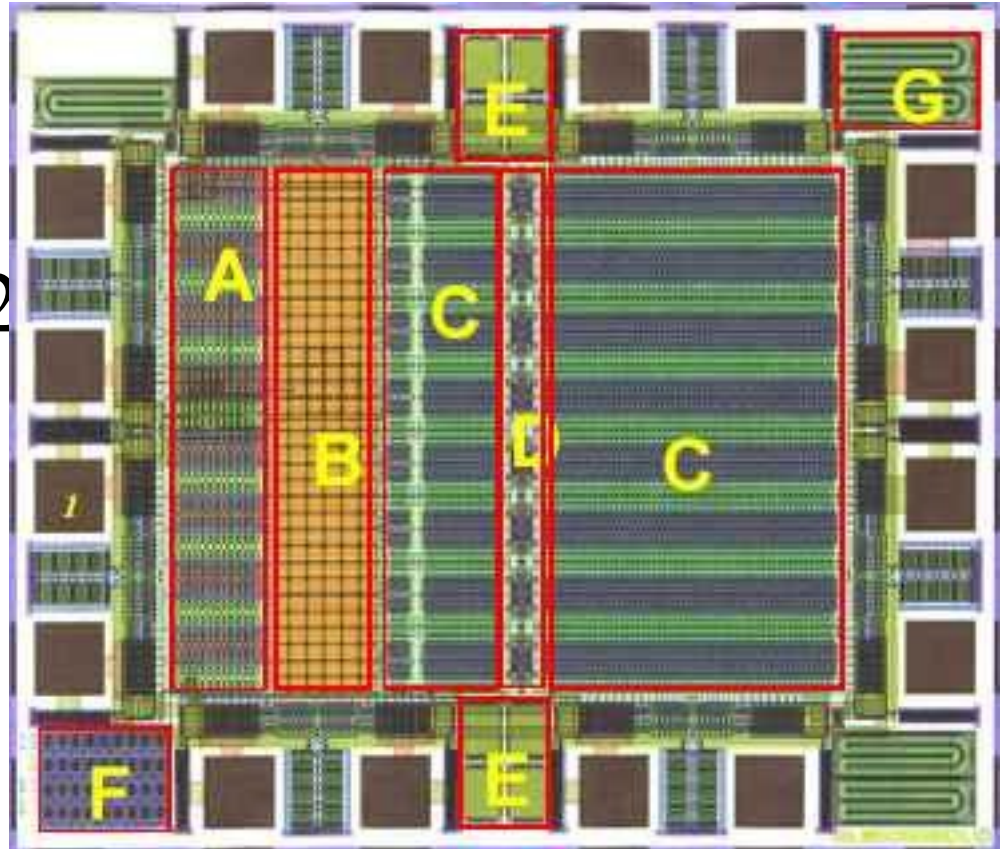
Phonak, stacked chips

- 3 IC
- digital
- analog
- memory

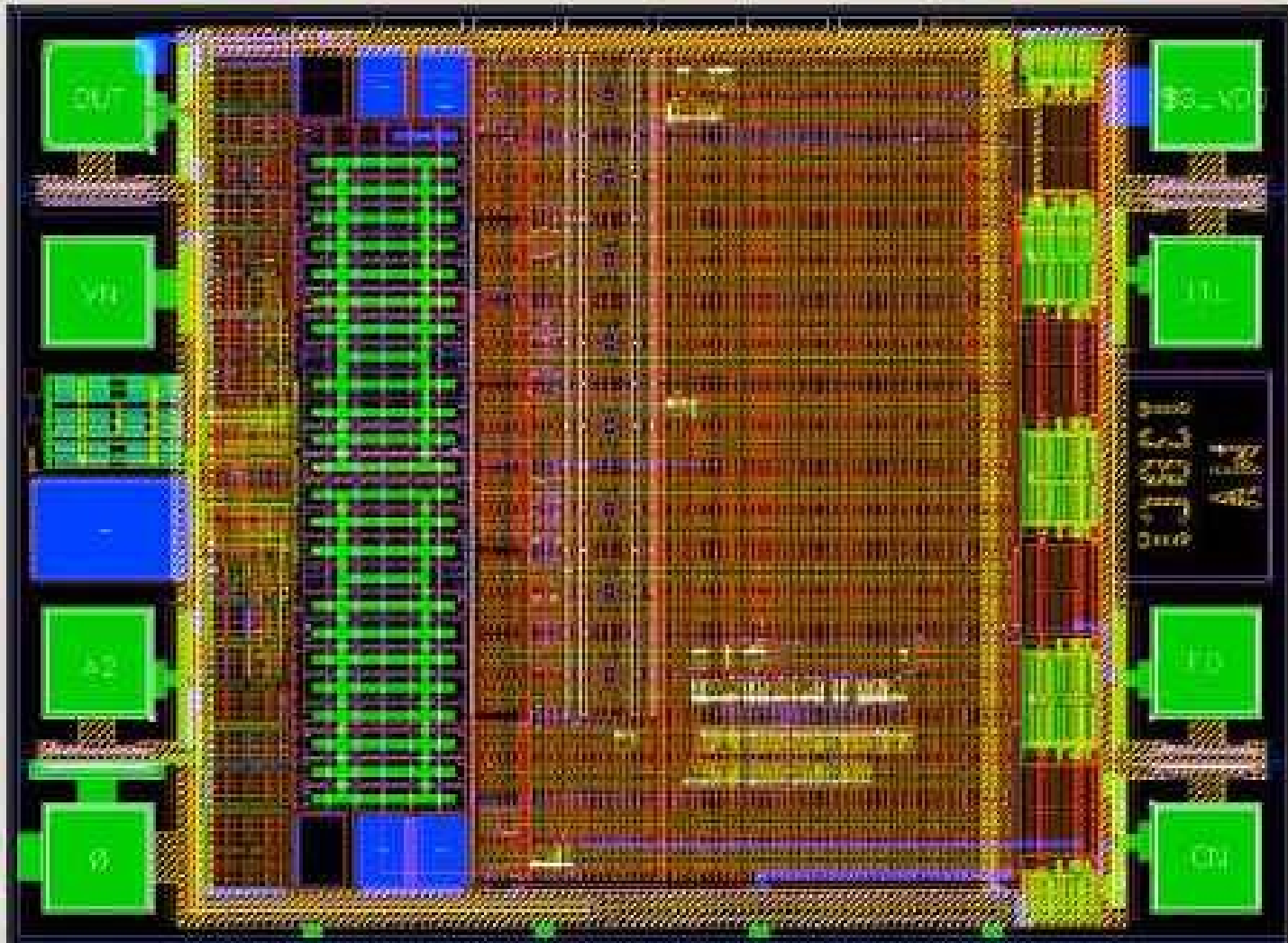


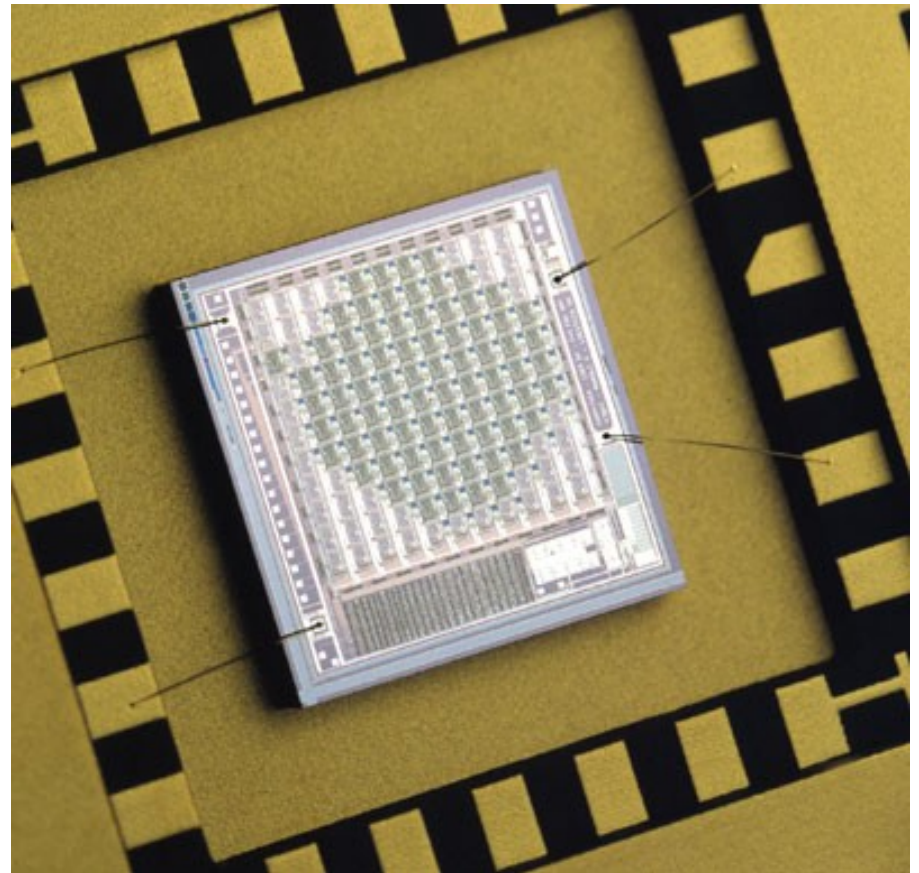
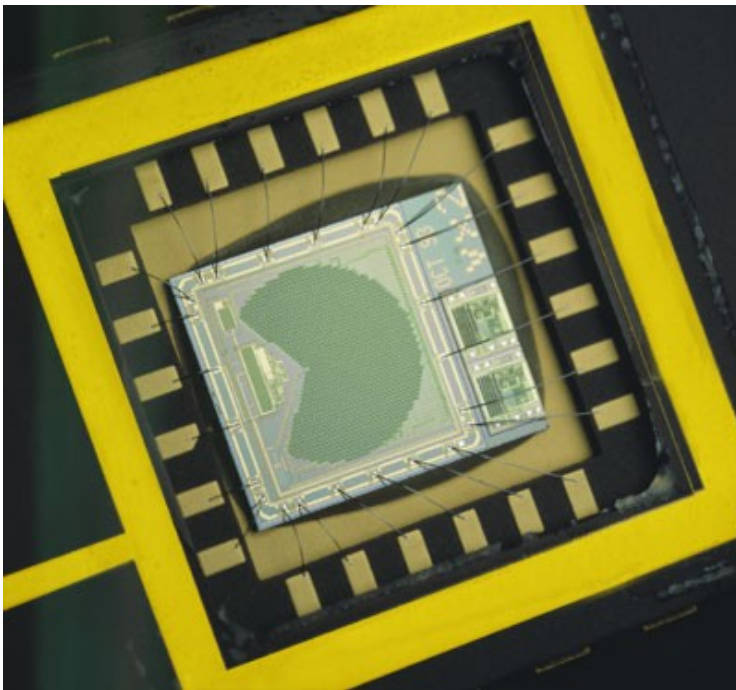
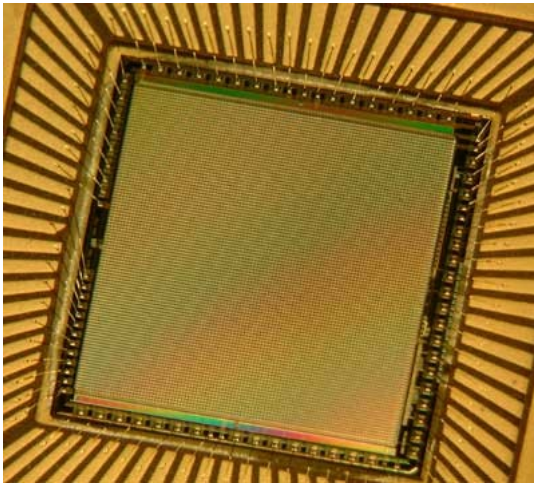
MD300

- ~ CHF 2.-
- 1 μ m CMOS
- 1.44 * 1.20 mm²
- EEPROM (D)
- PNP (F)
- Capa (B)

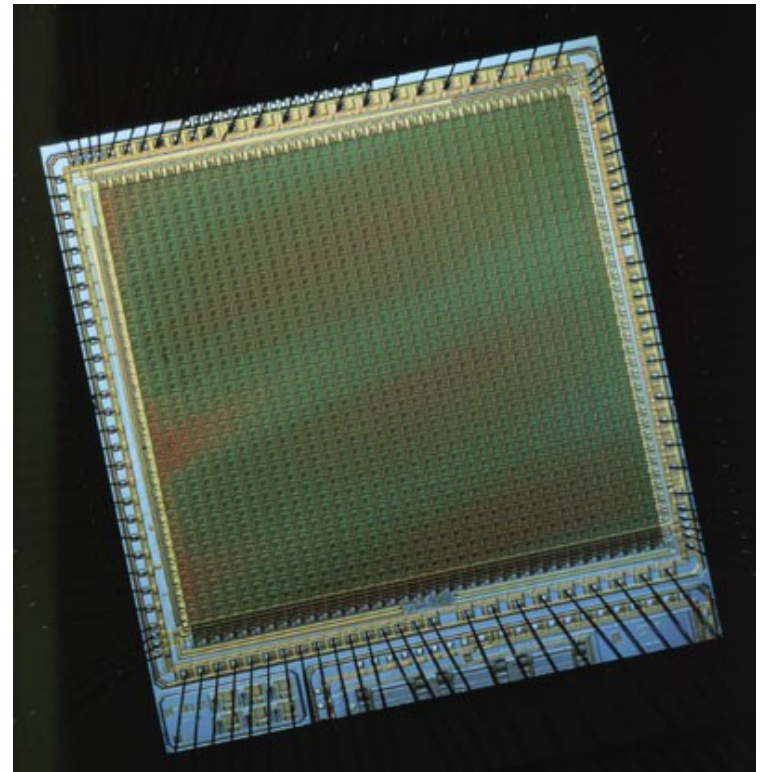
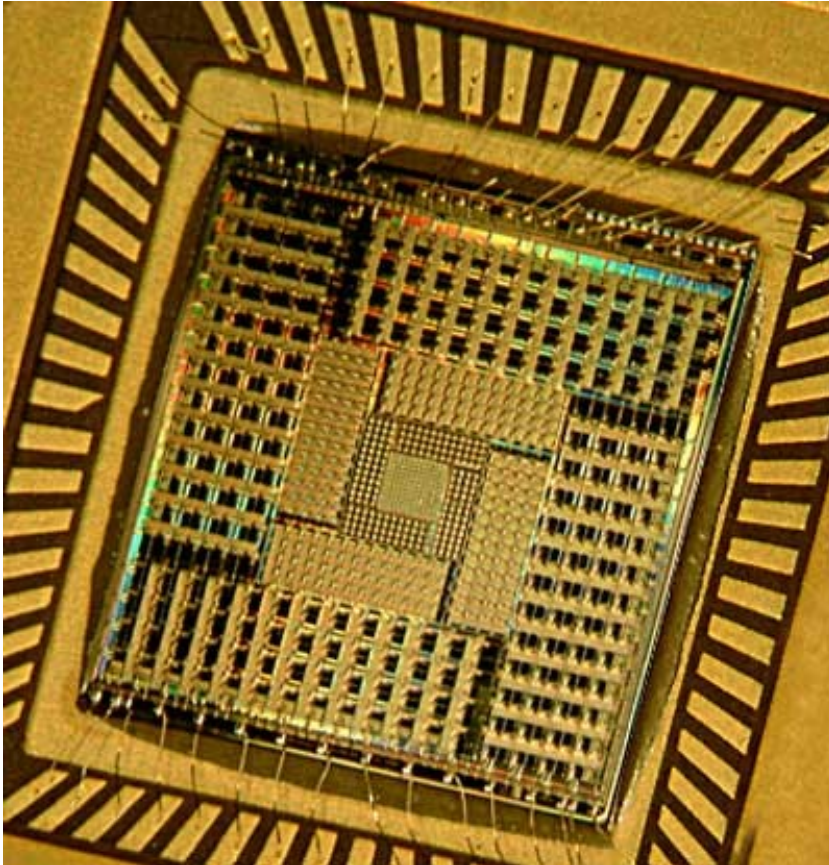


MD400 (1 μ m CMOS)



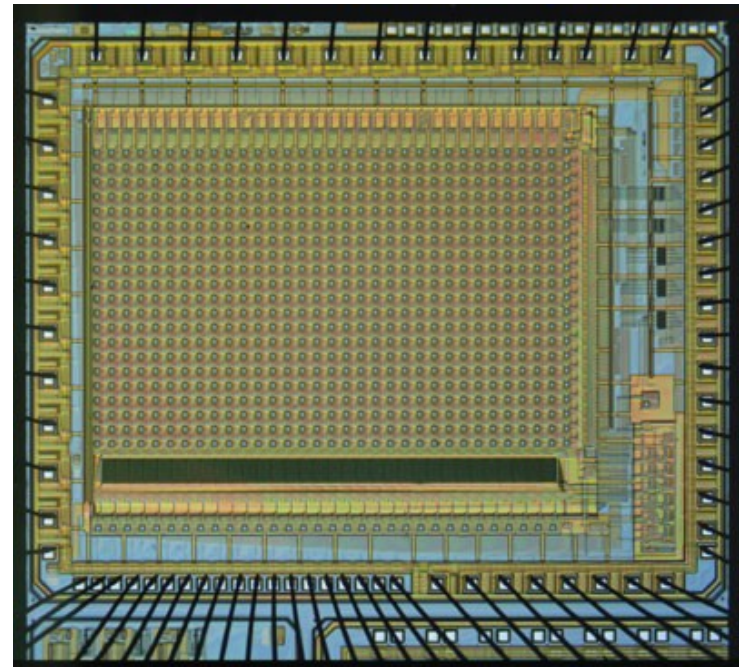
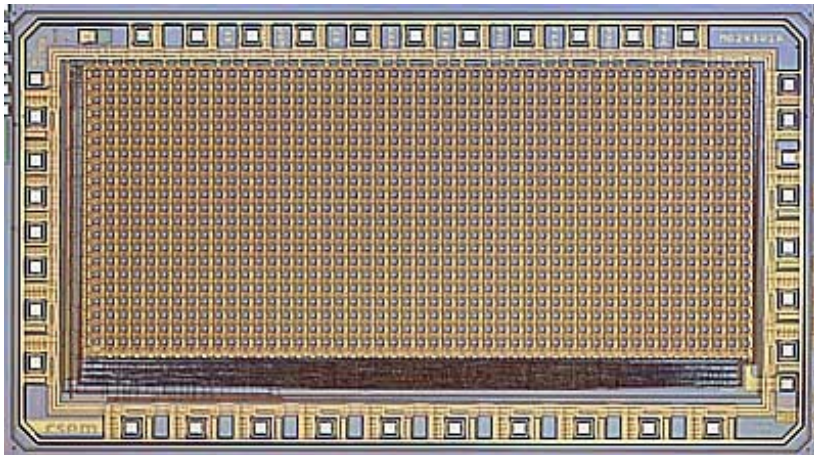


CSEM

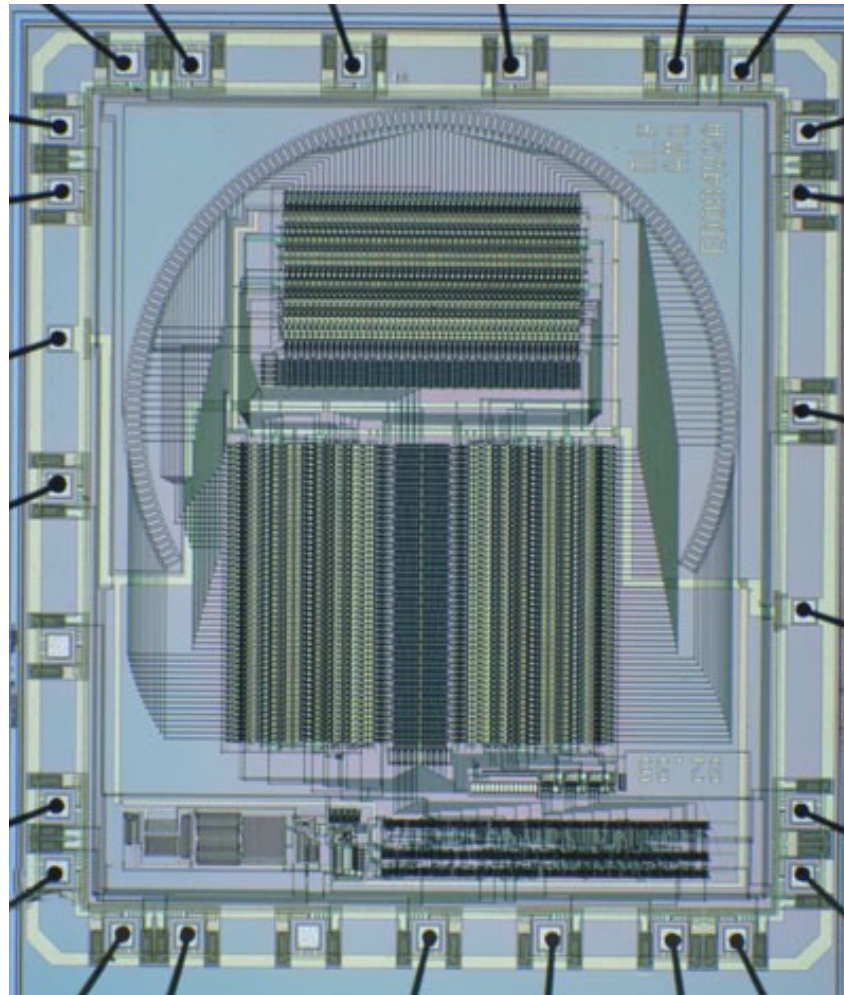


CSEM, Si retina

- 0.5 μm CMOS
- 2 poly
- 3 metal



CSEM 270° view angle retina



A composite graphic featuring a close-up of a green printed circuit board (PCB) with gold-plated components and pins. In the background, a black integrated circuit (IC) is visible with the text 'XEMICS XE1201 J723HM 9808' printed on it. The text 'Ultra Low Power' is overlaid in white at the top, and 'Wireless Solution' is overlaid in black in the center. At the bottom, the 'XE1200 SERIES' logo is displayed in a large, bold, sans-serif font, with 'XE12' in black and '00' in green.

Ultra Low Power

Wireless
Solution

XE1200 SERIES



EM MICROELECTRONIC - MARIN SA

A COMPANY OF THE  **SWATCH GROUP**



Your partner for ultra low power
standard and custom ICs and modules

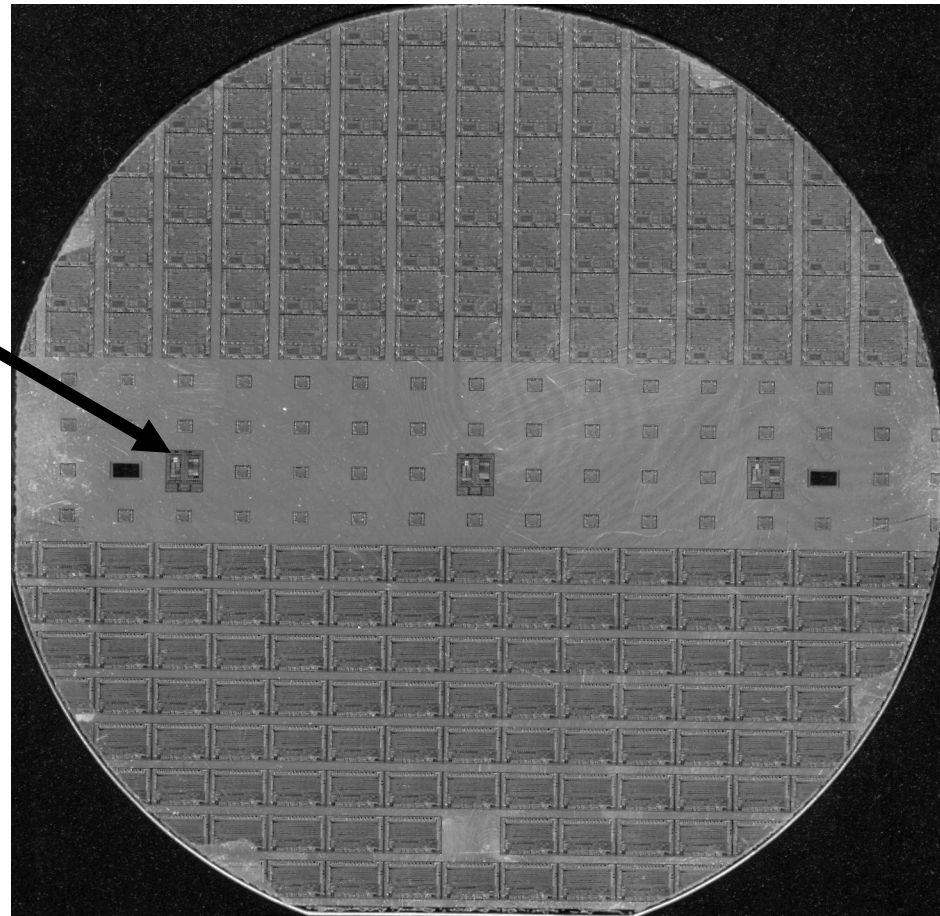
MPW (EM wafer)

IC 1

PCM

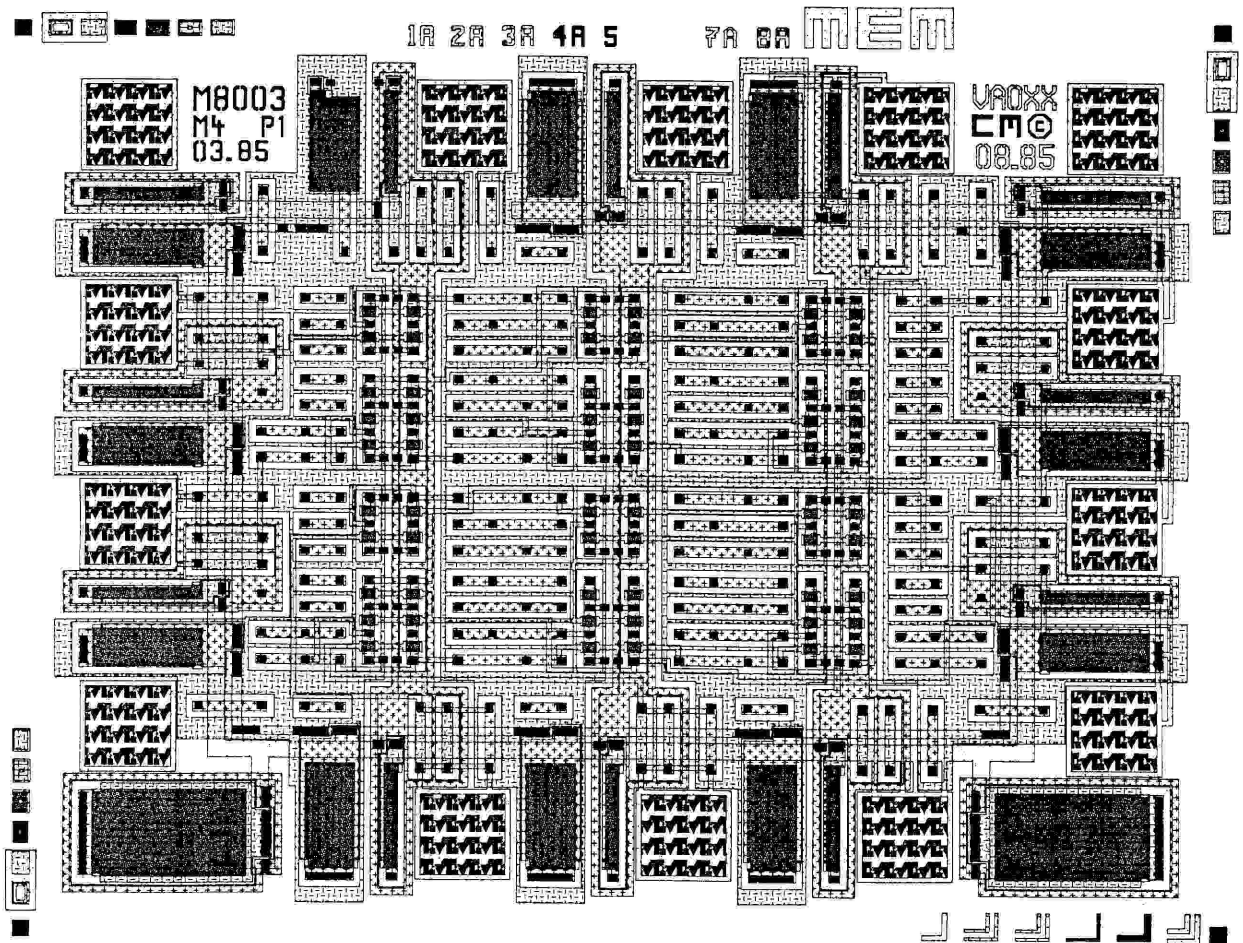
IC 2

IC 3

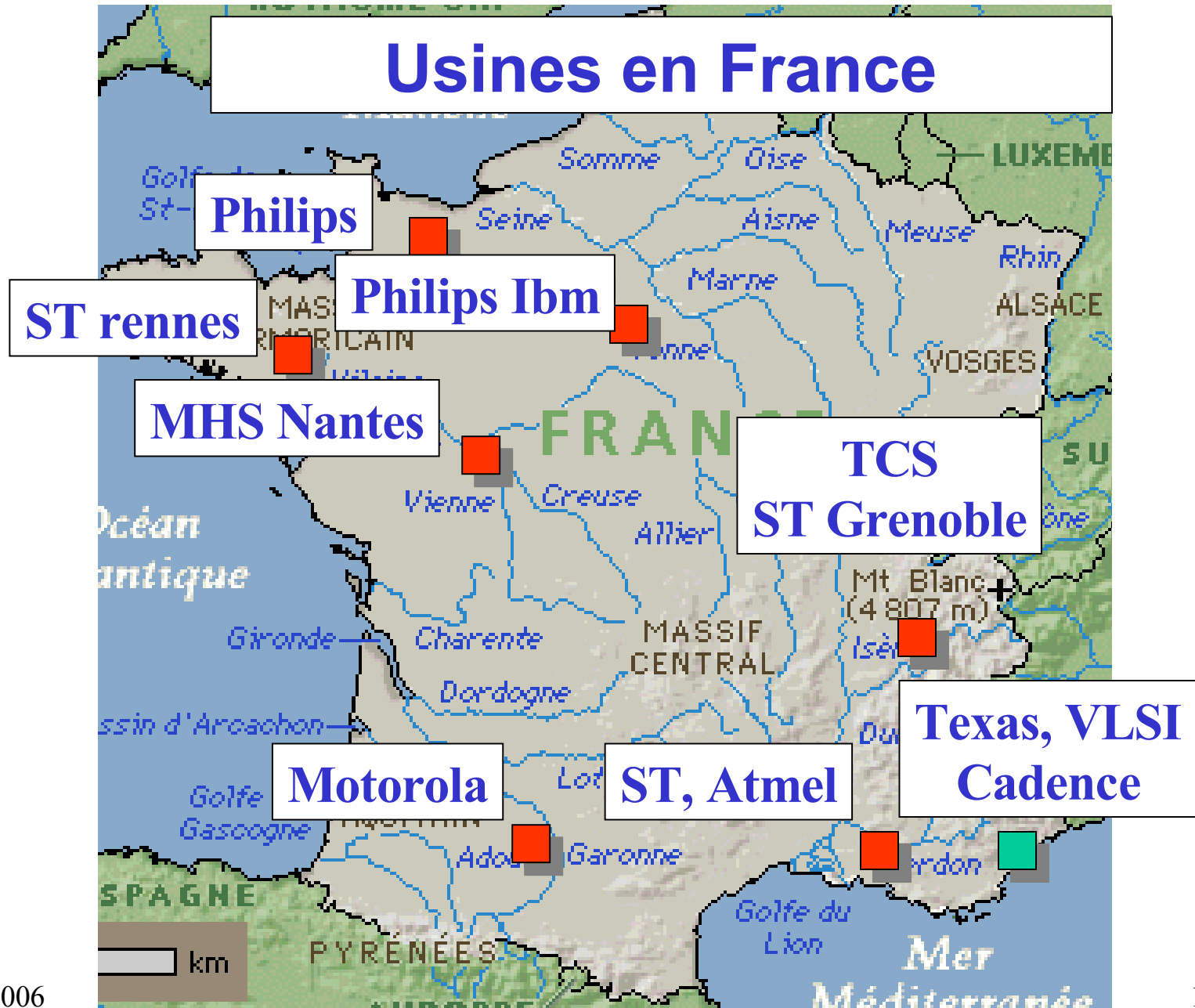


CROSSMOS

- IC design
- GA
- CMOS
- MG
- HV



Usines en France



Conclusions 2002 (ST)

Technology	Year	Metal	Supply (V)	Oxide(A)	Vt (V)	ST technology
1.2μm	1986	2	5.0	250	0.8	
0.7μm	1988	2	5.0	200	0.7	
0.5μm	1992	3	3.3	120	0.6	Hcmos5
0.35μm	1994	5	3.3	75	0.5	Hcmos6
0.25μm	1996	6	2.5	65	0.45	Hcmos7
0.18μm	1998	6	1.9	50	0.40	Hcmos8
0.12μm	2000	7	1.5	40	0.30	Hcmos9
0.10μm	2002	8	1.0	35	0.25	Hcmos10

**Increased metal
layers**

**Reduced
supply**

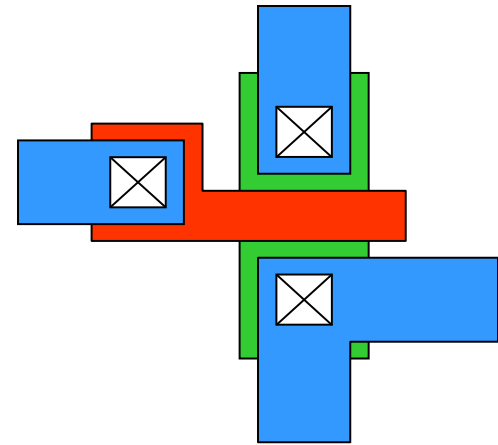
Reduced oxide

2014

Prévisions ...

SIA road map

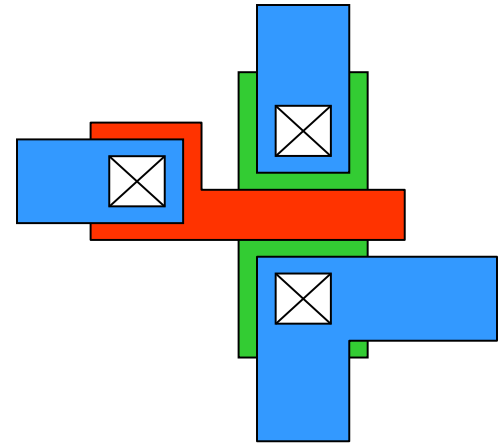
- Taille des transistors
- Longueur du MOS



1999 SIA	1999	2002	2005	2008	2011	2014
	0.18 μm	0.13 μm	0.10 μm	0.07 μm	0.05 μm	0.035 μm

2014

- 0.02 microns
- 20nm
- 10 électrons pour commuter

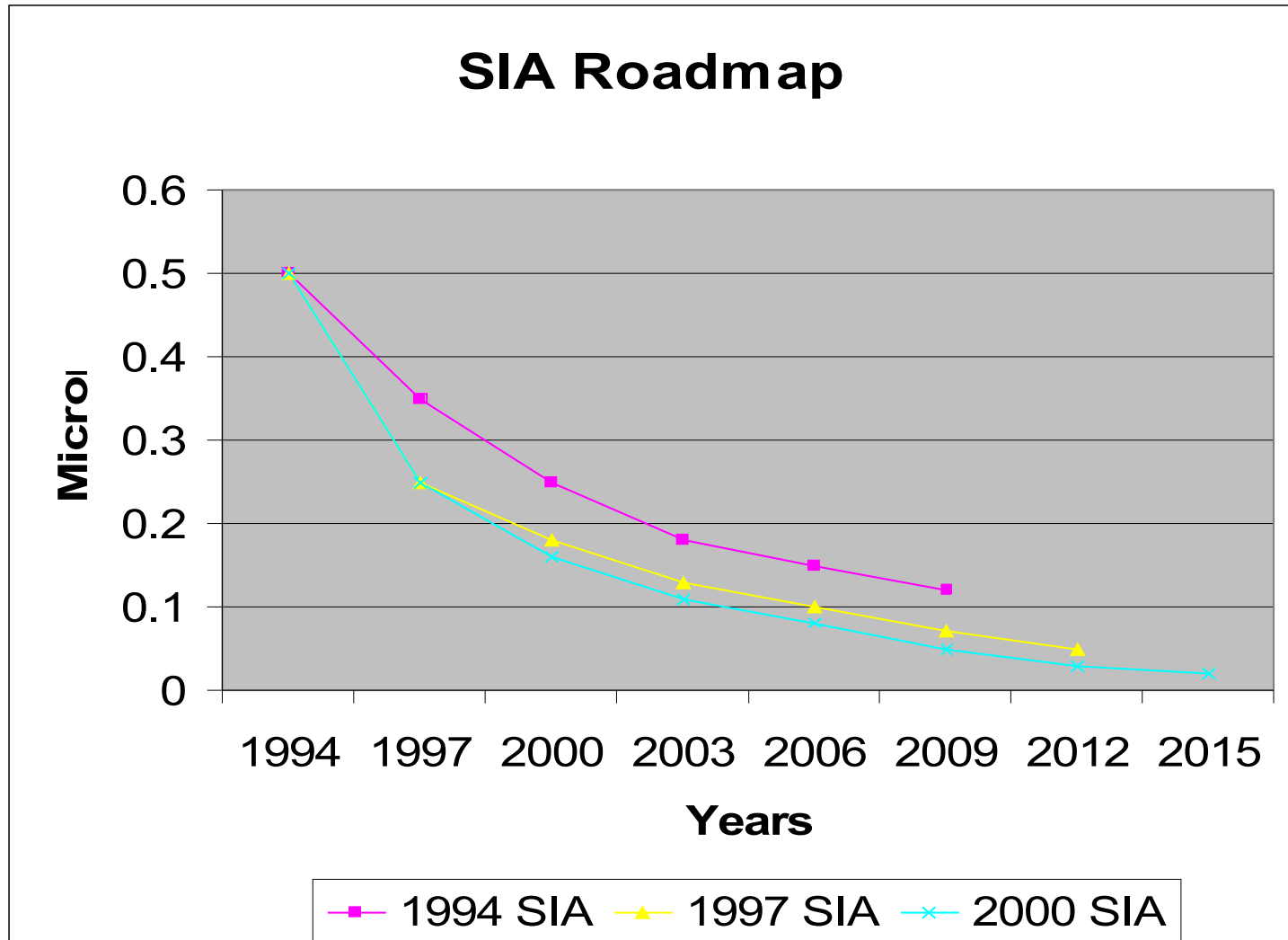


processeurs

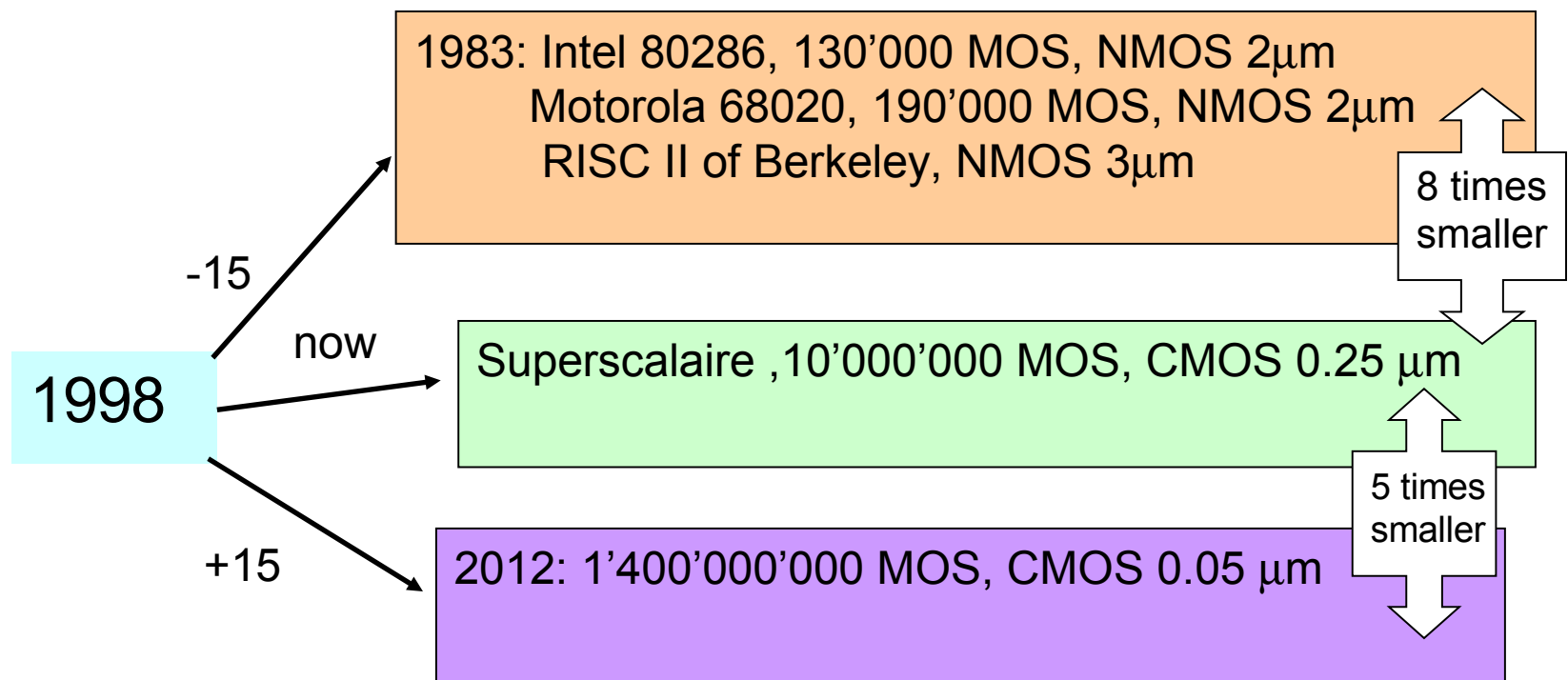
- prédictions

1999 SIA	1999	2002	2005	2008	2011	2014
feature	0.18 μ m	0.13 μ m	0.10 μ m	0.07 μ m	0.05 μ m	0.035 μ m
chip size	3.4 cm ²	3.7 cm ²	4 cm ²	4.5 cm ²	5.3 cm ²	6 cm ²
total MOS	25 M	70 M	190 M	500 M	1.5 G	4 G
MOS/mm2	7 K	20 K	50 K	100 K	280 K	650 K
Nb pads	740	1000	1400	1900	2600	3500

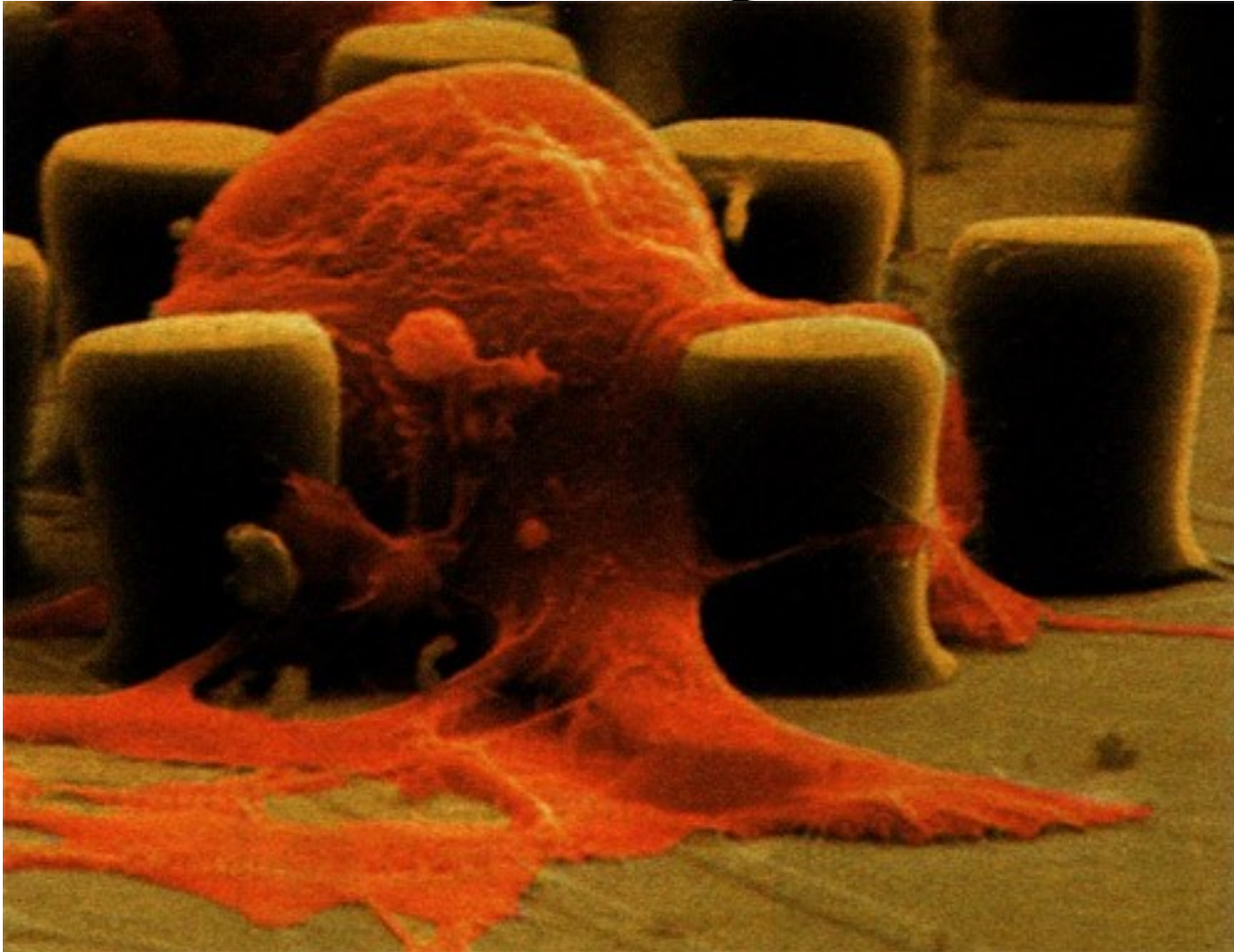
Loi de Moore

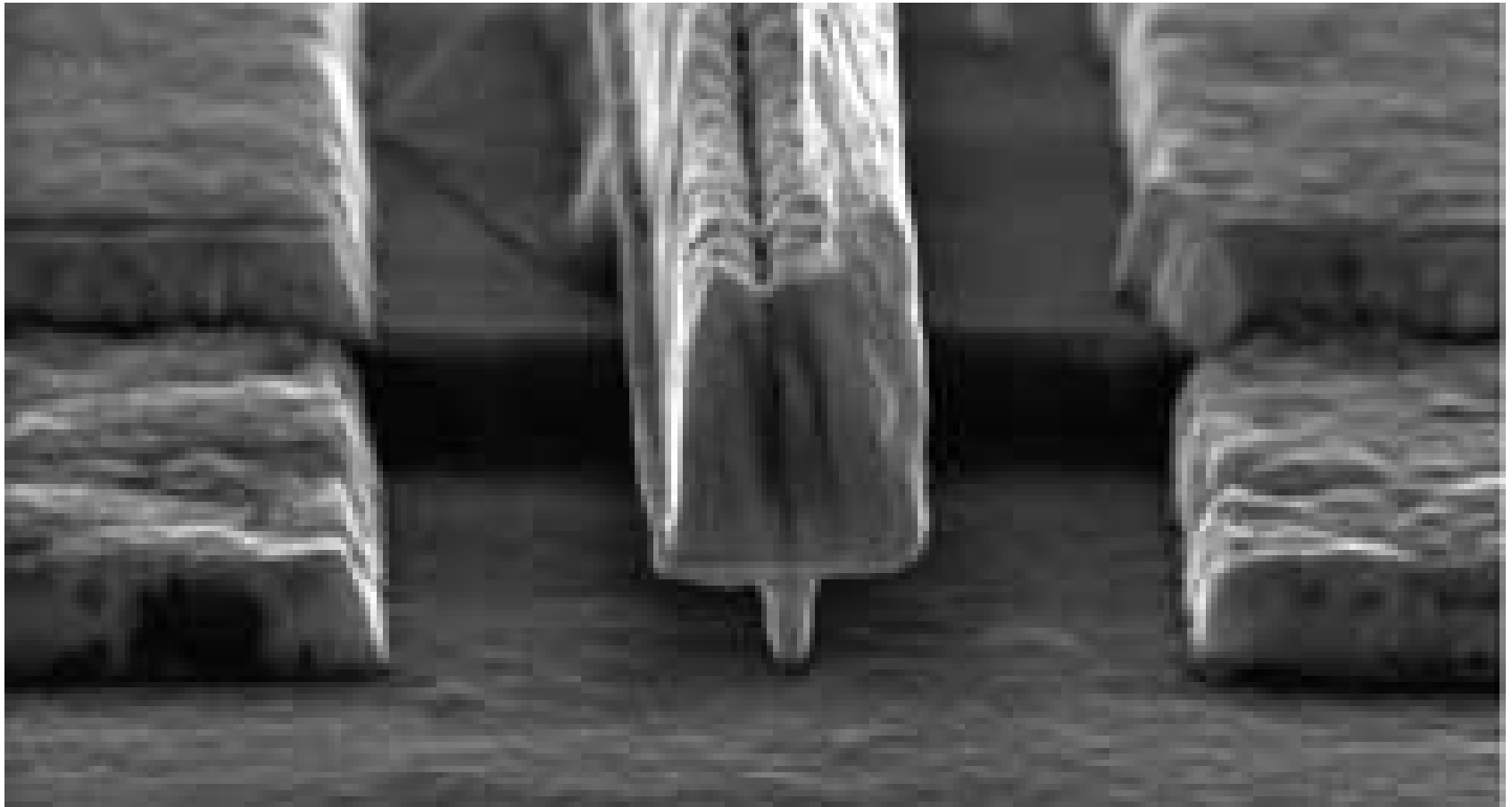


Moore avant et après



Neurones de lapin sur Si





The 60-nm-wide gate is flanked by the indium gallium arsenide source and drain.

IEEE Spectrum april 2004

Popular Mechanics, 1949

"Les futurs ordinateurs ne pèseront peut-être qu'une tonne et demi"

Ken Olsen, CEO of DEC, 1977

"Il n'y a aucune raison que les gens aient un jour un ordinateur chez eux"

Pascale Weil

"En écoutant les prévisions, on en apprend plus sur aujourd'hui que sur demain"